

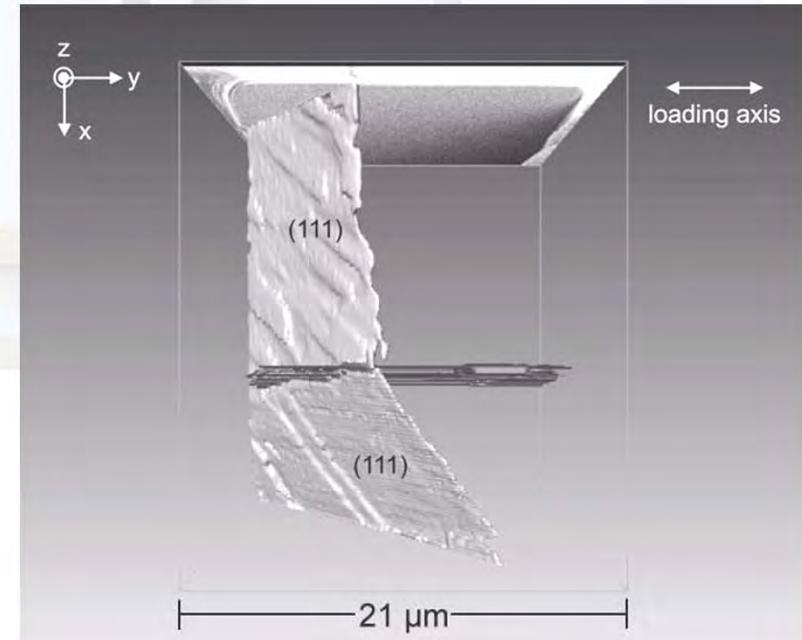


From 3D-Tomography to lattice rotation in nano sized bicrystals

What can be learned from local characterization methods

Horst Vehoff, Michael Marx, Afrooz Barnoush

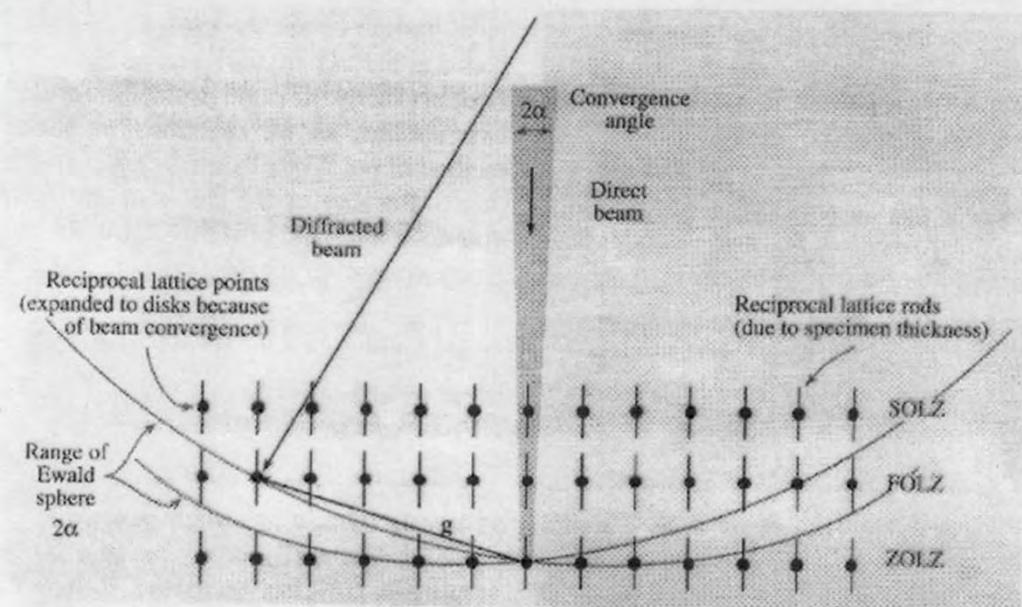
- EBSD and Orientation gradient mapping
- FIB Tomography
- Nano indentation
- Interaction crack - grain boundary
- Nanopillar bicrystals
- Strength of interfaces
- Ultra fine grained materials



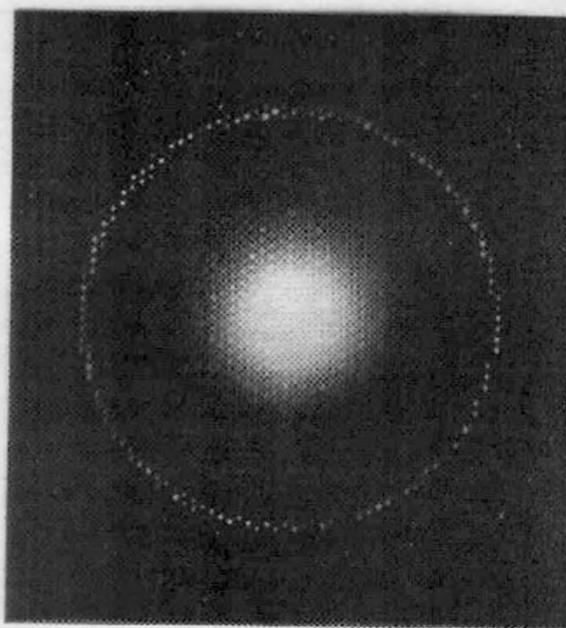
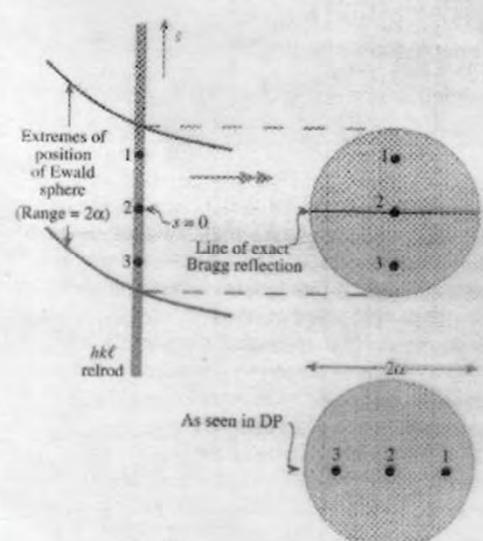


Beugungsbild im TEM

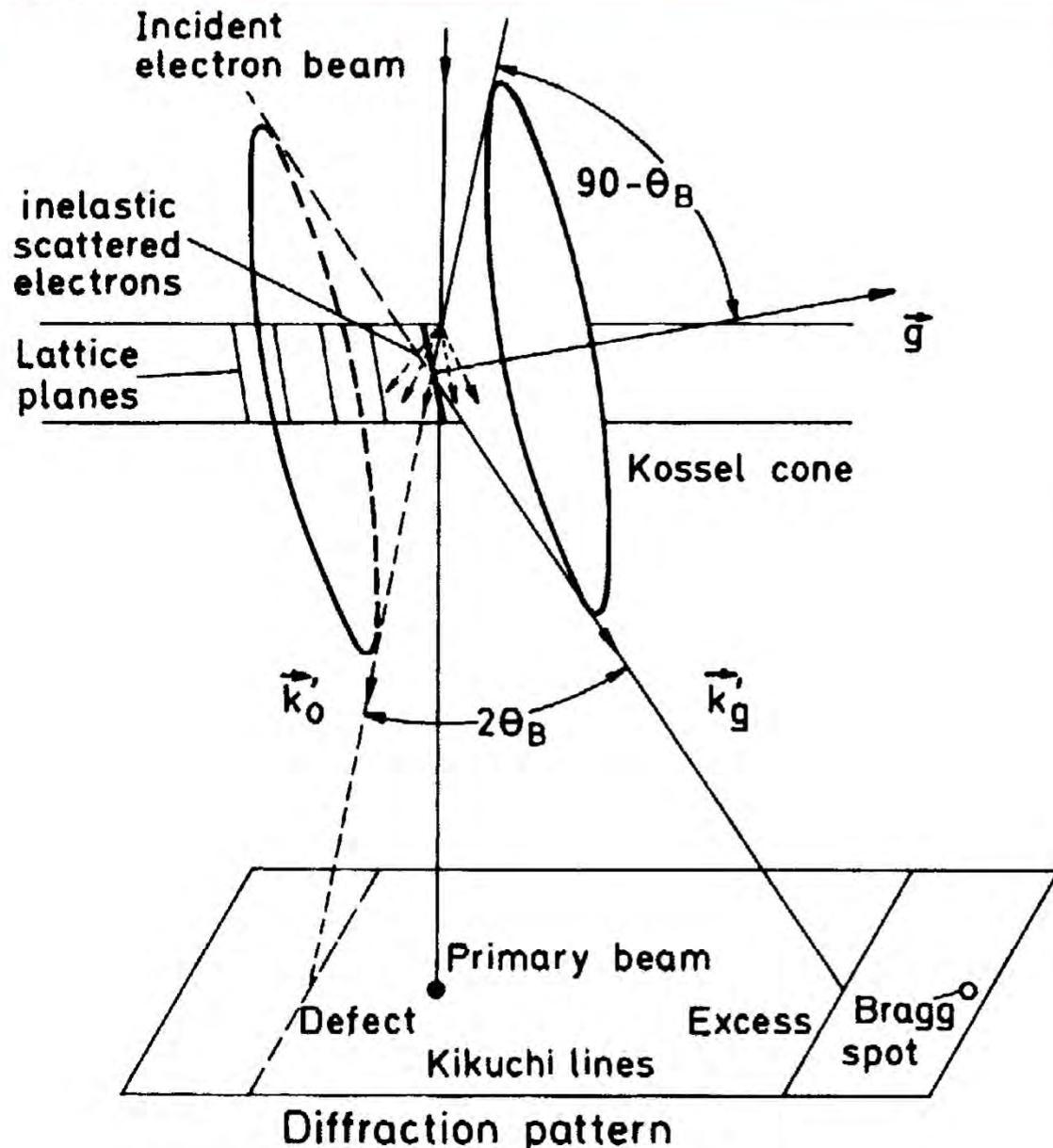
A



B



Mit Hilfe eines divergenten Strahls werden mehrere Lauezonen erfasst



Schema der Bildung der Kikuchilinien

Streuung der Elektronen an den Netzebenen in alle Richtungen auf zwei Kegelmäntel (Kosselkegel) gestreut.

geringen Öffnungswinkels des Kegels (um 1°)
 → Schnitt der Kegelmäntel mit dem Schirm Geraden.

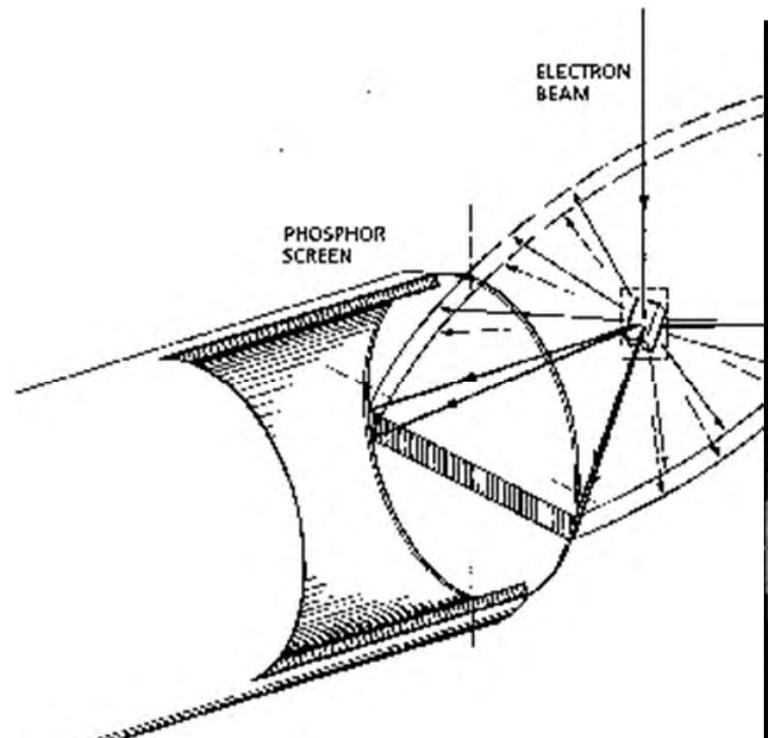
Zu jeder Netzebenenschar gehören eine helle und eine dunkle Kikuchilinie



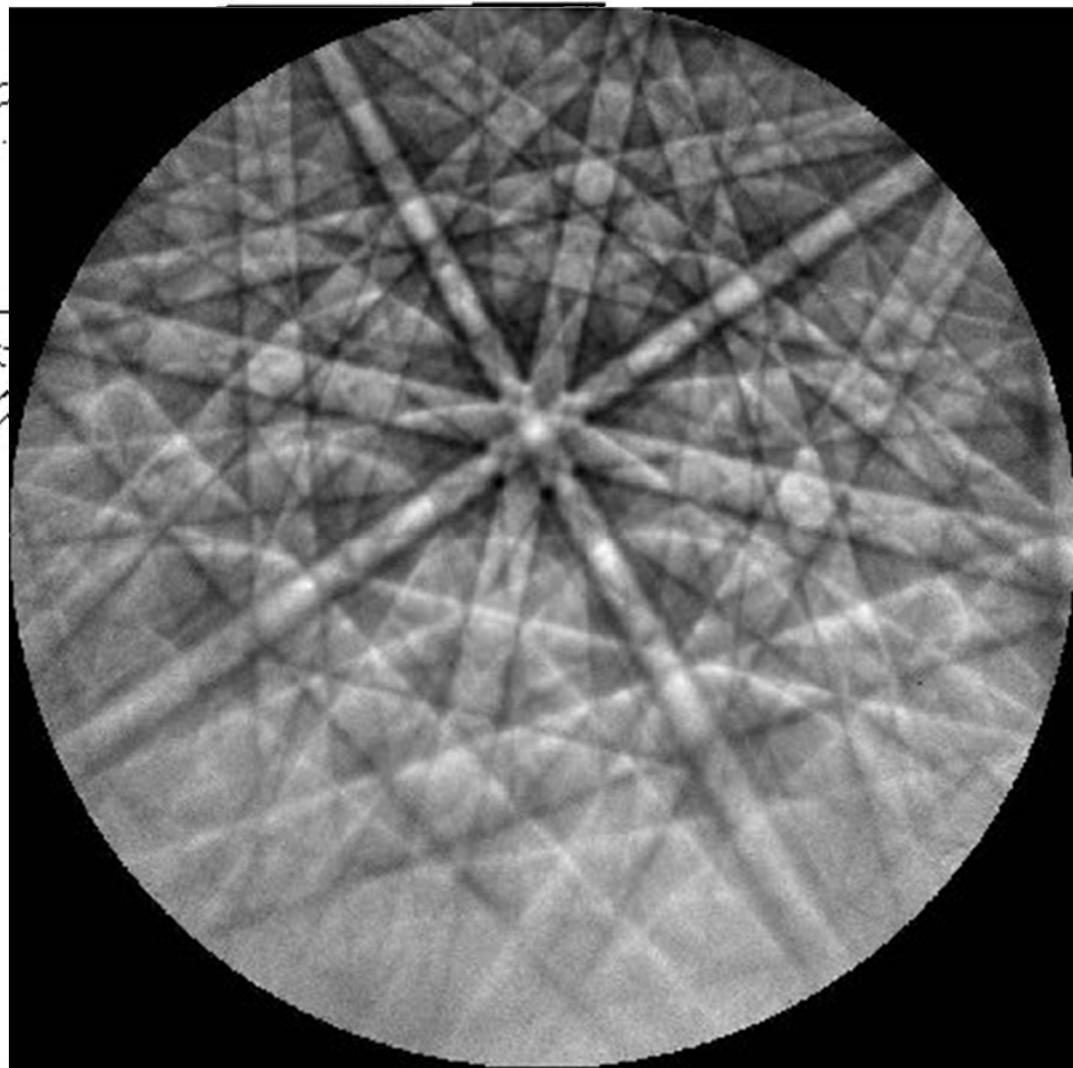
EBS

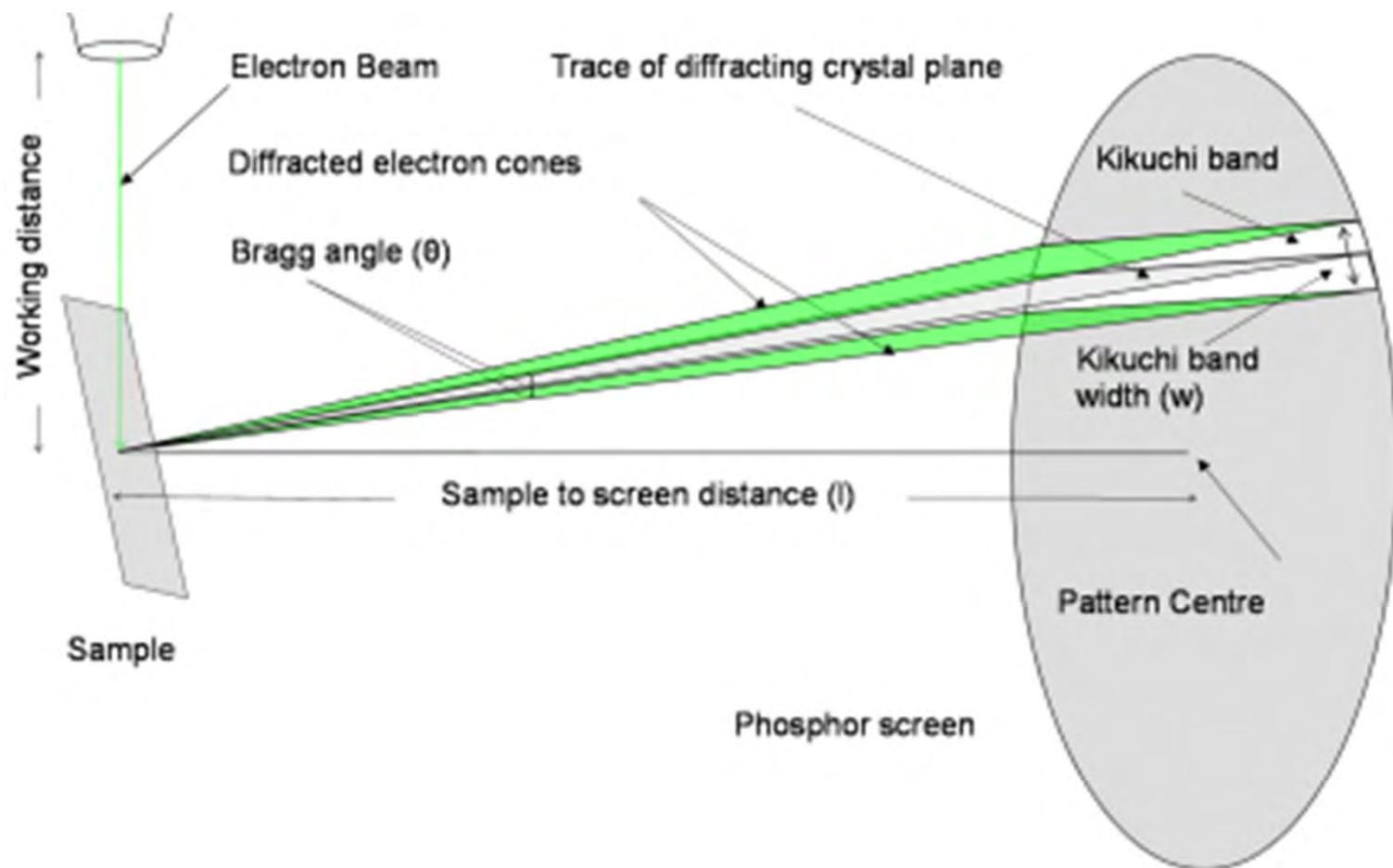


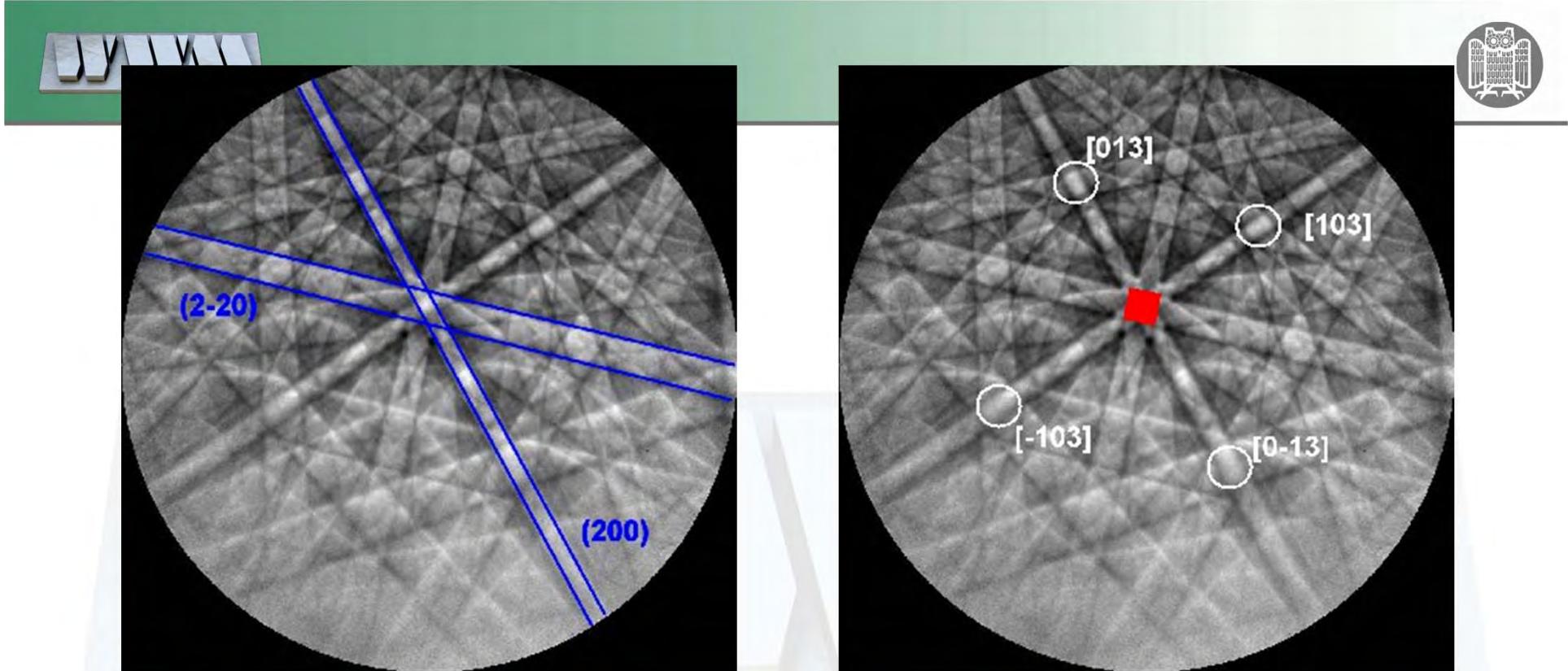
Bildung der ‚Electron Backscatter Diffraction Pattern‘ (EBSP)



Die auf eine Kristallebene im Braggwinkel einfallenden Elektronen werden in zwei Kegel gebeugt und Kikuchi Bänder im Beugungsmuster bilden sich







Kikuchi-Linienbreite

Ebenenabstand d:

$$d(200) > d(2-20)$$

→ Kikuchi-Bänder-Breite b

$$b(200) < b(2-20)$$

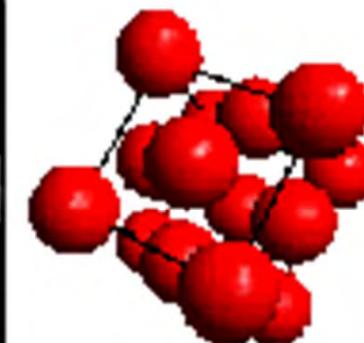
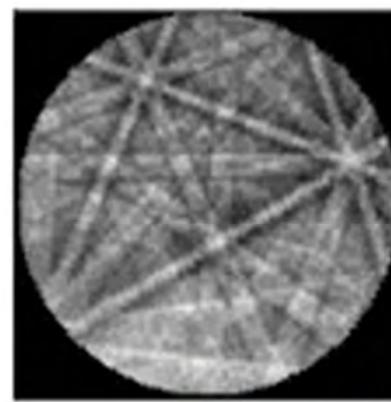
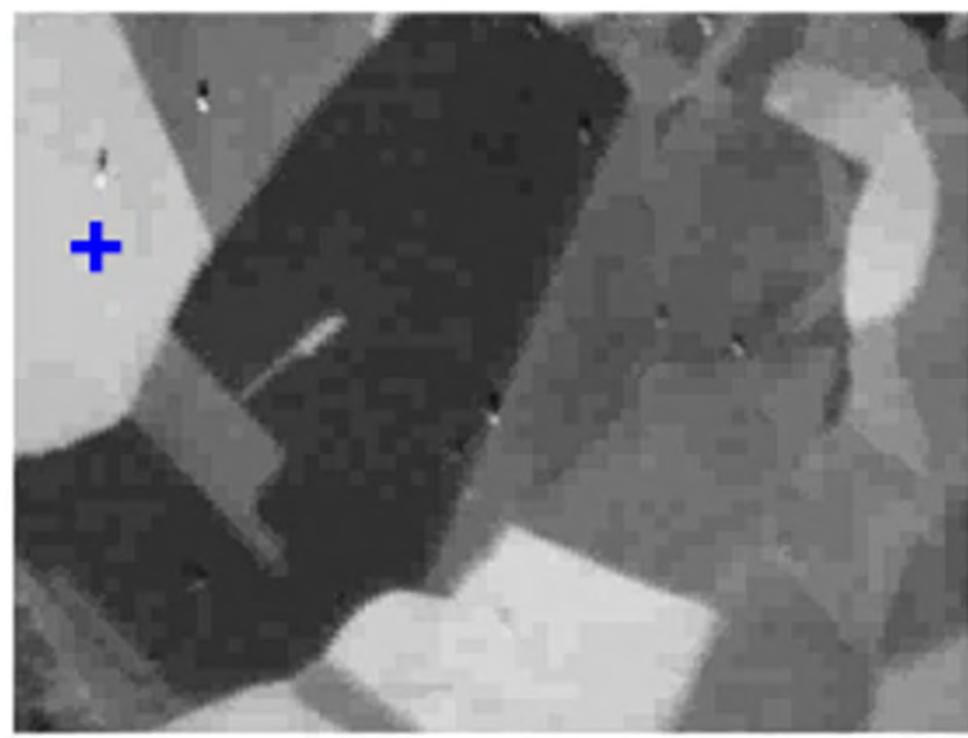
Kristallsymmetrie

z. B. vierfältige Symmetrie um die [001]-Richtung durch symmetrisch äquivalente $\langle 013 \rangle$ Zonenachsen

$$b \approx 2l\theta \approx \frac{nl\lambda}{d}$$



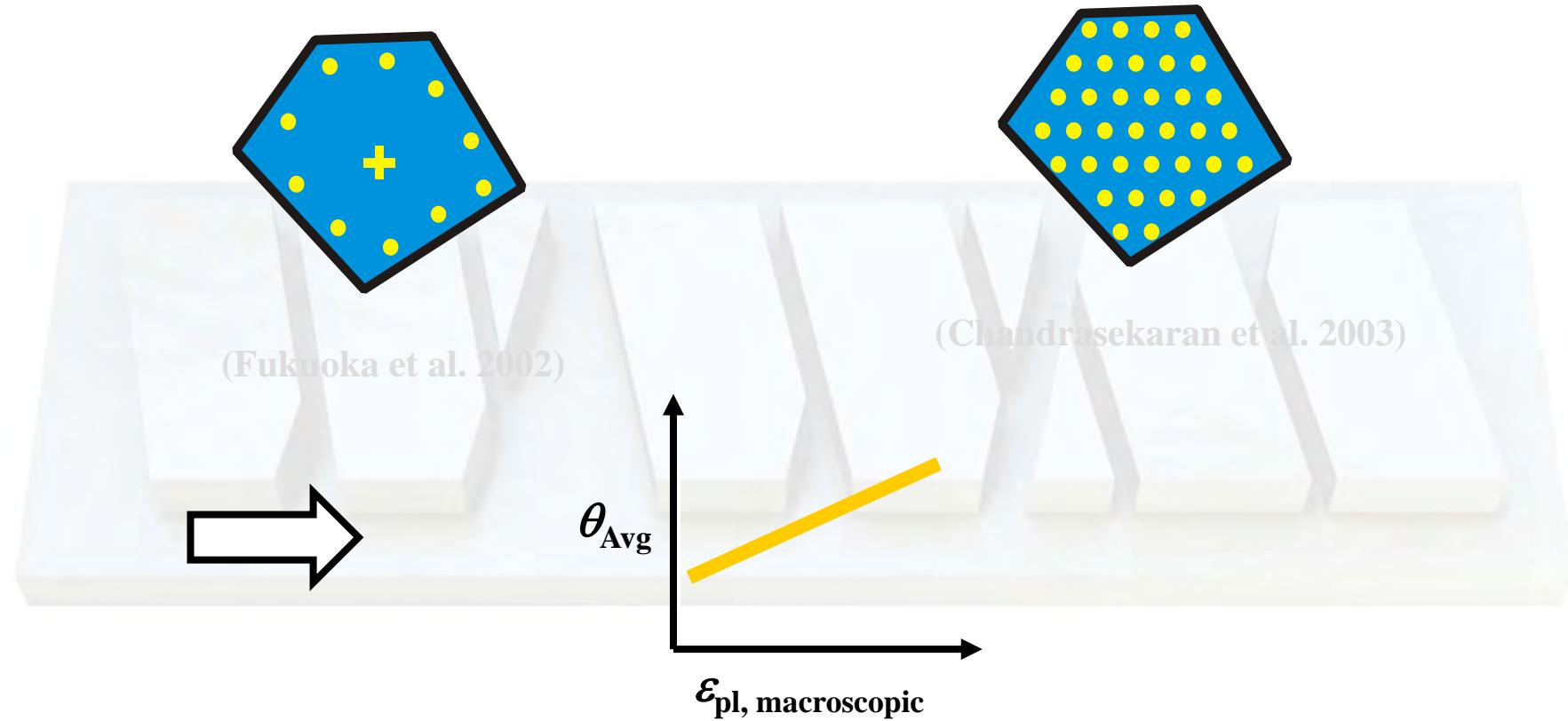
Automatischer Scan



Texture: {3 -1 7}<-4 9 3>



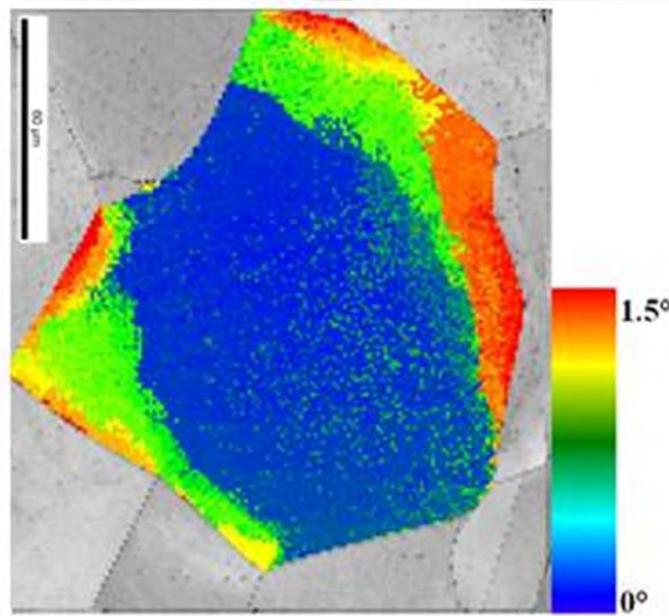
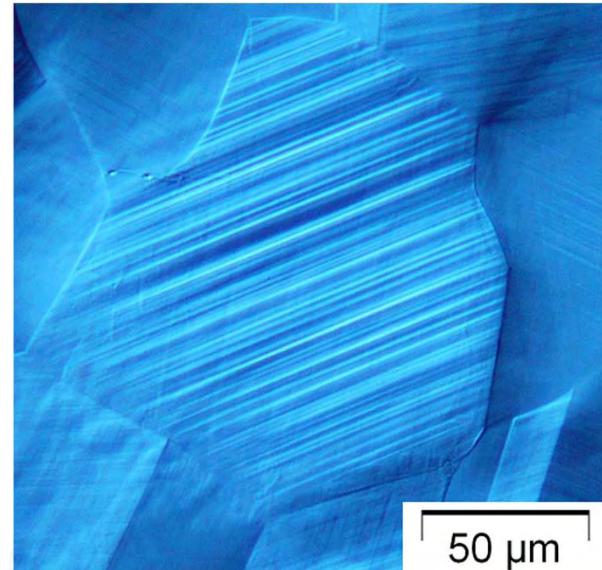
Why: lattice rotations can be easier compared with simulations than dislocation densities



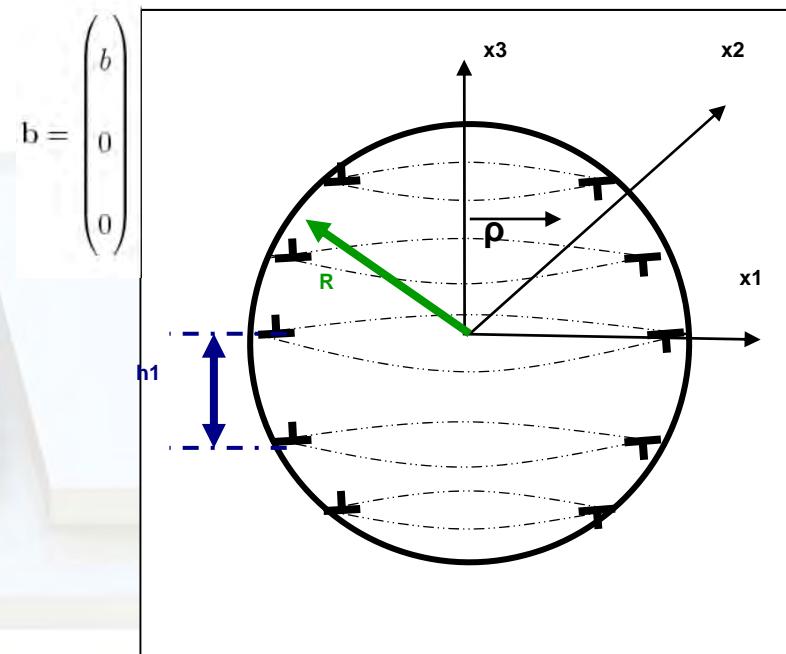
Results for uniform and cellular
dislocation structure are consistent



Dislocations and boundaries



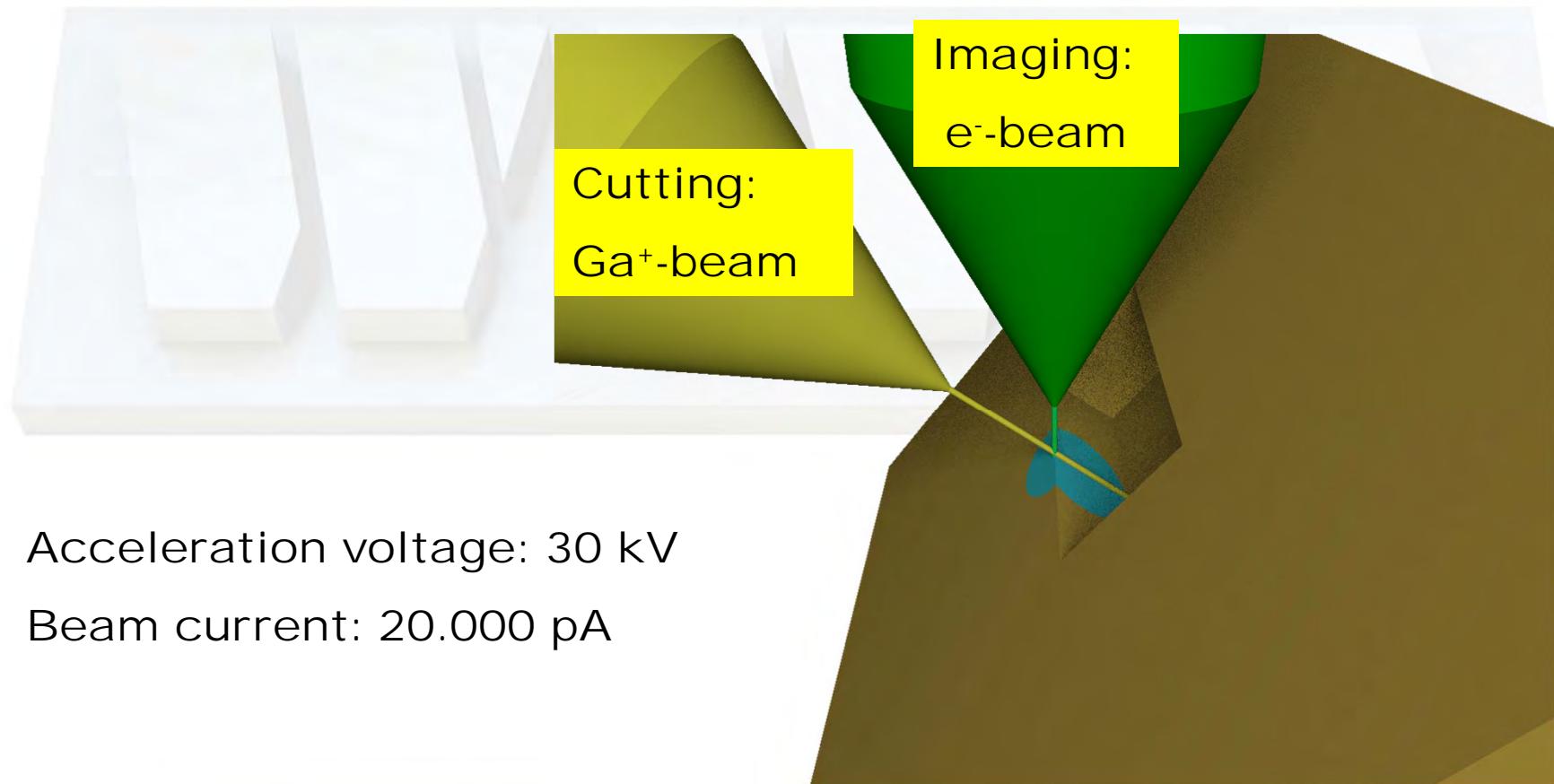
Analytical model of the problem



Orientation gradient mapping
Lattice rotations due to GND's

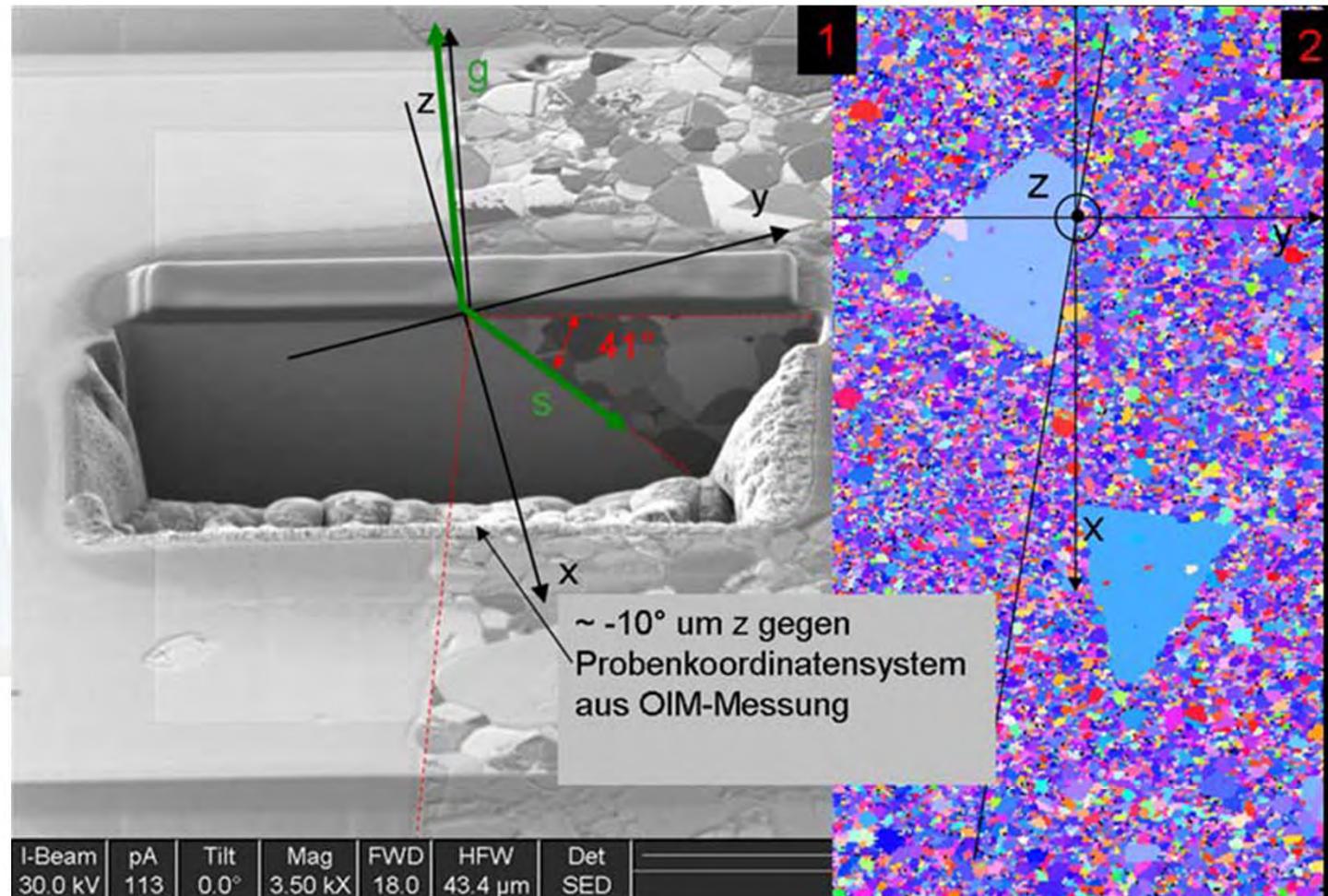


Cutting micro cracks near grain boundaries with the correct geometry



Acceleration voltage: 30 kV

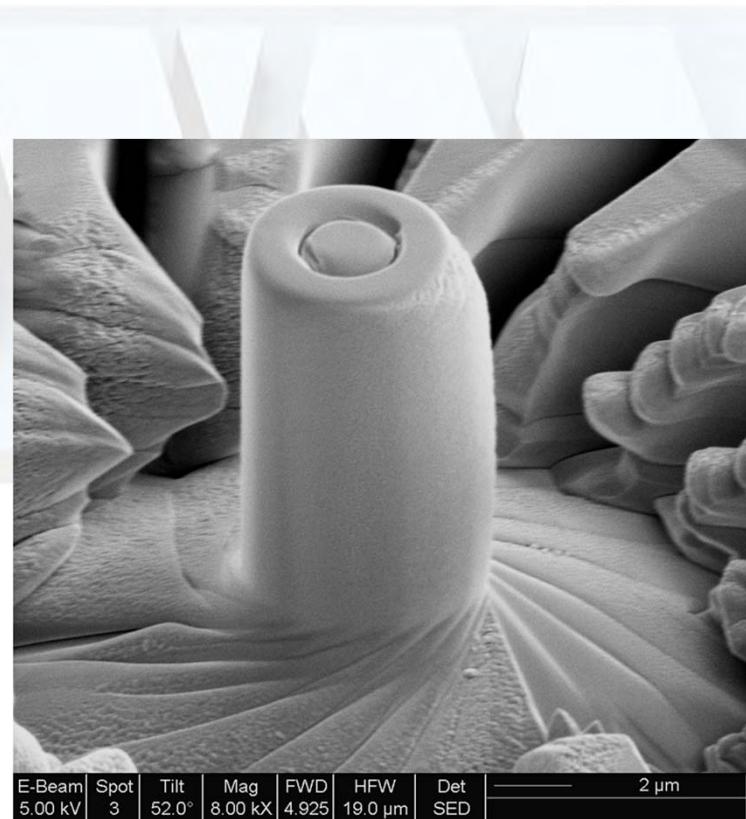
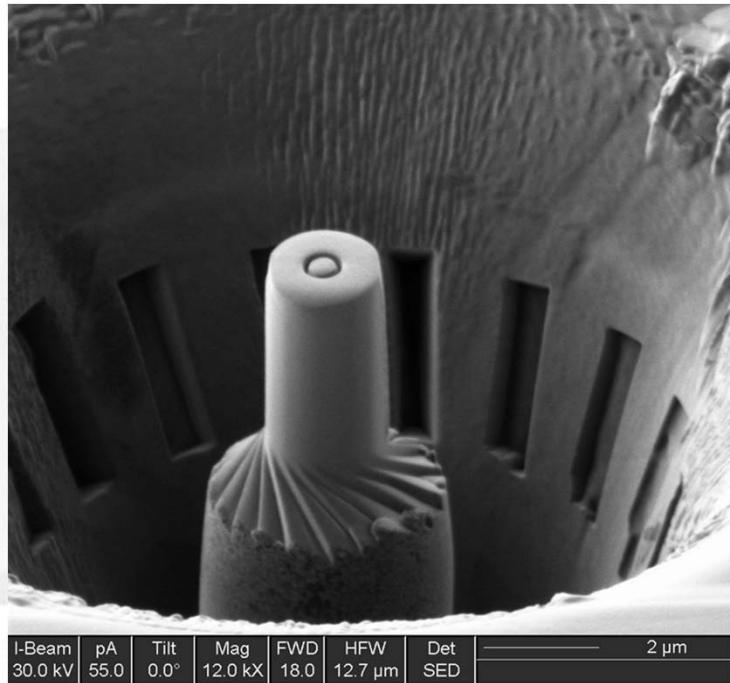
Beam current: 20.000 pA



Techniques used to characterize grains

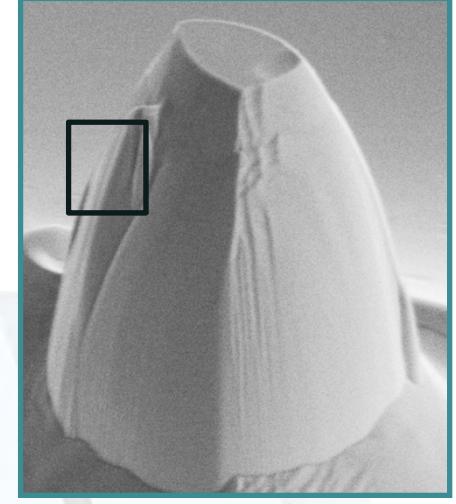
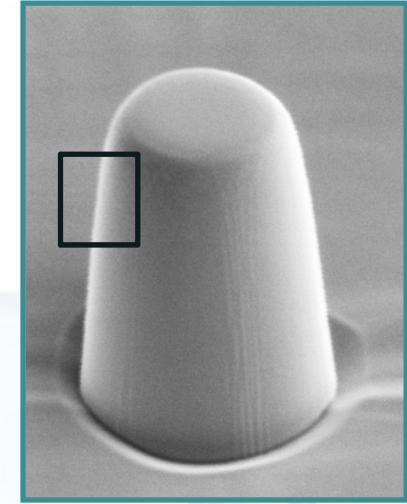
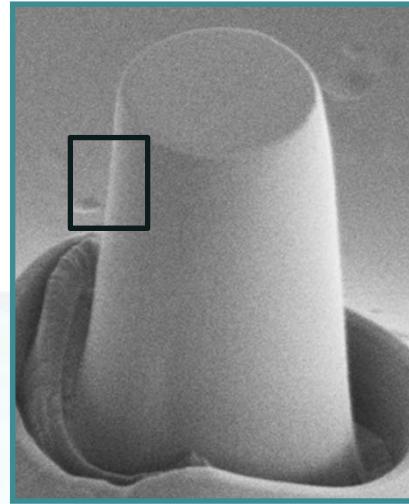
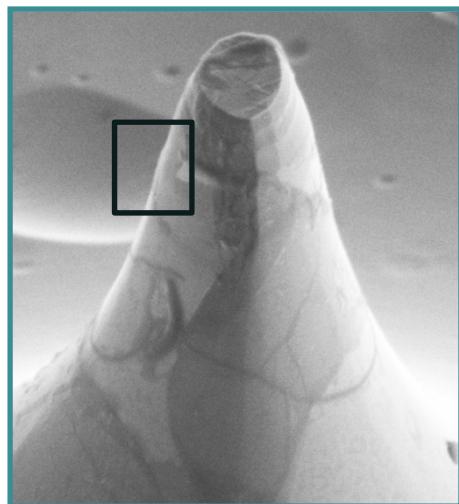


Sputtering process by FIB

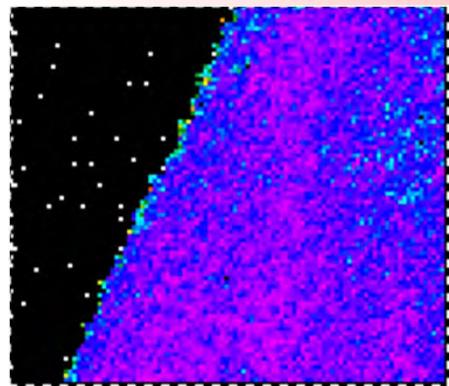




FIB Damage

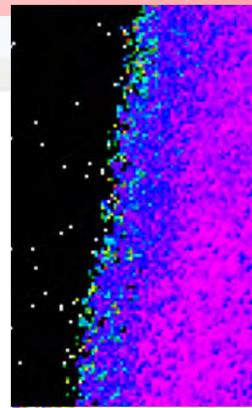


Lithography



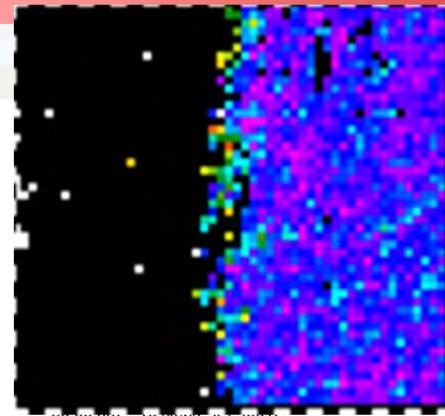
6 nm

Lithography+ FIB



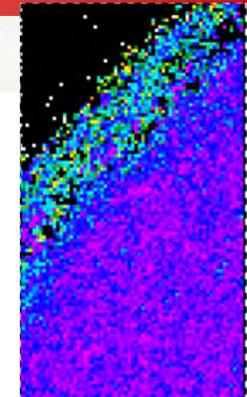
11 nm

FIB



15 nm

FIB

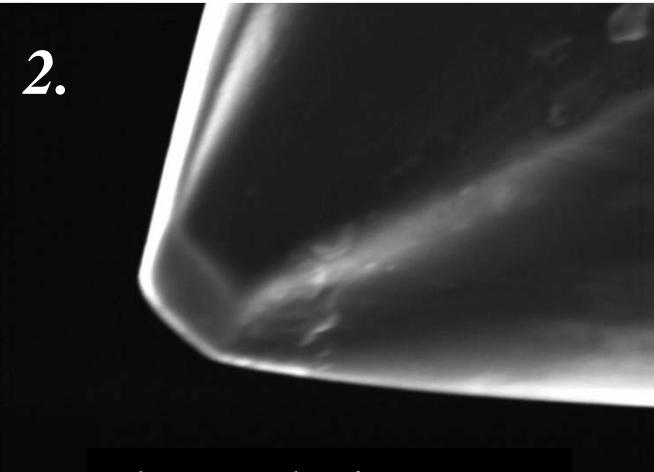
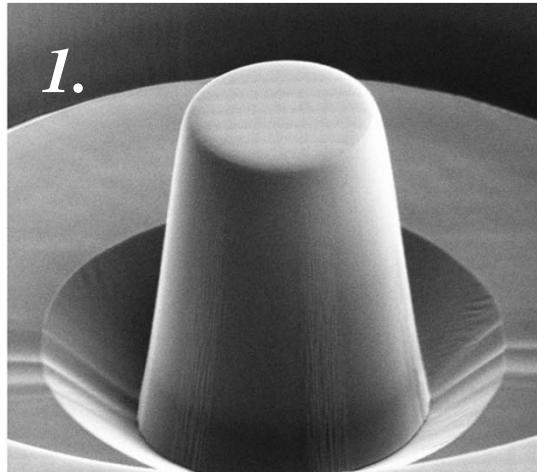


13

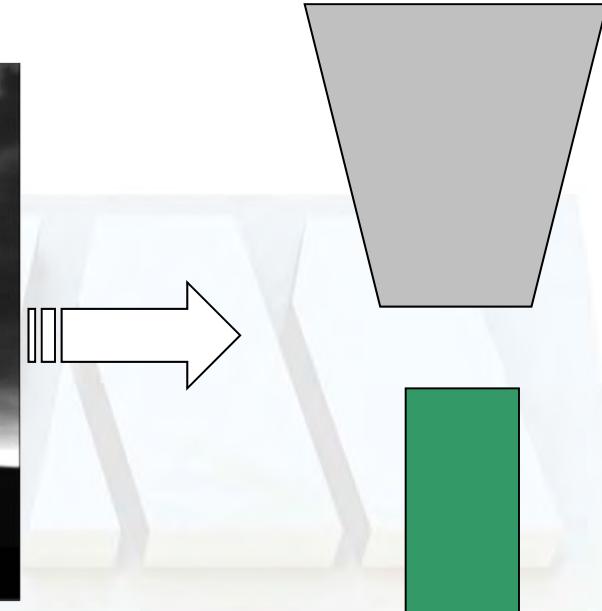
100 nm



Mikroproben



Flat Punch Tip

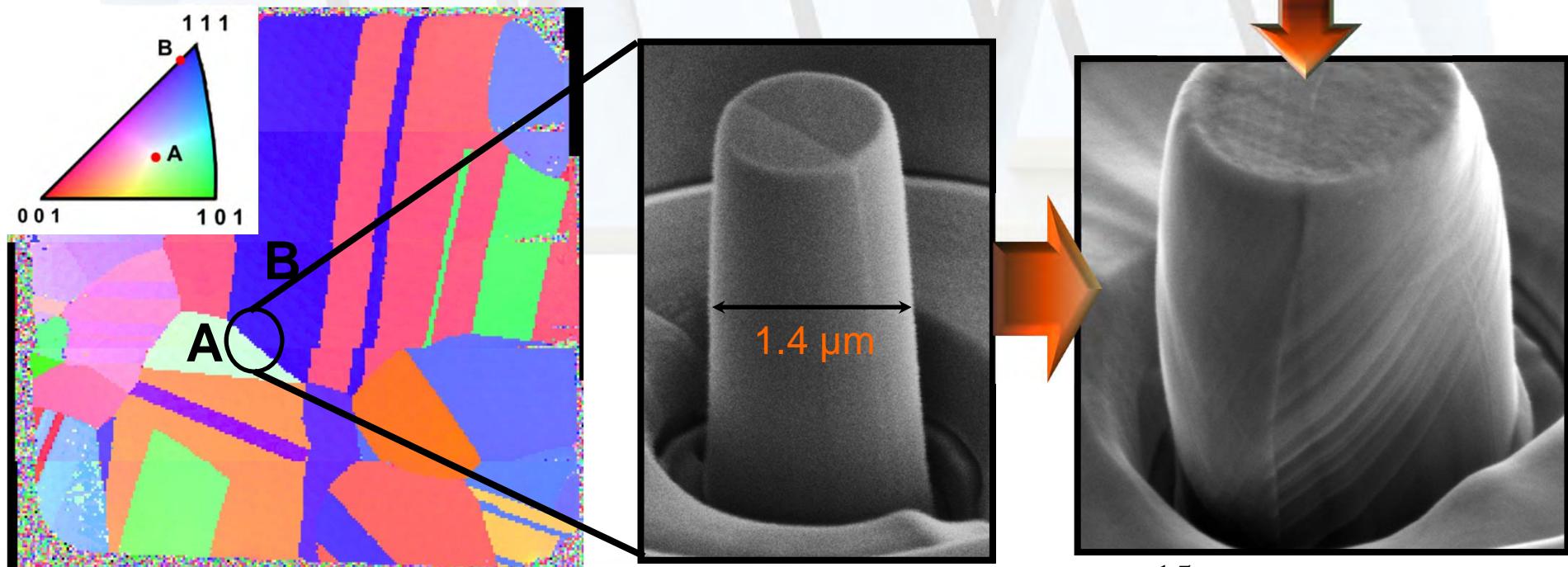




Experimental



- ✓ Mesoscopic length scale
- ✓ Molecular Dynamics (MD) simulation
- ✓ 1 to 4 Mio. atoms
- ✓ Embedded atom potential



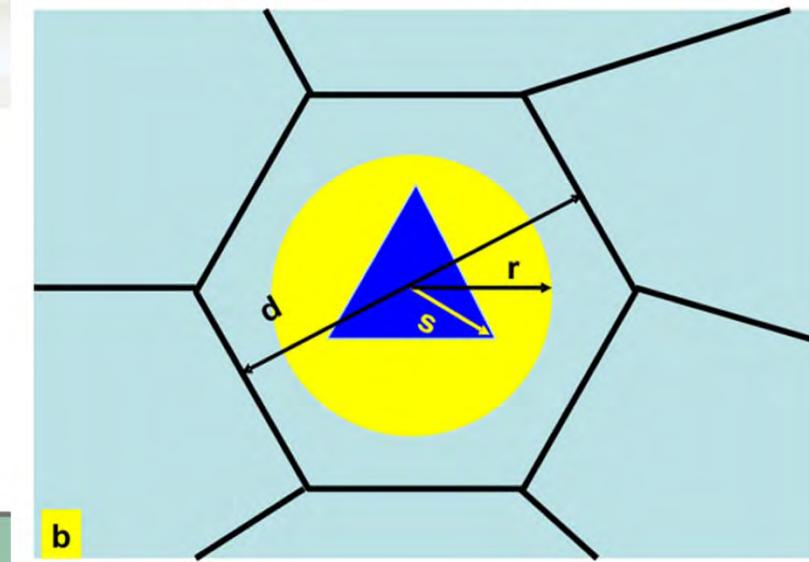
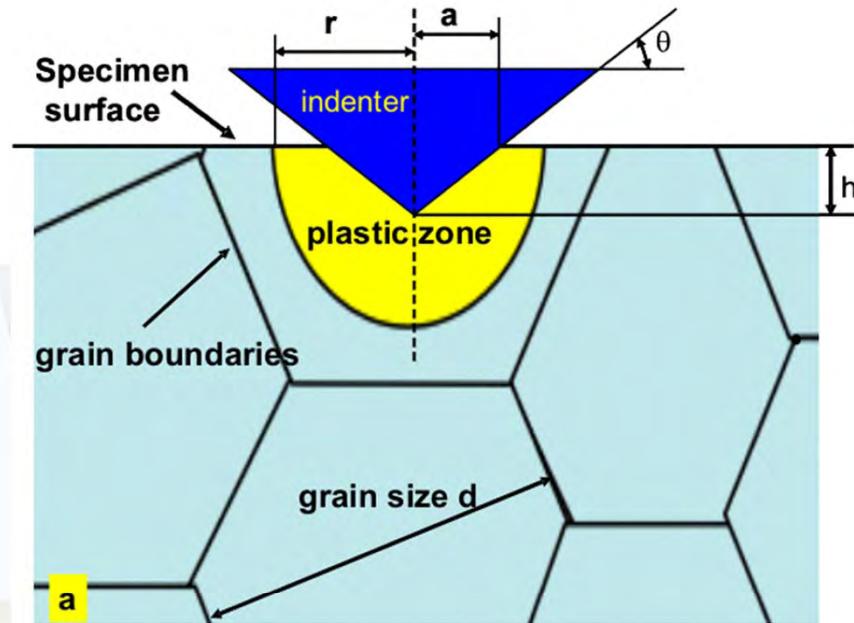
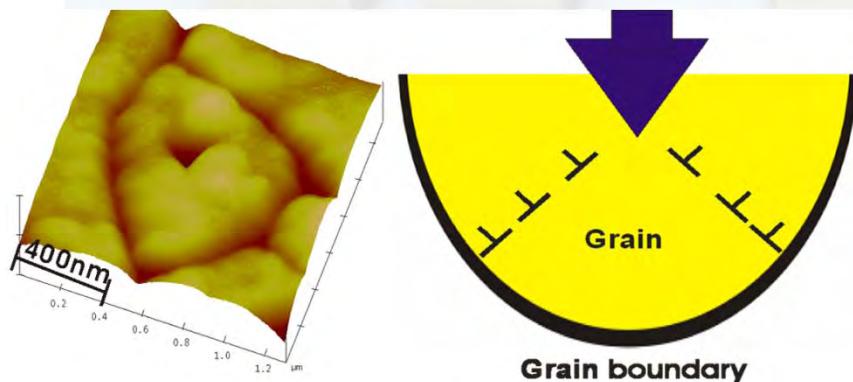
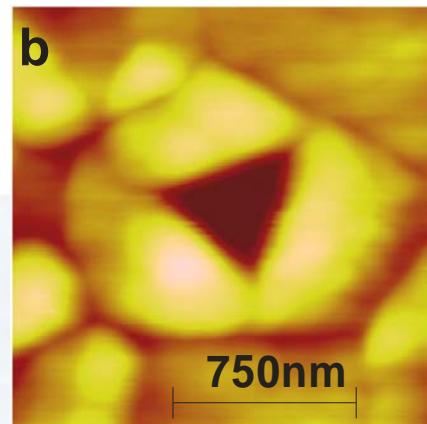
In cooperation with Dr. Ing. Afroz Barnoush (WWM) and Dr. Mao Wen (Shanghai Jiao Tong University, China)



The indentation size effect and grain boundaries

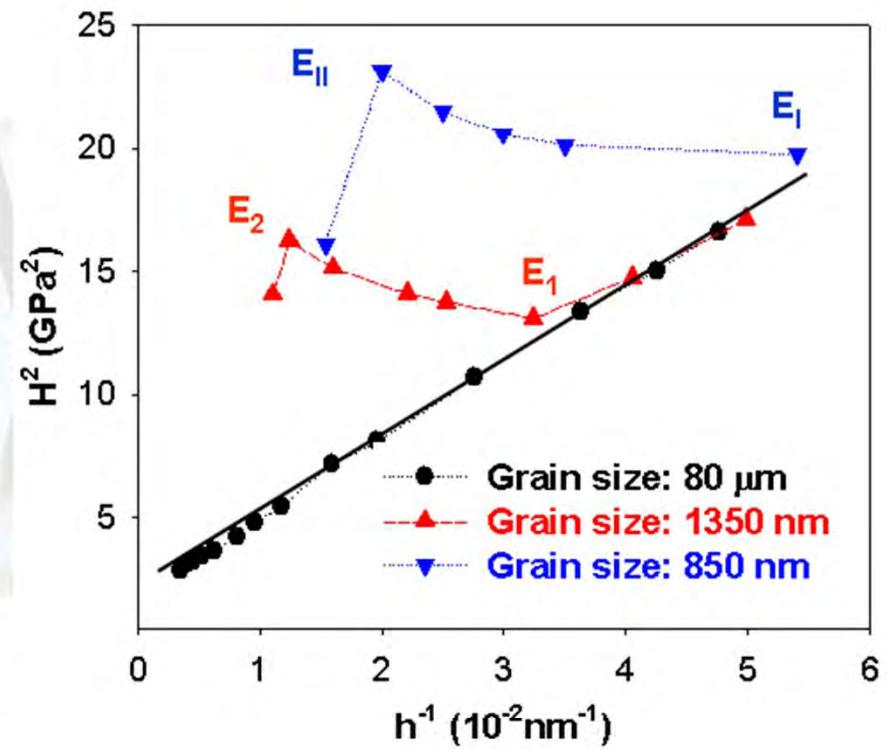
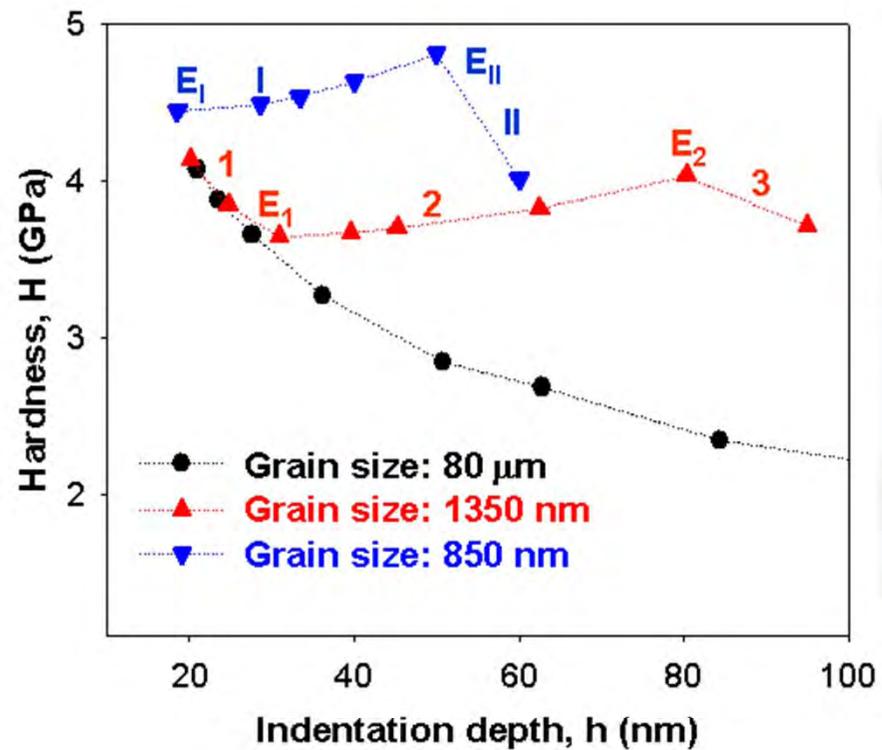


- Nanoindentation





Indentation size effect and lateral boundaries



$$H^2 = H_0^2 \left(1 + \frac{h_0}{h} \right)$$

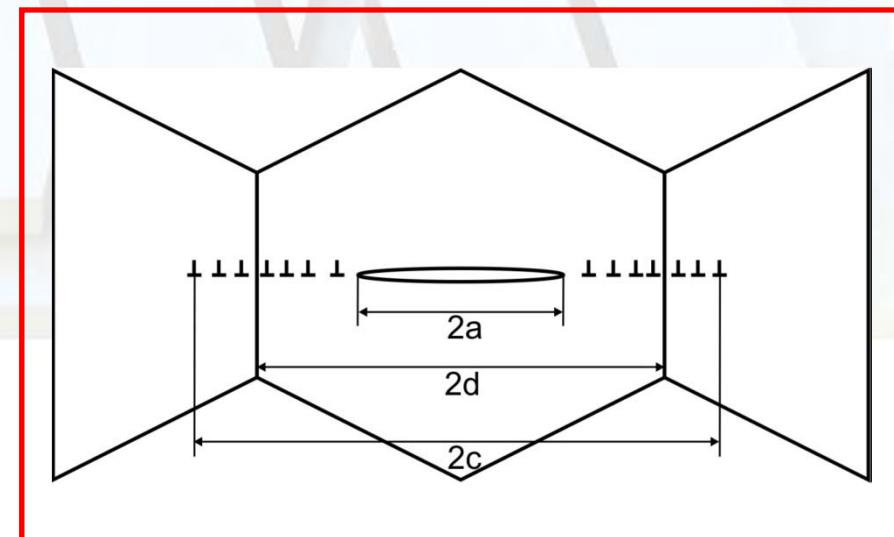
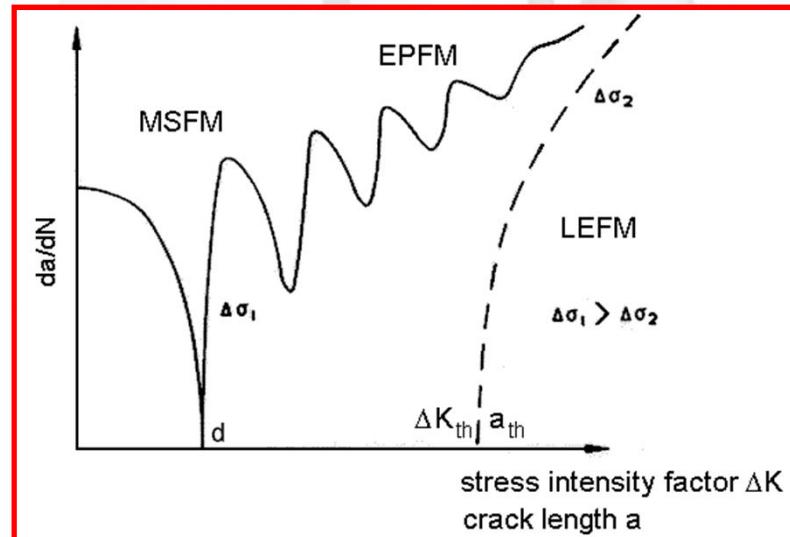


Grain boundary in front of the crack tip:

fluctuating crack propagation rate

crack stop possible

**which parameters describe the resistance of a grain boundary against
crack propagation?**



Experiments:

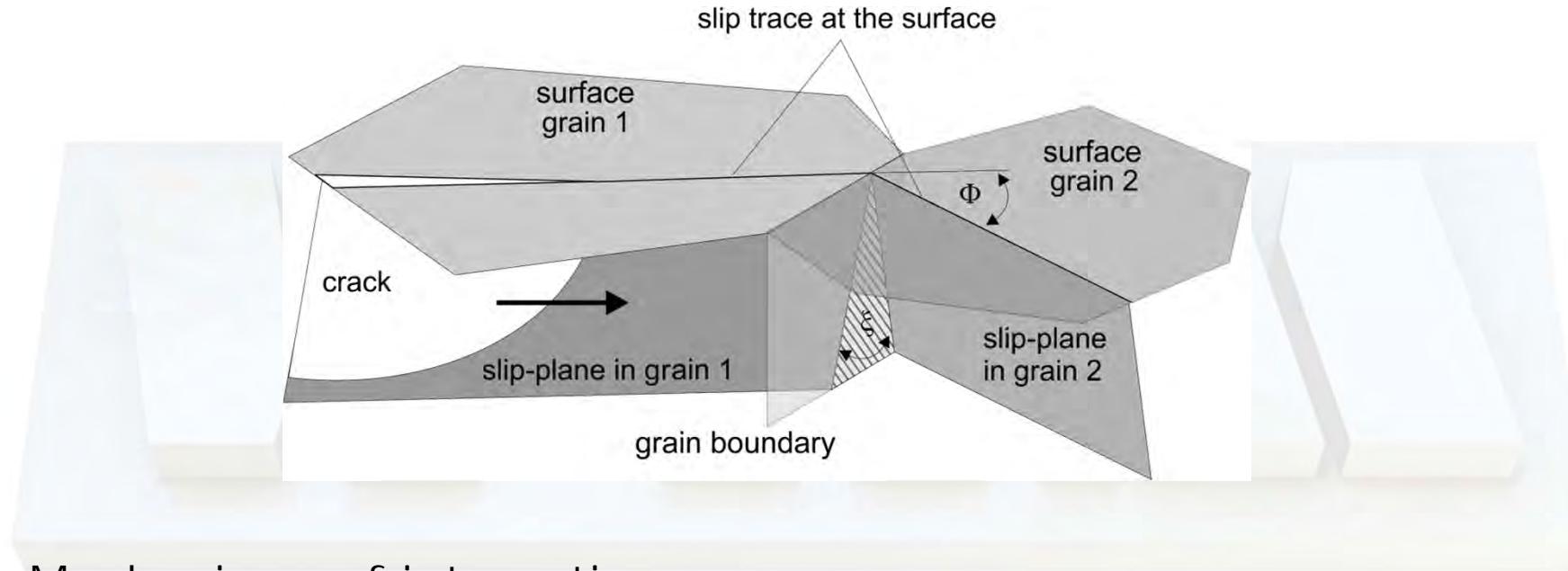
- Same Boundary, distance between crack and boundary is varied
- Same Crack, but different types of boundaries and grains



Interaction crack - grain boundary



3-D-problem: model of Zhai as example:



Mechanisms of interaction:

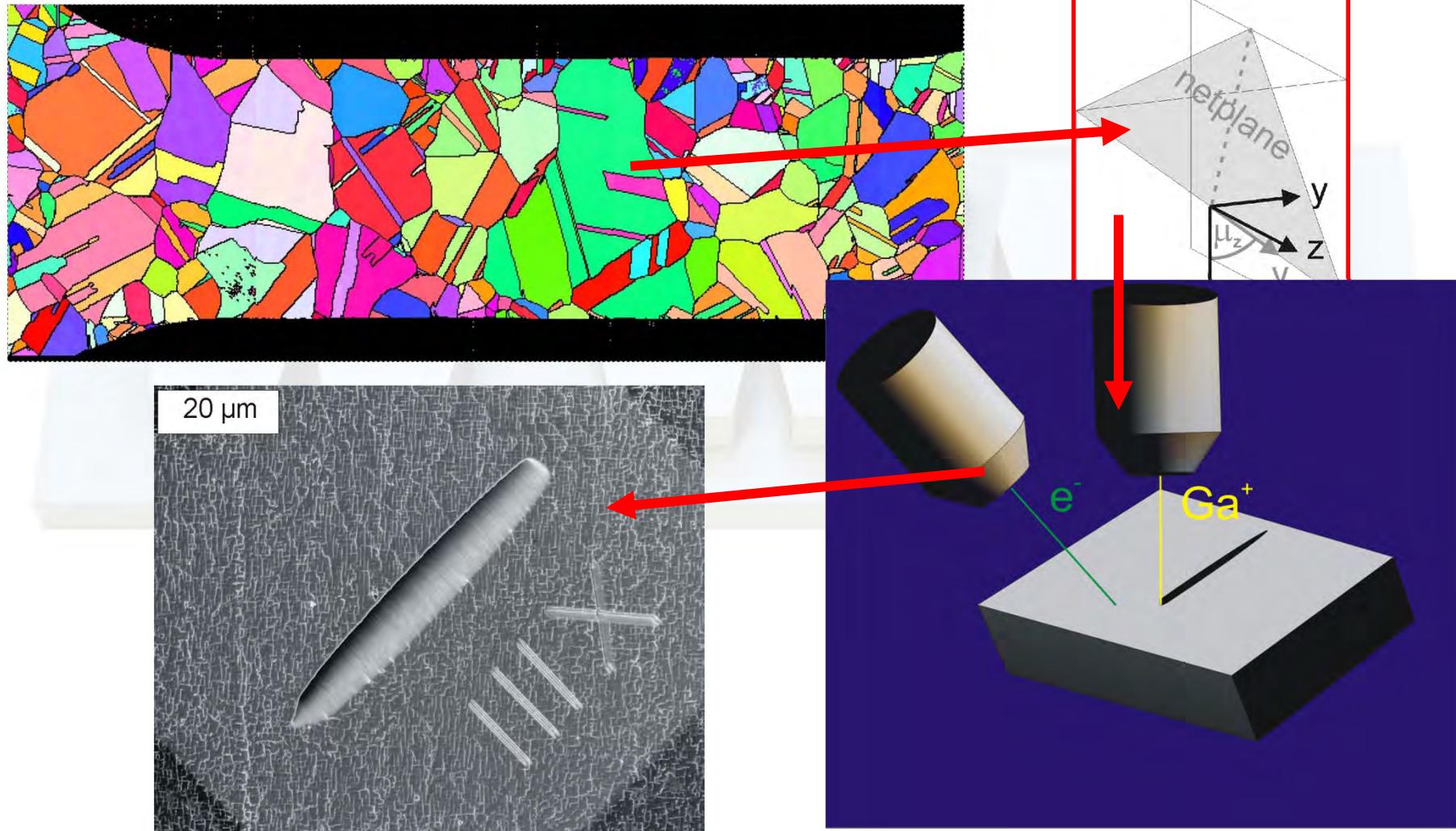
- inclination angle of the grain boundary?
- involved slip planes?
 - => 3 dimensional information needed!
 - => quantifying the model by 3D FIB tomography



Artificial crack initiation

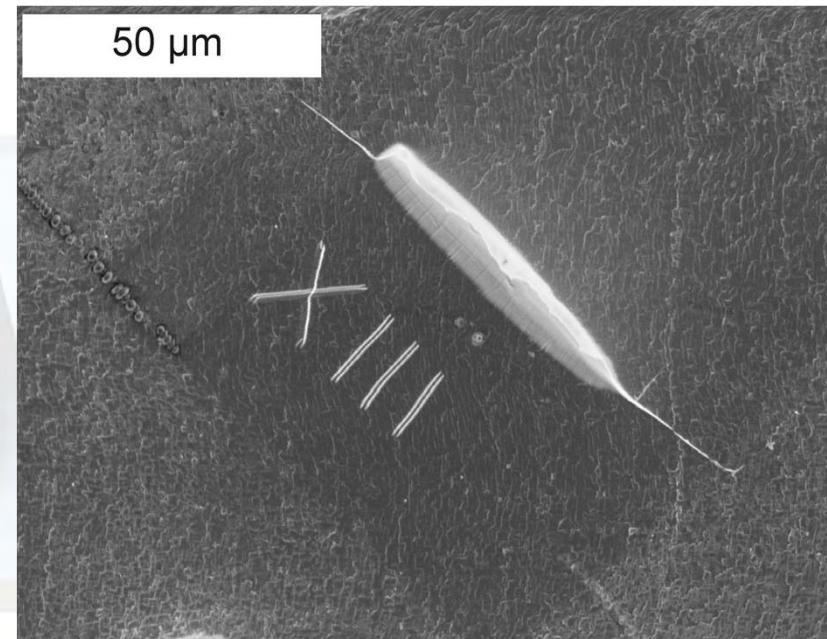
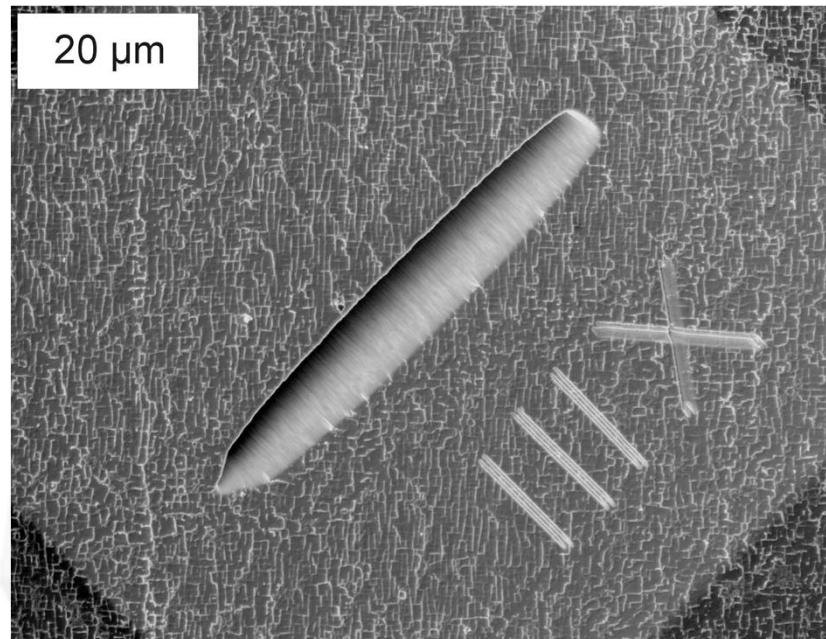


Initiating a crack with a FIB cut notch:





Stage I crack parallel to a slip plane



Combining OIM with FIB

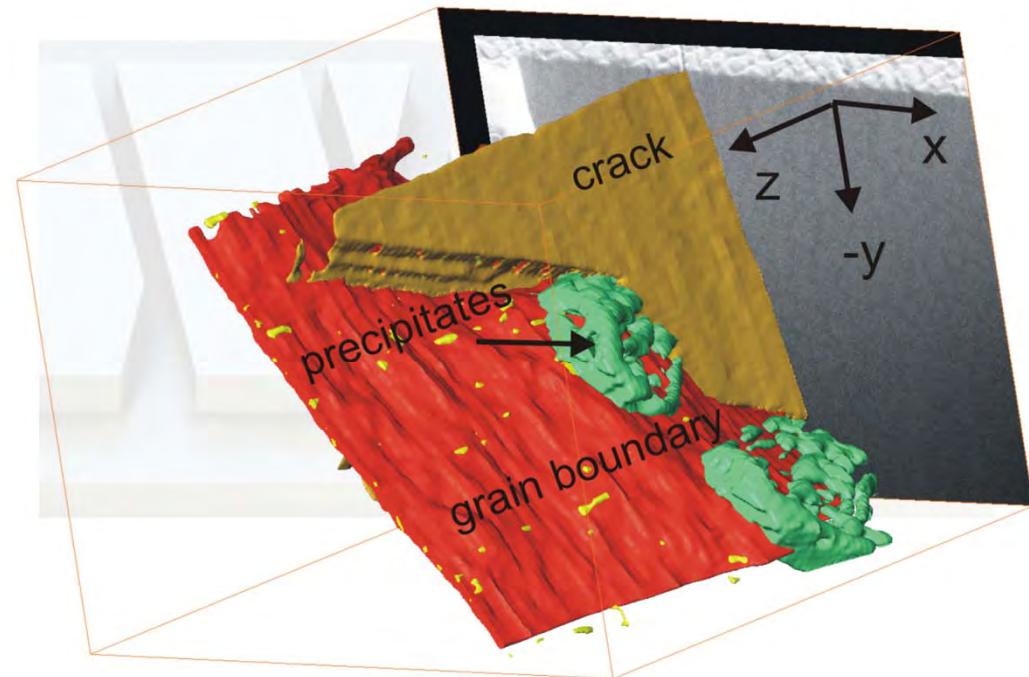
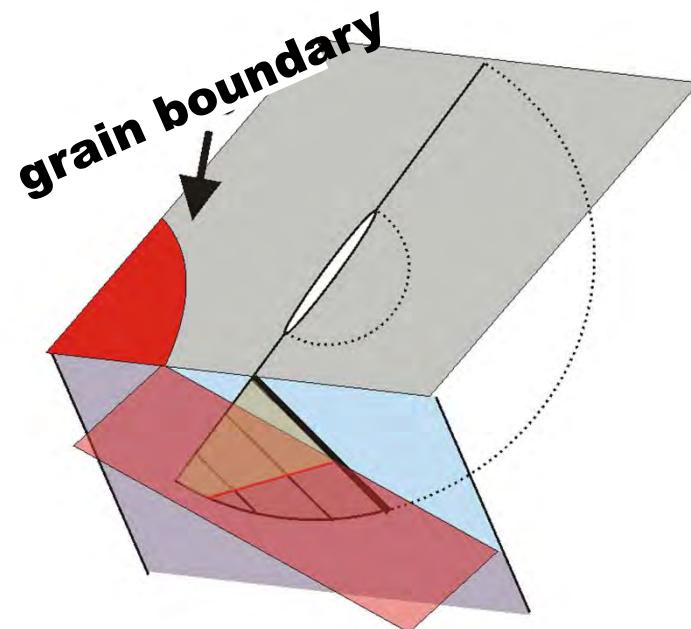
Schäf, Marx, Holzapfel, Vehoff, Mat. Sci. 2006



FIB-tomography



Analysis of the images enables **a 3D reconstruction of the crack**





Growth of artificial cracks

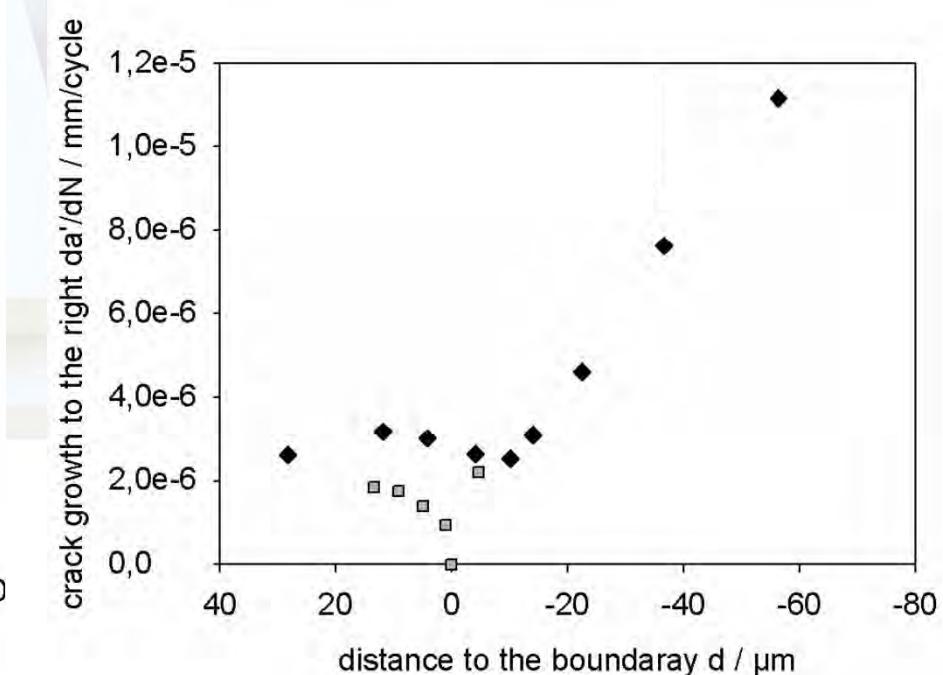
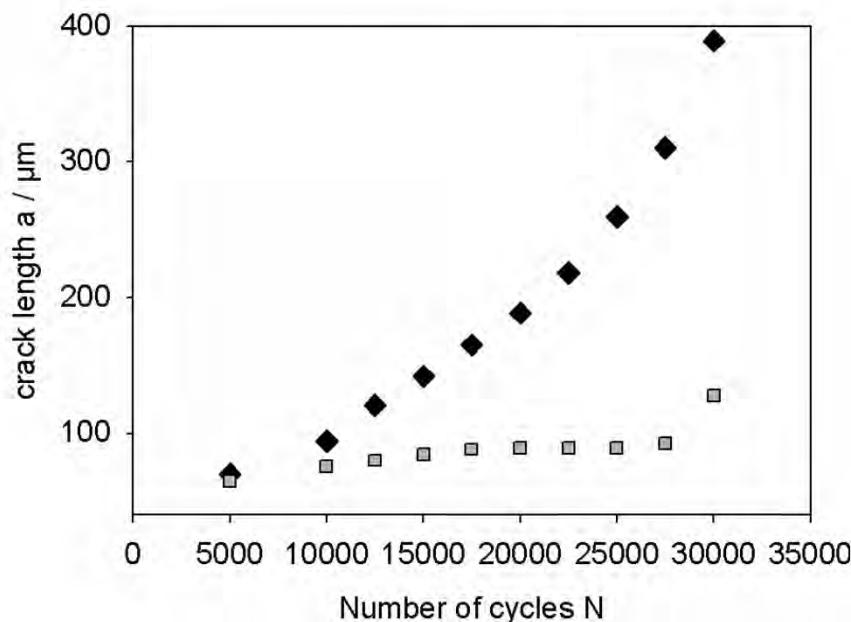


Fatigue tests interrupted for replicas

- stress amplitude: $\sigma_A = 300 \text{ MPa}$

- load ratio $R = -0.1$

Two cracks with different lengths interact with the same grain boundary



different crack propagation rates!

Some cracks stop or only move slower, why?

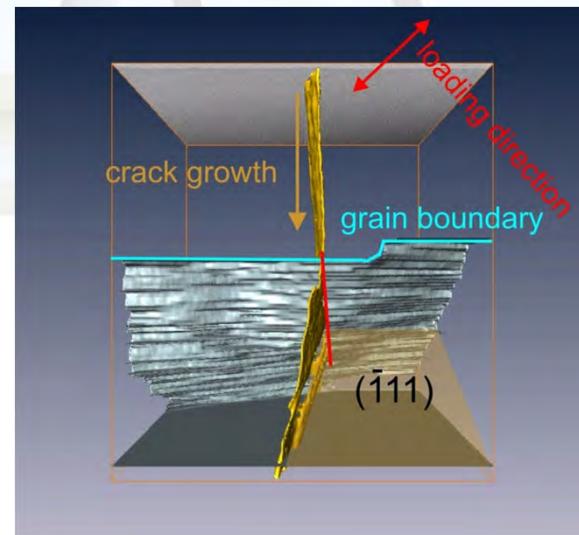
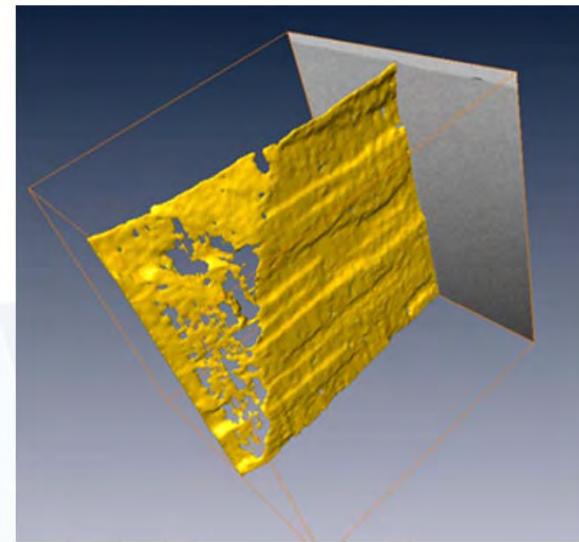
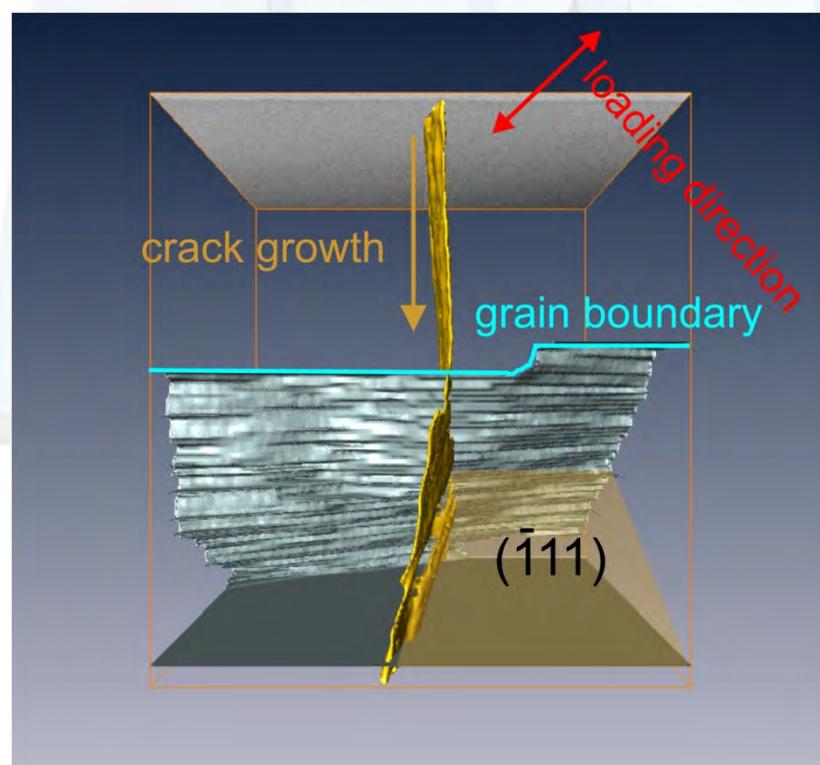


Influence of the microstructure



Mechanisms of interaction:

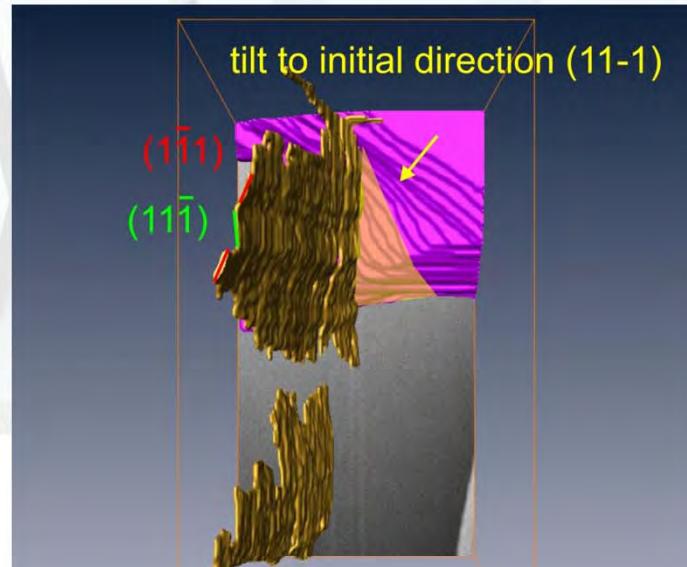
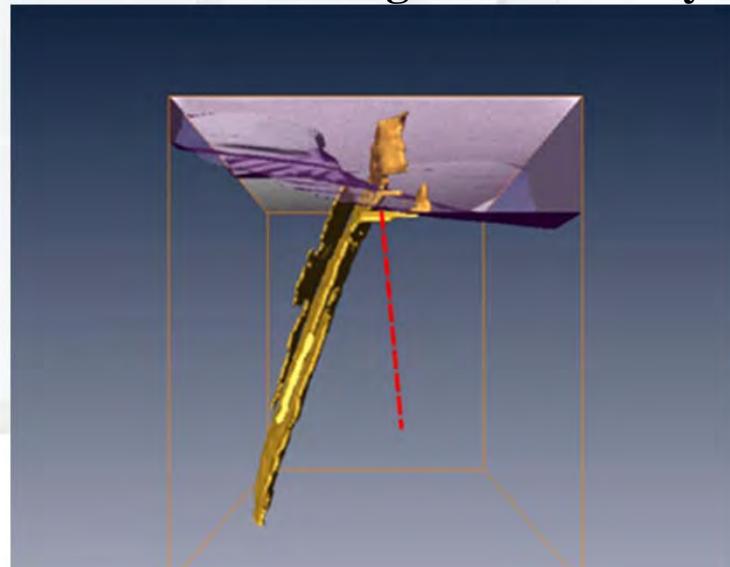
- large misorientation angle
- but only deceleration





Mechanisms of interaction:

- same grain boundary
- second crack with identical crack parameters
- other inclination of the grain boundary



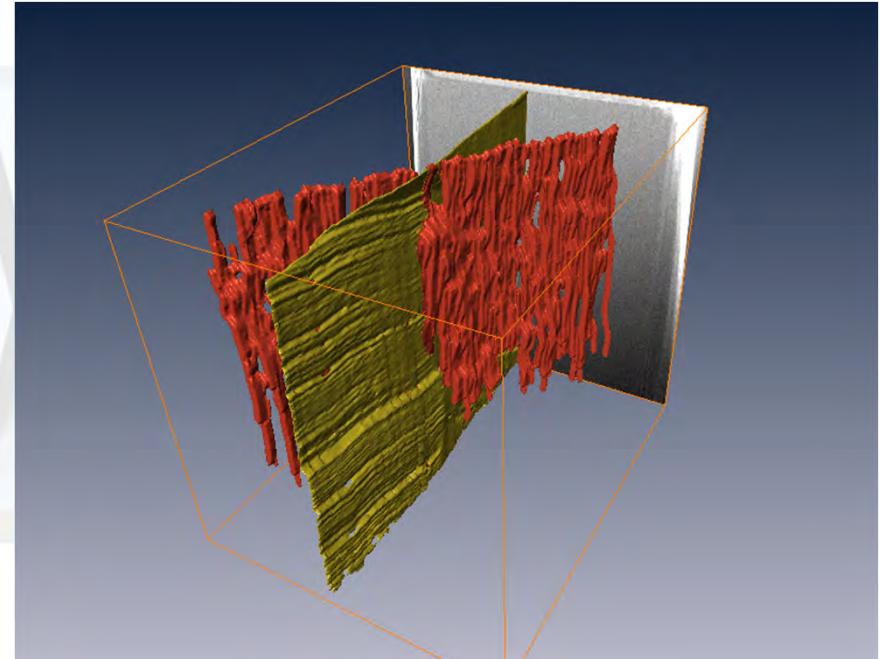
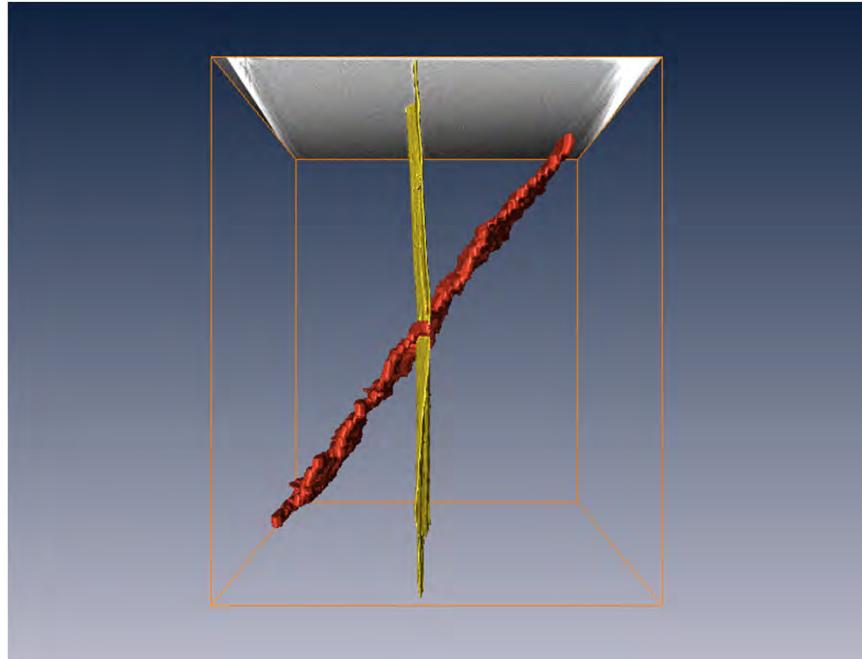
resistance of a grain boundary against crack propagation determined by:

- possibility for the crack to propagate continuously through the grain boundary
- not determined by the misorientation angle of the active slip planes?



Mechanisms of interaction:

- grain boundary with special orientation



crack passes the grain boundary by alternating activation of (111) slip planes for a continuous propagation through the grain boundary



Quantifying the crack propagation:

1. for a slip band without grain boundary (Equilibrium Slip Bands, ESP):

$$\frac{da}{dN} = C \cdot \Delta CTSD^n$$

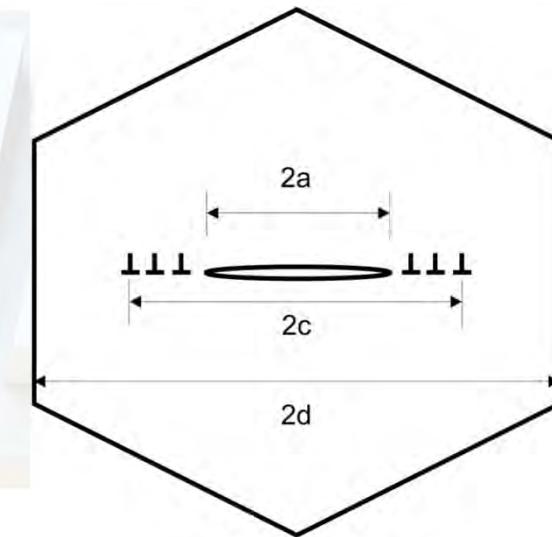
BCS-model used by Tanaka¹:

crack tip sliding displacement

$$\Delta CTSD = \left(\frac{2\tau^* a}{\pi^2 A} \right) \ln \left(\frac{c}{a} \right), \quad A = \frac{G}{2\pi(1-\nu)}$$

τ^* = shear-stress necessary to move a dislocation

$$\frac{a}{c} = \cos \left(\frac{\pi \Delta \tau}{2\tau^*} \right)$$



parameters needed:

- constants C and n
- shear-stress τ^*
- Schmid-factor (to calculate $\Delta\tau$ from applied load σ)

¹Tanaka K., Akiniwa Y., Nakai y., Wei R.P.: Engineering Fracture Mechanics, Vol.24, 803-819, 1986



Numerical model

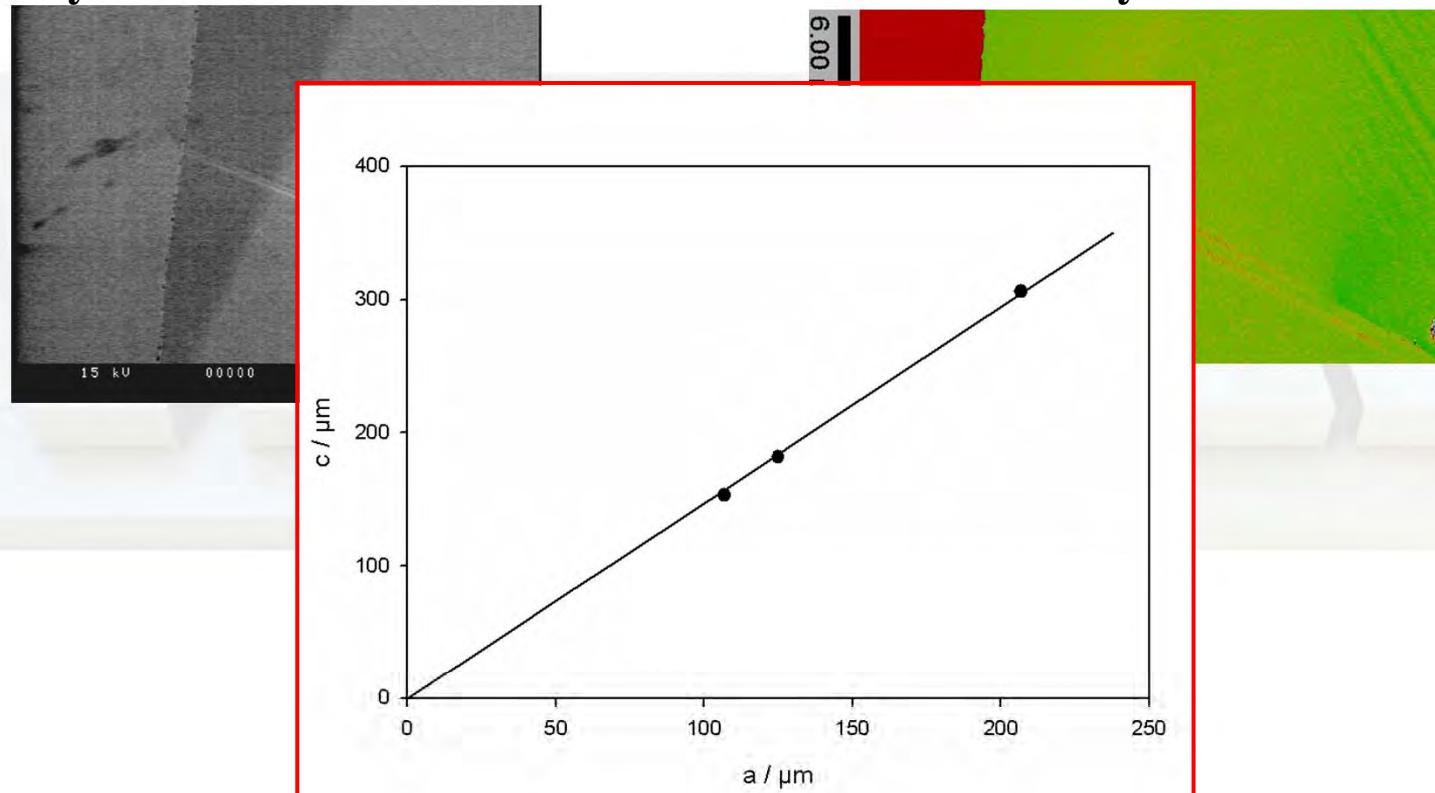


Quantifying the crack propagation:

measuring the plastic zone size:

by ECCI

and by EBSD



$$\frac{a}{c} = \cos\left(\frac{\pi\Delta\tau}{2\tau^*}\right) \Rightarrow \text{shear-stress } \tau^* = 502 \text{ MPa}$$



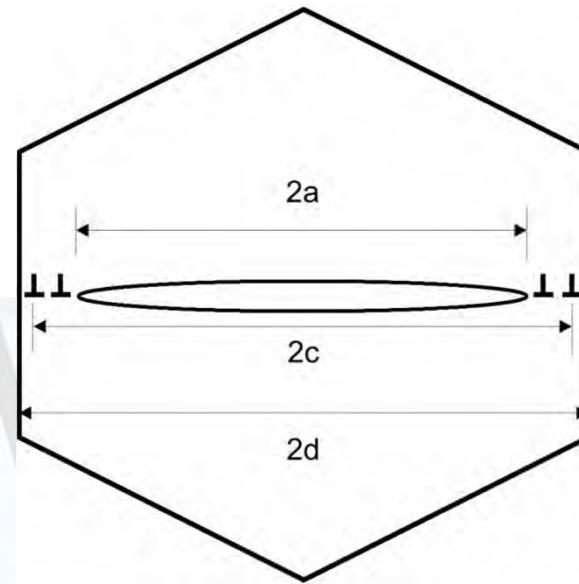
Quantifying the crack propagation:

2. for a slip band with grain boundary

2 a) plastic zone blocked by the grain boundary (Blocked Slip Band, BSB):

$$\Delta CTSD = \left(\frac{\beta \Delta \tau}{\pi A} \right) (c^2 - a^2)^{1/2} + \left(\frac{2\tau^* a}{\pi^2 A} \right) \ln \left(\frac{c}{a} \right)$$

$$\beta = 1 - \left(\frac{2\tau^*}{\pi \Delta \tau} \right) \arccos \left(\frac{a}{c} \right)$$



2 b) plastic zone spread in the neighboring grain (Propagating Slip Band, PSB):

resulting shear-stress τ^* determined by τ_1 and τ_2 of both grains:

$$\Delta CTSD = \left(\frac{2\tau^* a}{\pi^2 A} \right) \ln \left(\frac{c}{a} \right) + \left(\frac{\tau_{-2}^* - \tau^*}{\pi^2 A} \right) g(a; c, d)$$

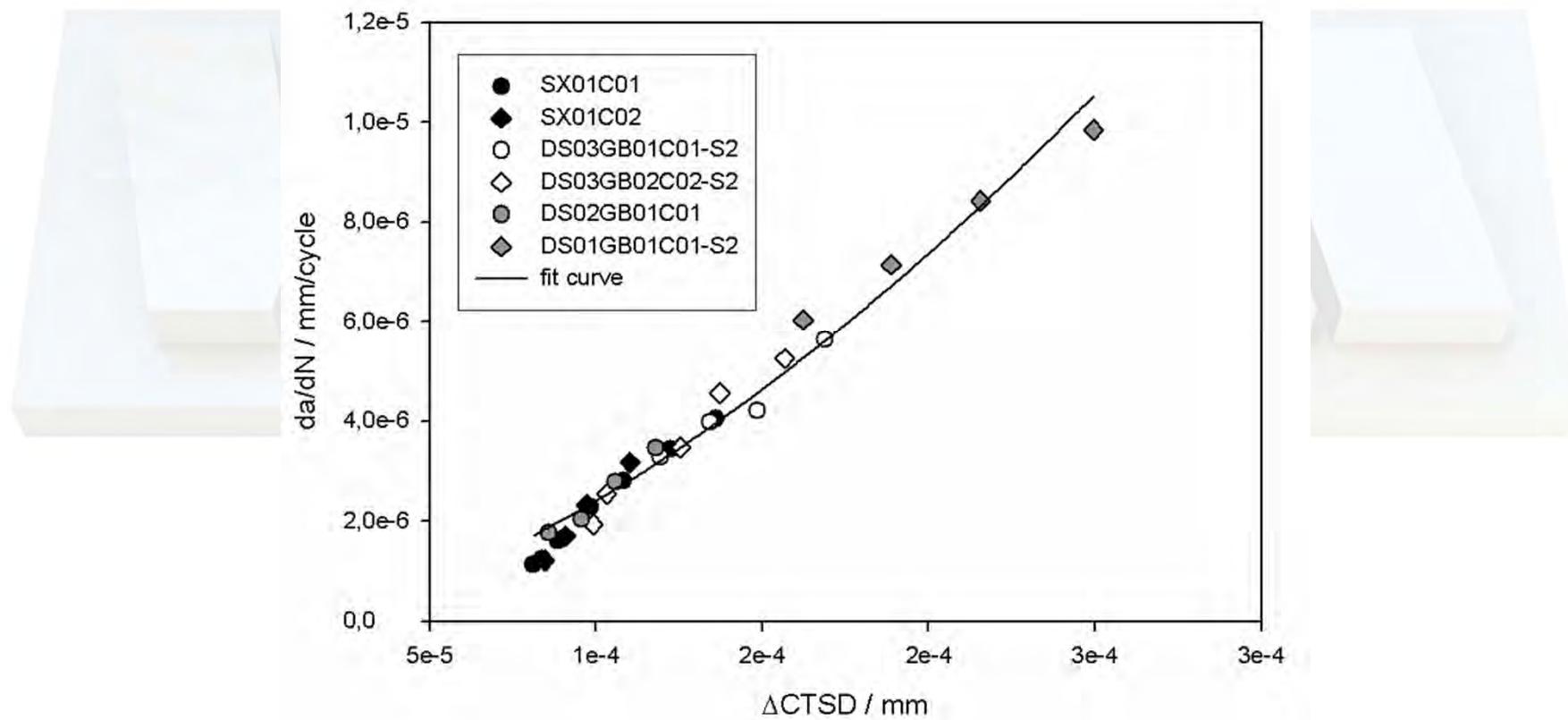
$$g(a; c, d) = d \cdot \ln \left| \frac{\sqrt{c^2 - d^2} + \sqrt{c^2 - a^2}}{\sqrt{c^2 - d^2} - \sqrt{c^2 - a^2}} \right| - a \cdot \ln \left| \frac{a\sqrt{c^2 - d^2} + d\sqrt{c^2 - a^2}}{a\sqrt{c^2 - d^2} - d\sqrt{c^2 - a^2}} \right|$$



Numerical model



Quantifying the crack propagation:
measuring the crack propagation rate by replica technique

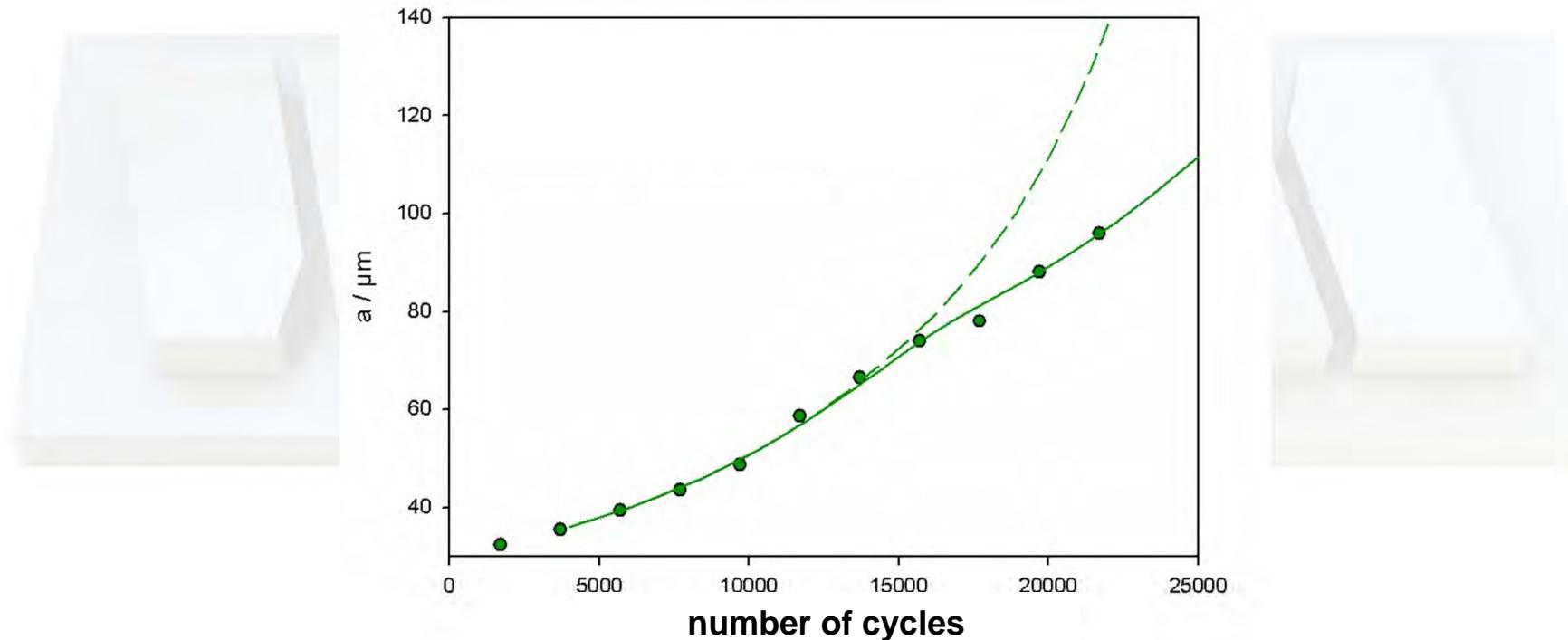




Quantifying the crack propagation:

2. for a slip band with grain boundary

2 b) plastic zone spread in the neighboring grain (Propagating Slip Band, PSB):



calculation done with the parameters from the single crystal measurements

no further fit-parameter!

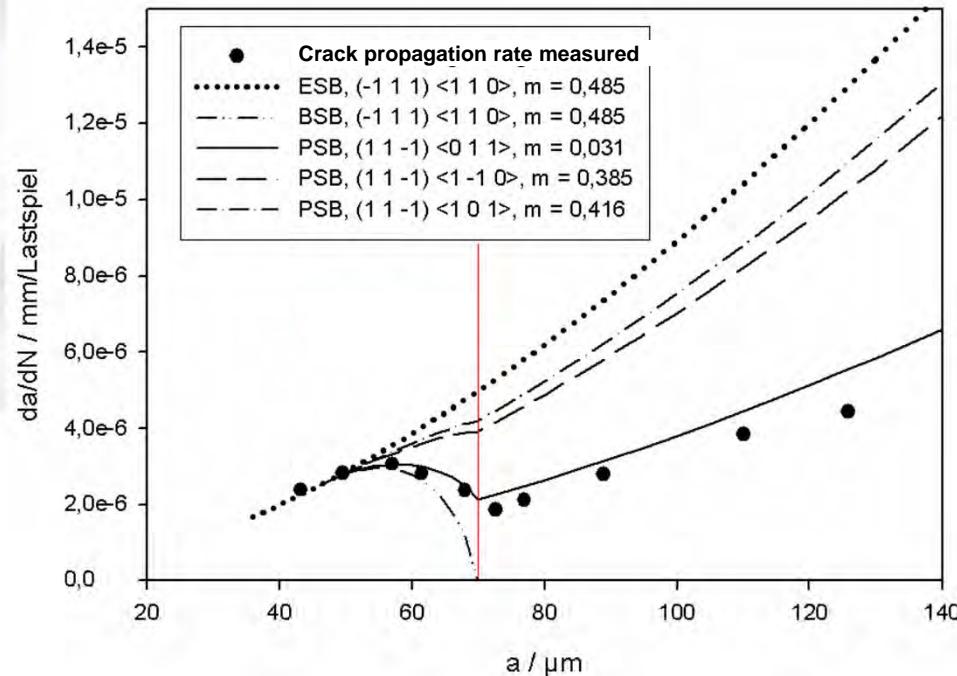


Quantifying the crack propagation:

2. for a slip band with grain boundary

2 b) plastic zone spread in the neighboring grain (Propagating Slip Band PSB):

shear-stress τ^* determined by τ_1 and τ_2 of both grains:

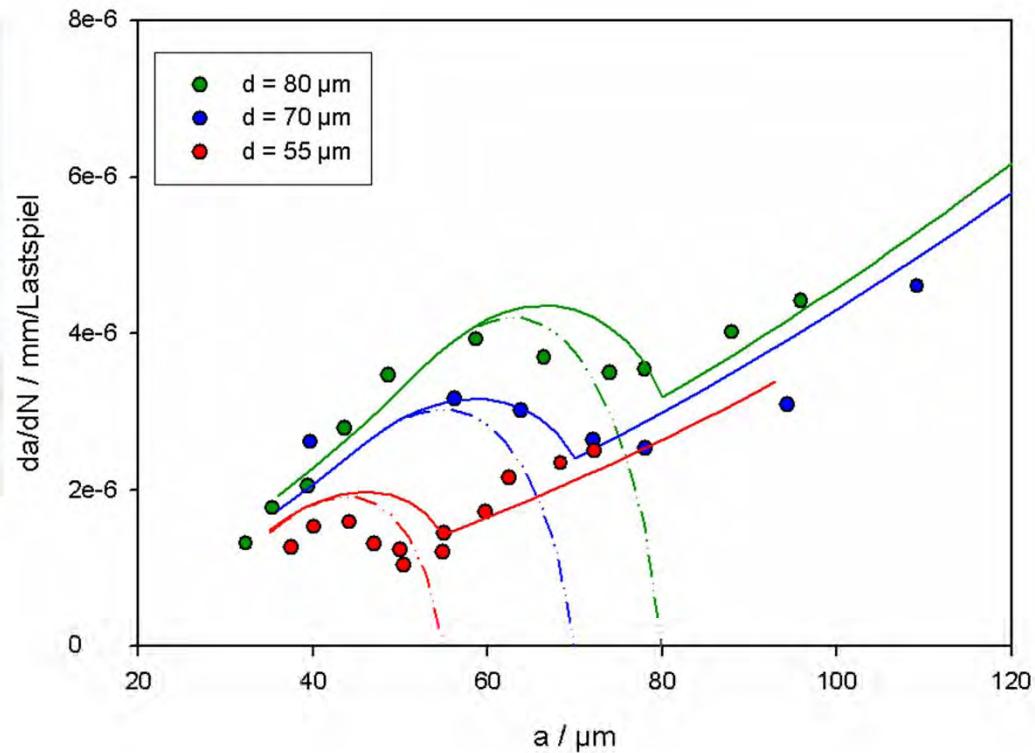


τ_2 determined for the adjacent grain by the slip system with the lowest Schmid-factor



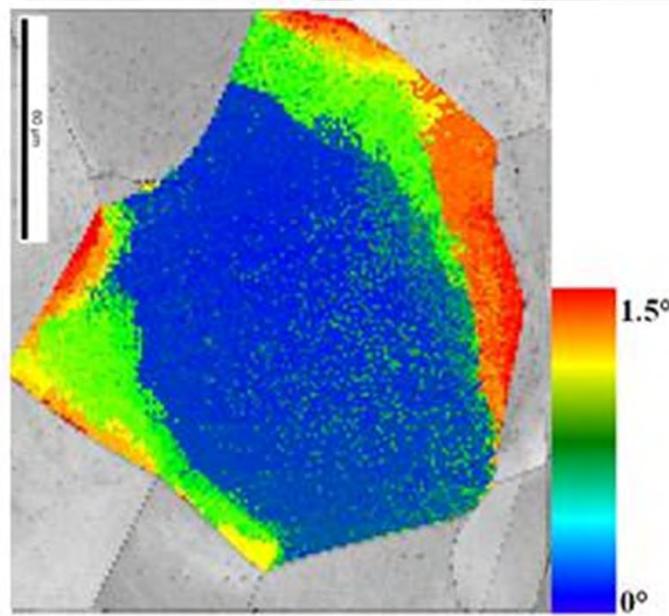
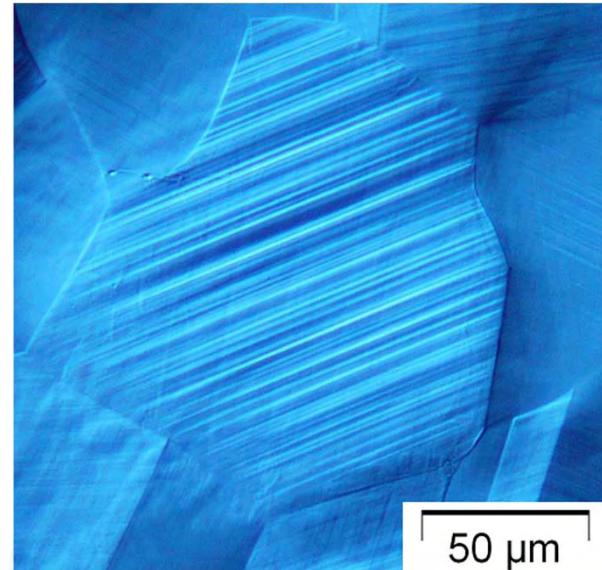
Quantifying the crack propagation:

2. for a slip band with grain boundary and different distances between notch tip and grain boundary

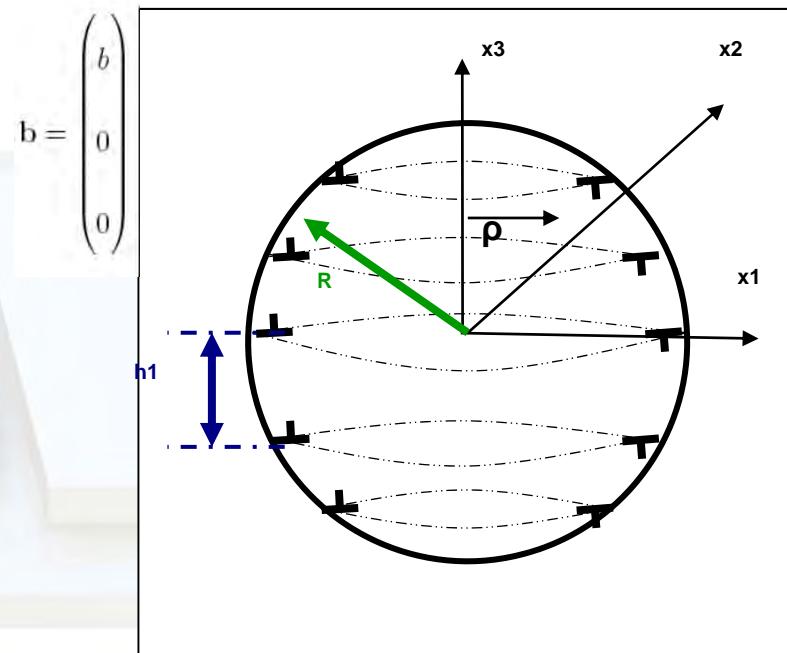




Dislocations and boundaries



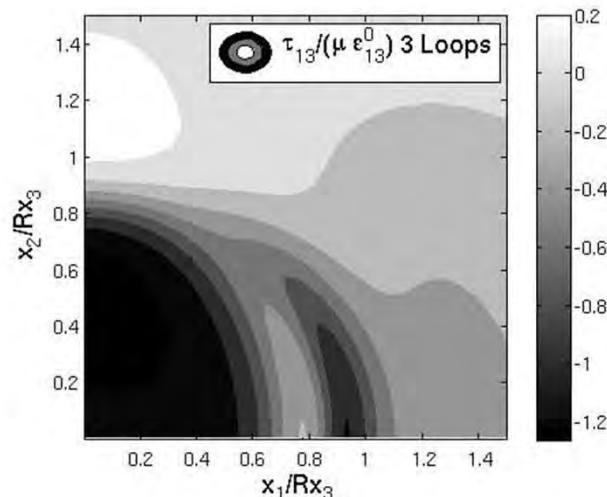
Analytical model of the problem



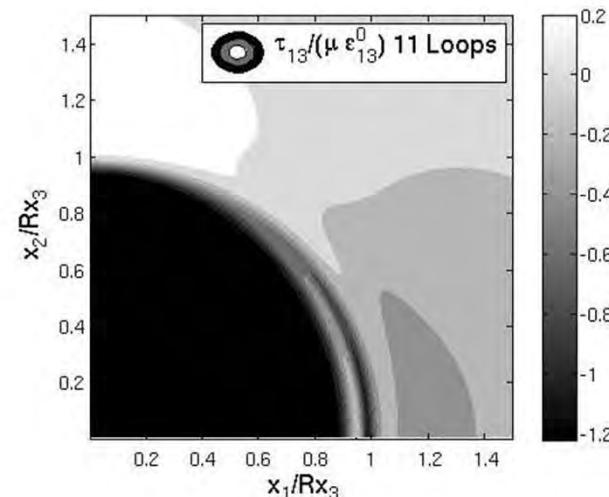
Orientation gradient mapping
Lattice rotations due to GND's



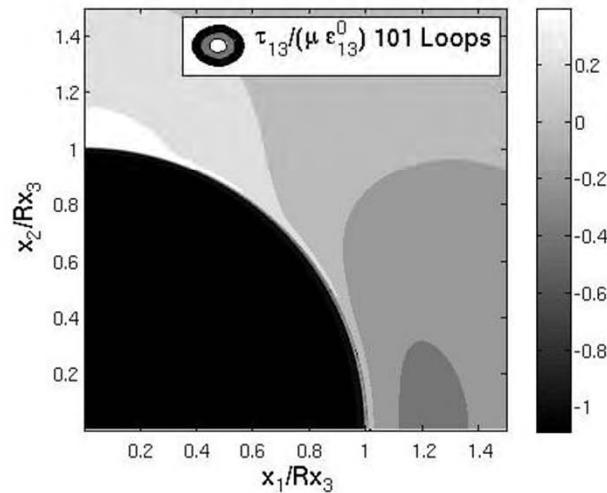
Stress concentration at grain boundaries as a function of the number of discrete slipbands



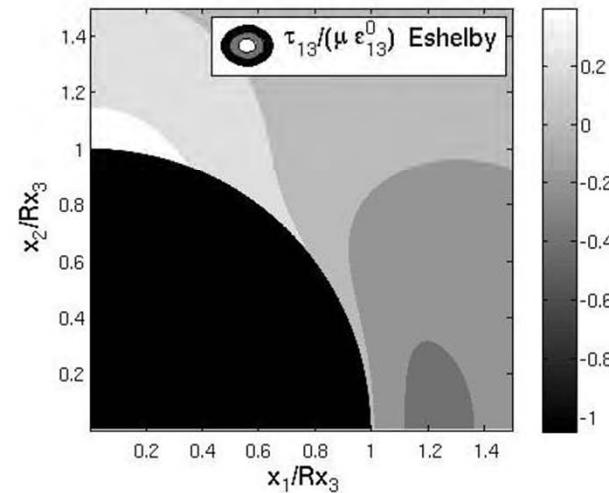
(a)



(b)



(c)



(d)

3 and 11
Slip bands

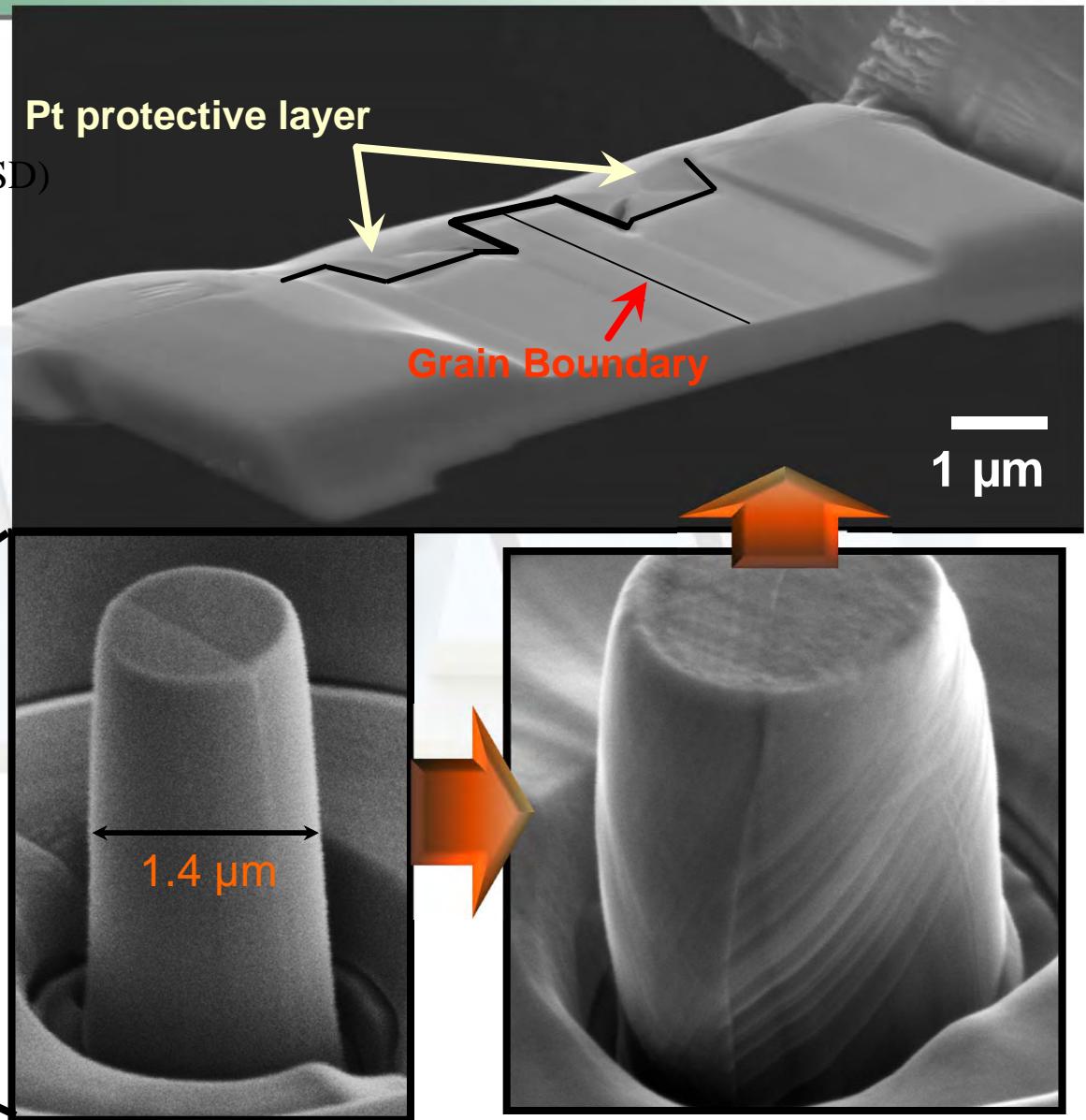
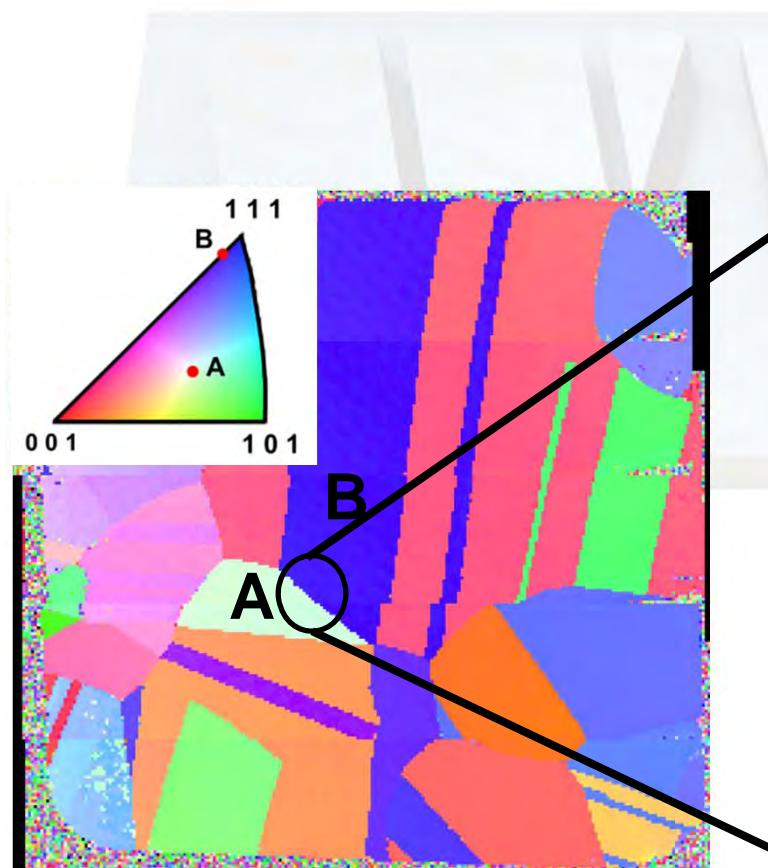
101 and
continuum



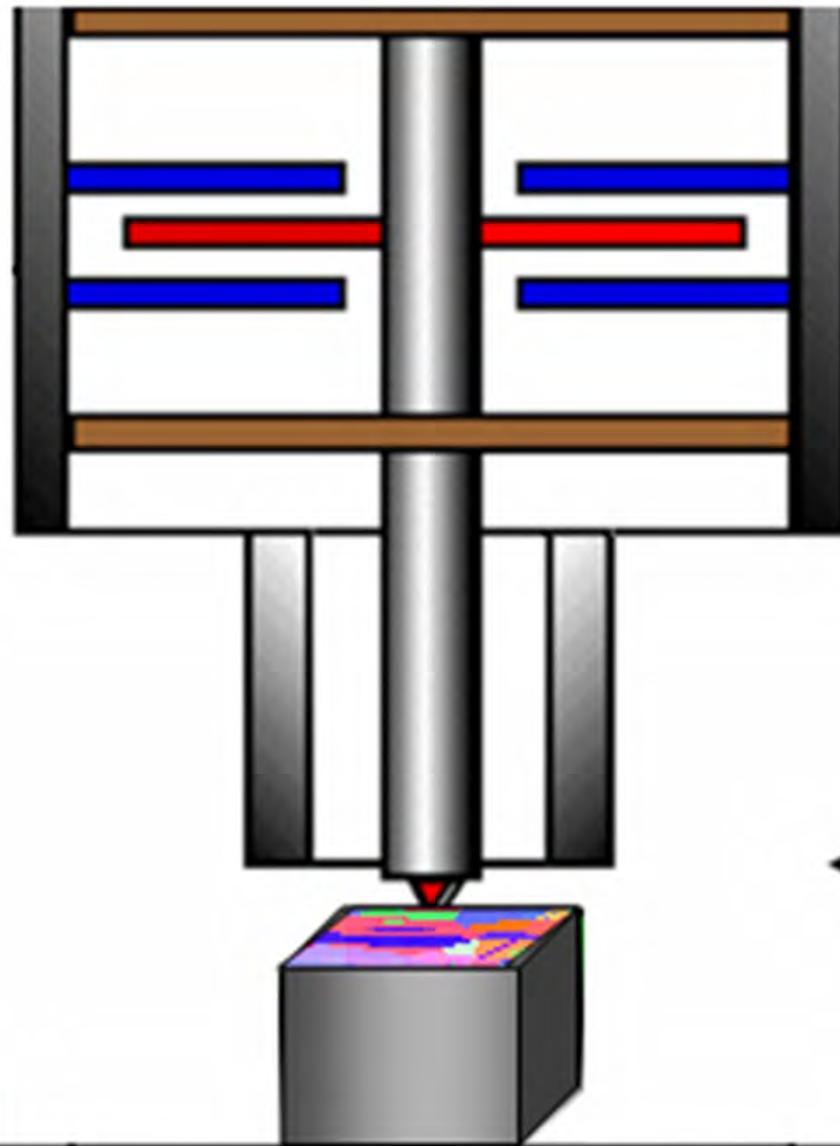
Nanopillar bicrystals, the effect of boundary strength



- ✓ Mesoscopic length scale
- ✓ Electron Backscattered Diffraction (EBSD) measurements



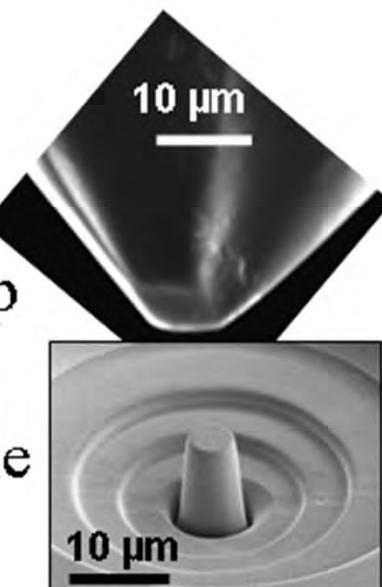
Micromechanical testing



Transducer

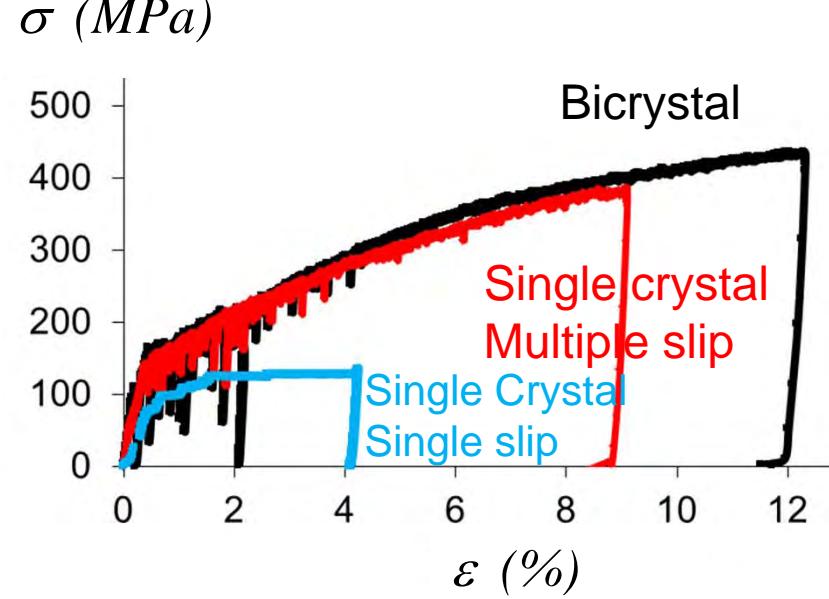
Indenter tip

Test sample
37

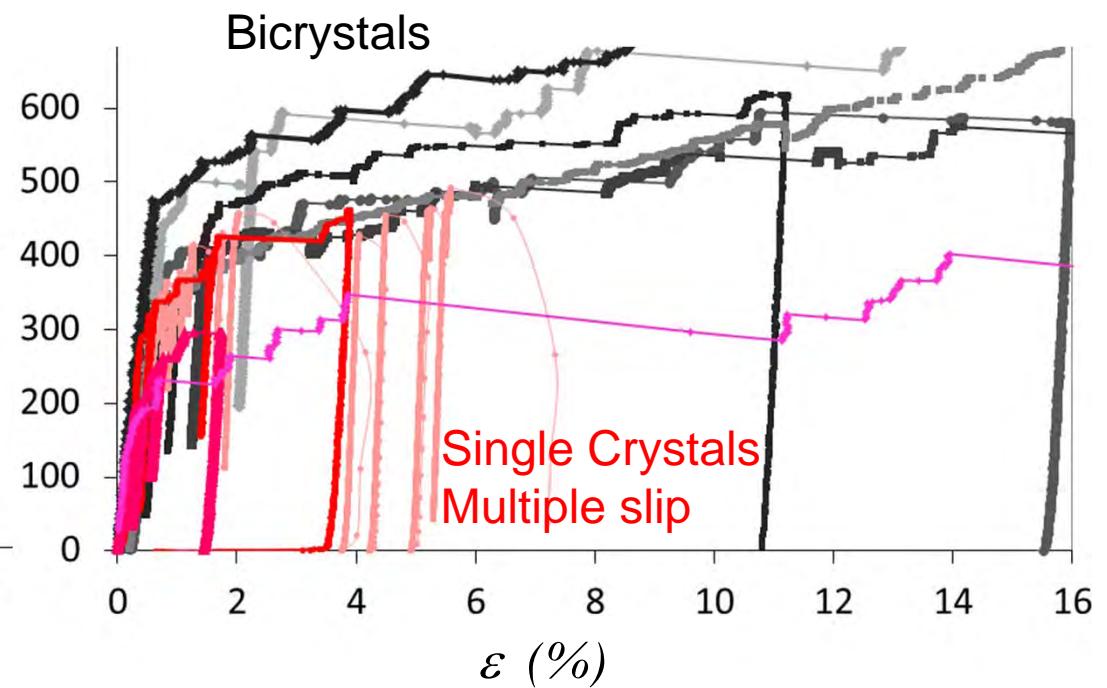




Compression test results



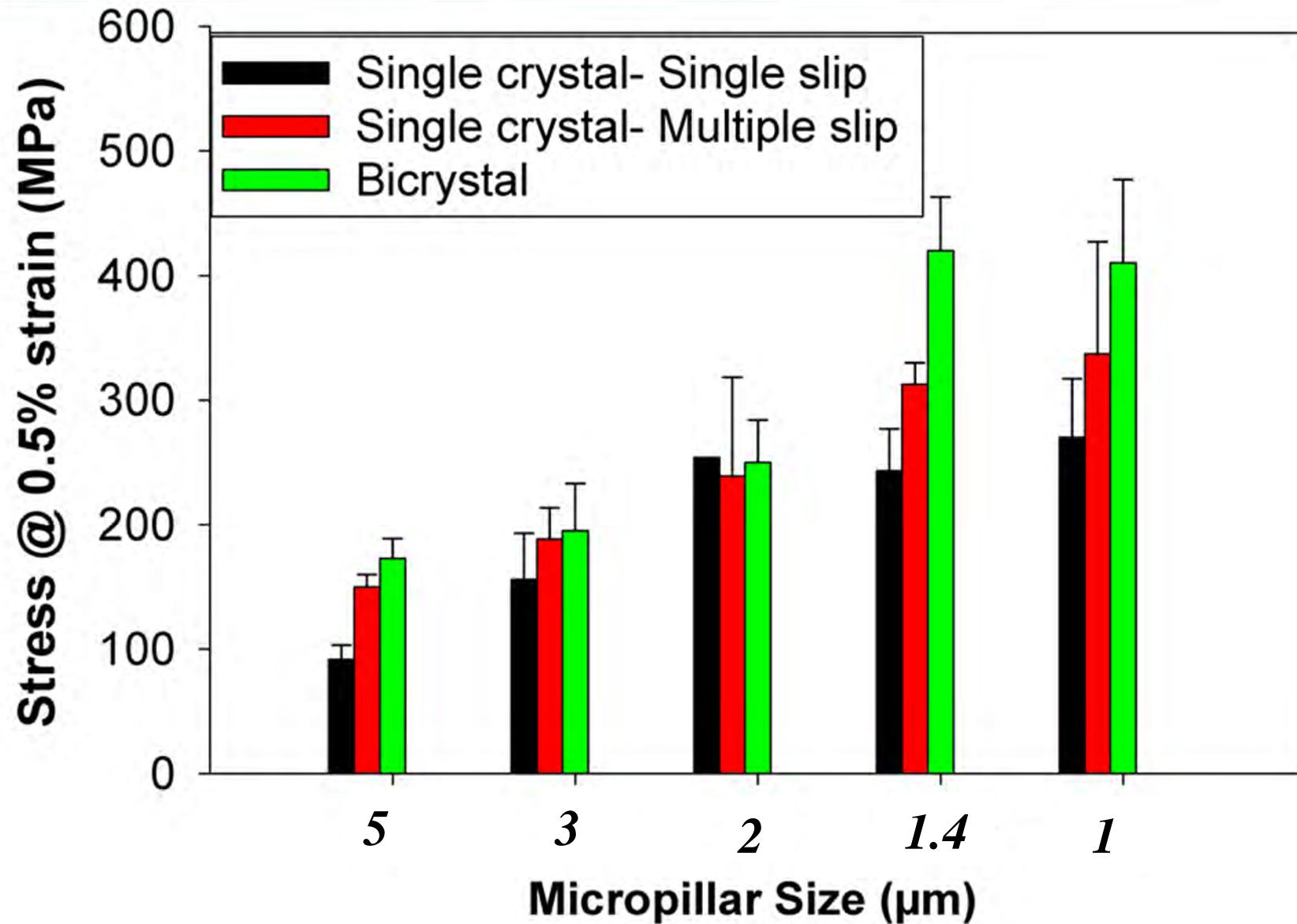
$$\phi = 5 \mu\text{m}$$



$$\phi = 1 \mu\text{m}$$



The effect of grain size on strength



The gb effects the strength

$\phi < 2 \mu\text{m}$

39

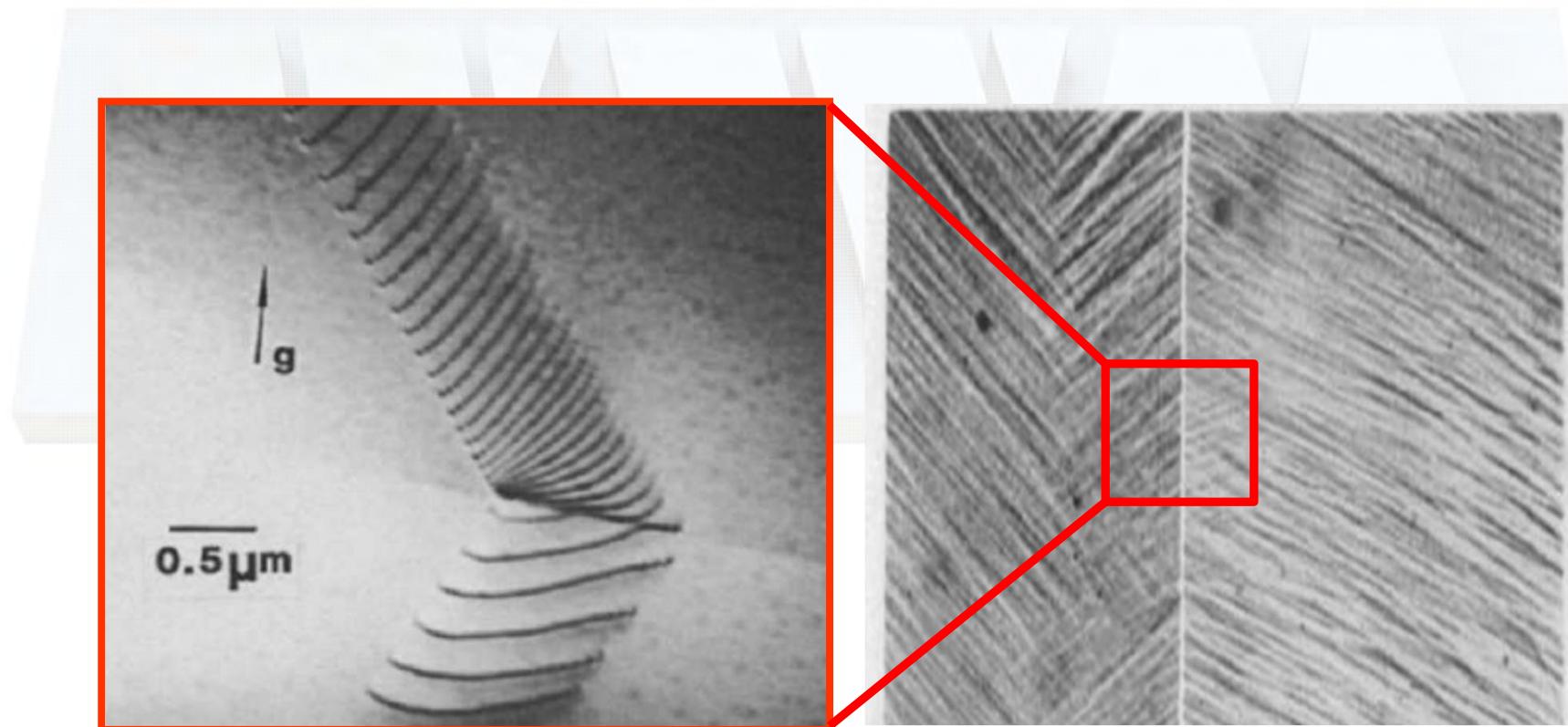


Interaction dislocations - boundary



❖ Local

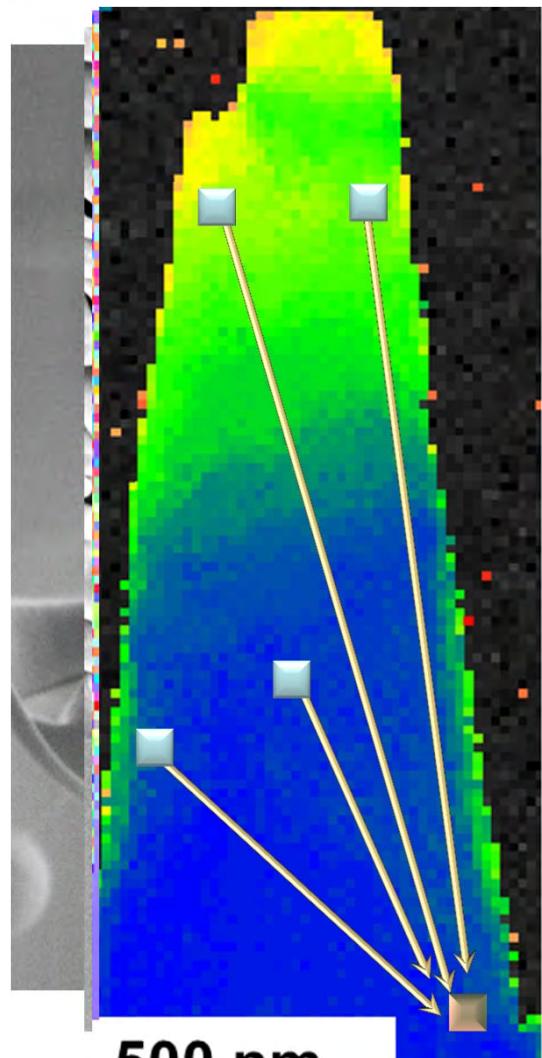
- Macroscopic bicrystals (Chalmers et al. from 1937)
- Microscopic bicrystals (TEM)



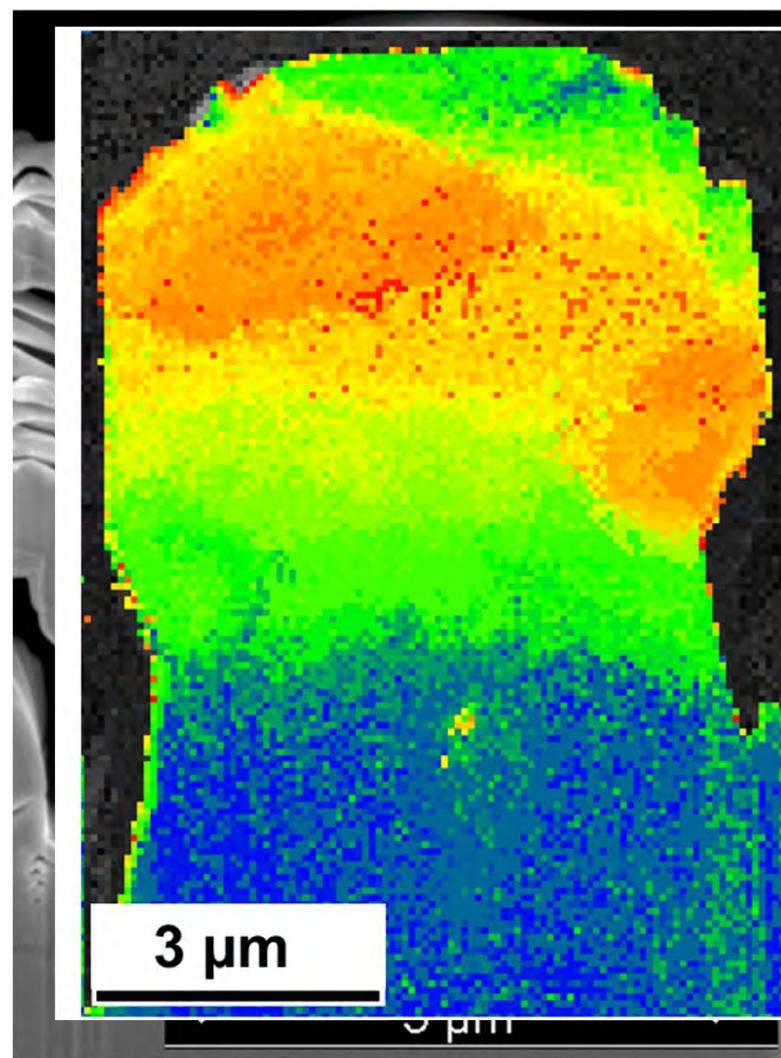
Z.Shen et al., Acta Metallurgica 36,1988



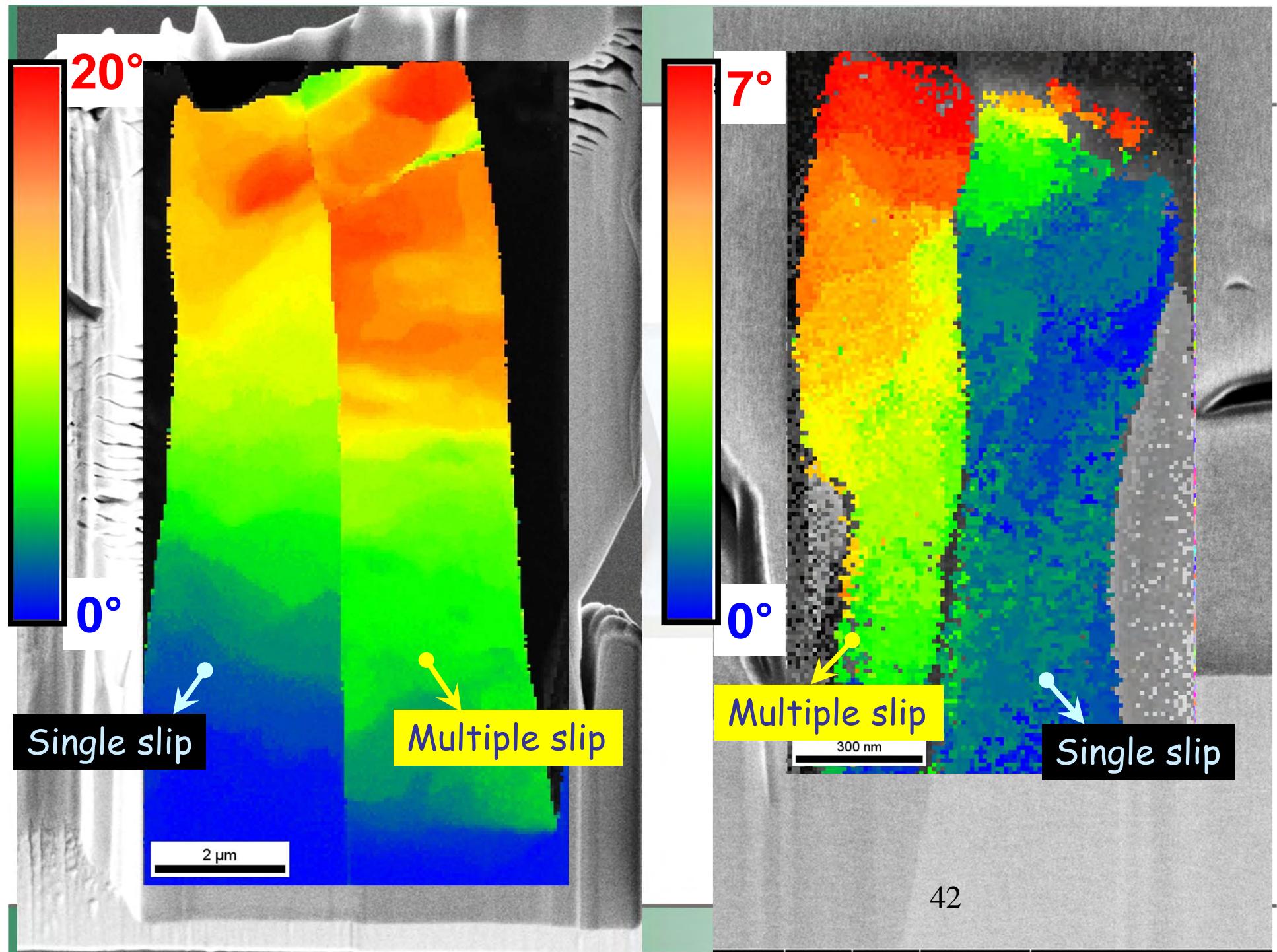
Misorientation Mapping



Single slip orientation
(-12 25 -9)

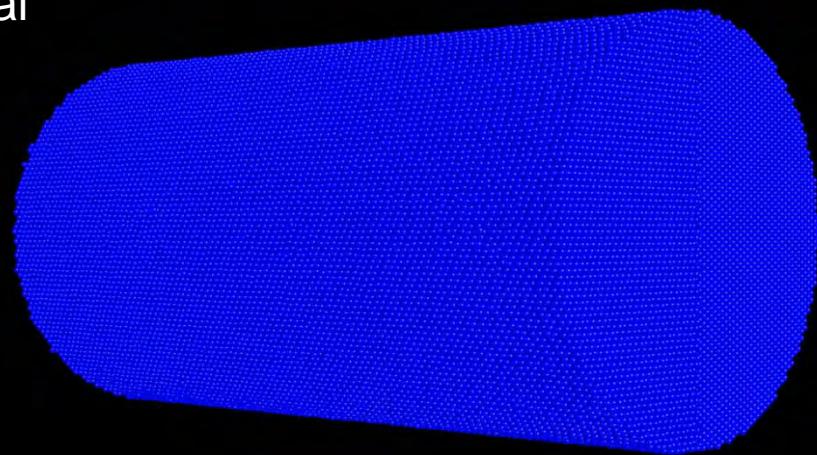


Double slip orientation
(11 1 18)



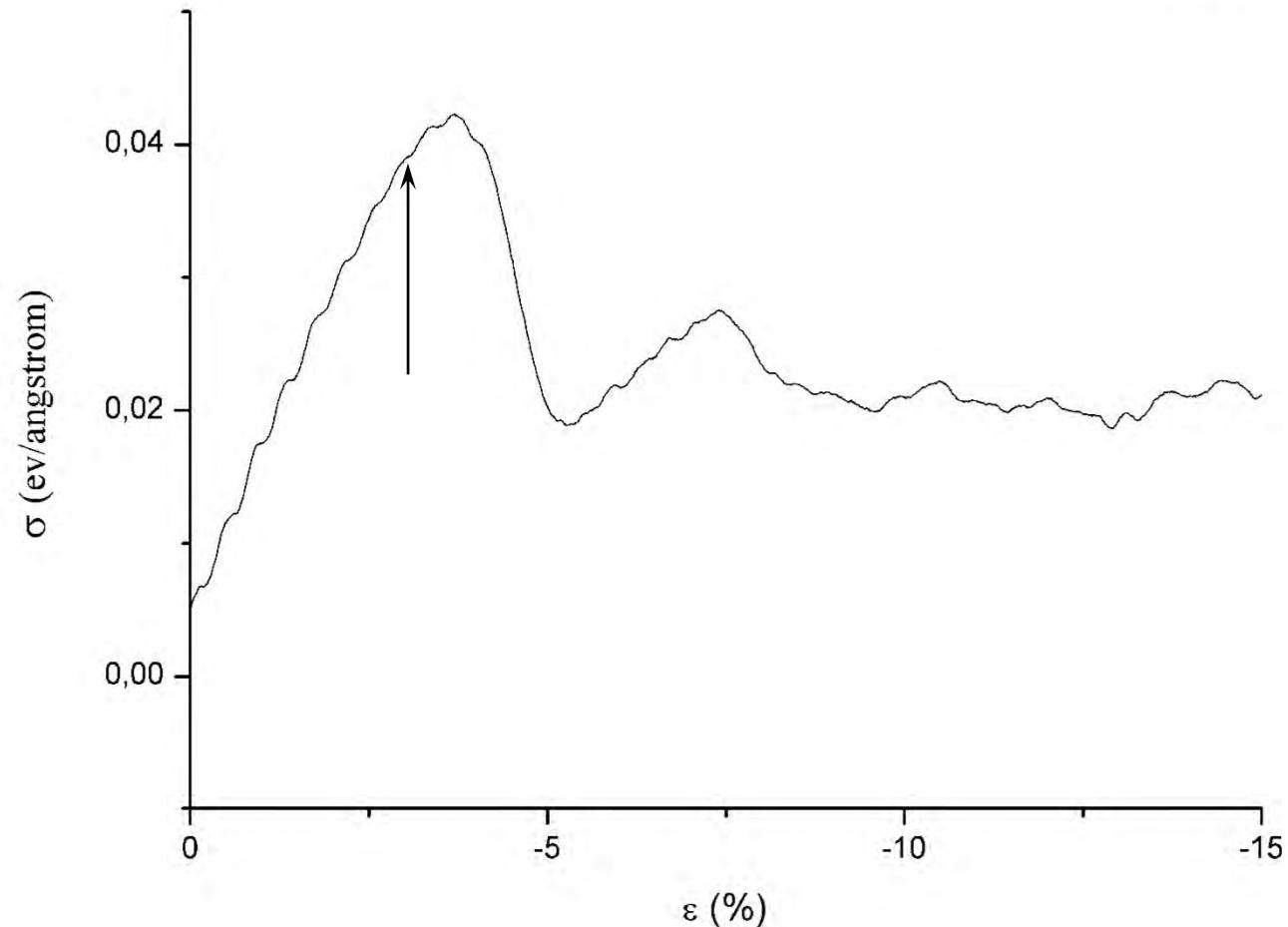


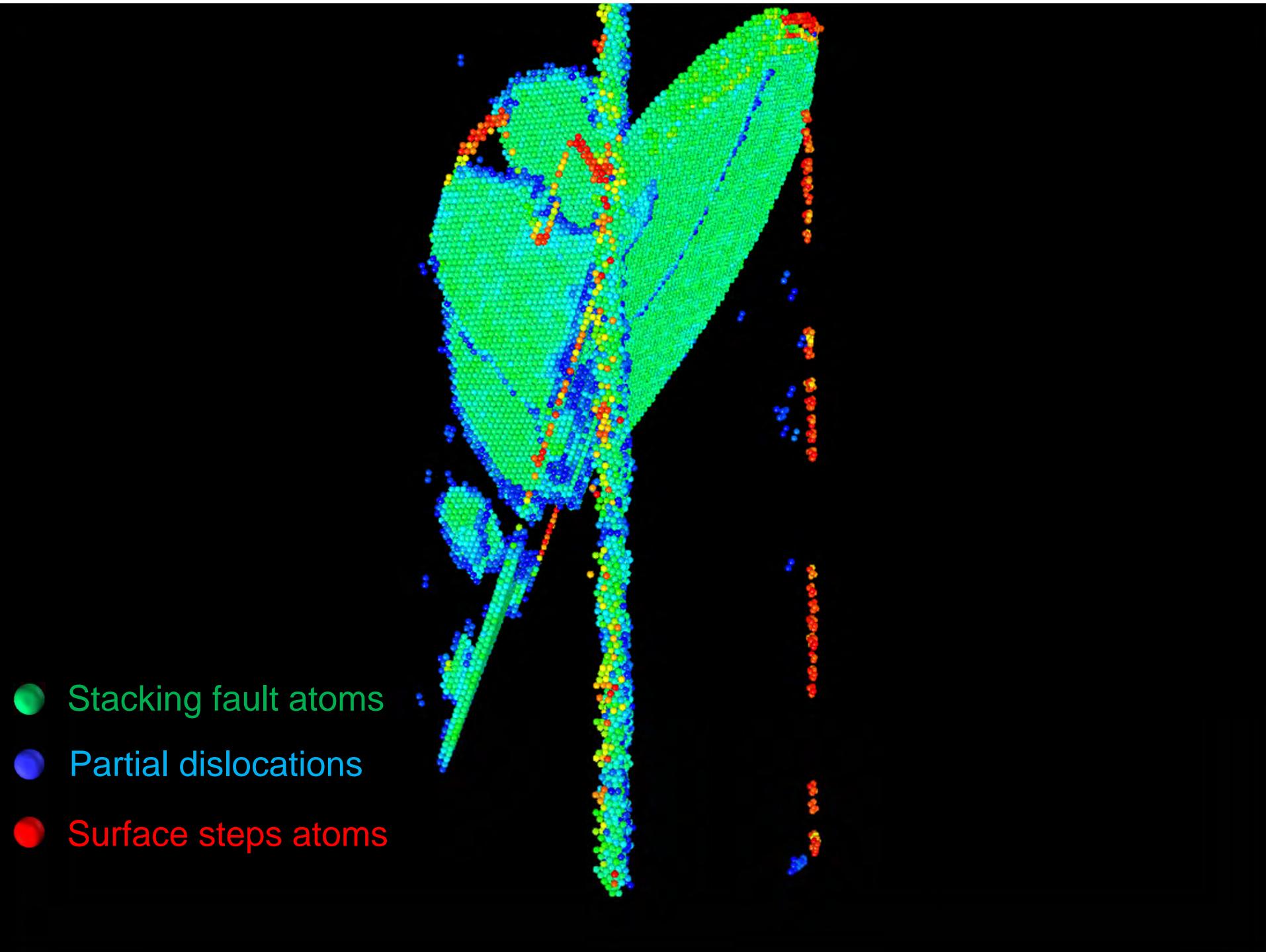
Half Million atom MD
simulation with EAM
empirical potential





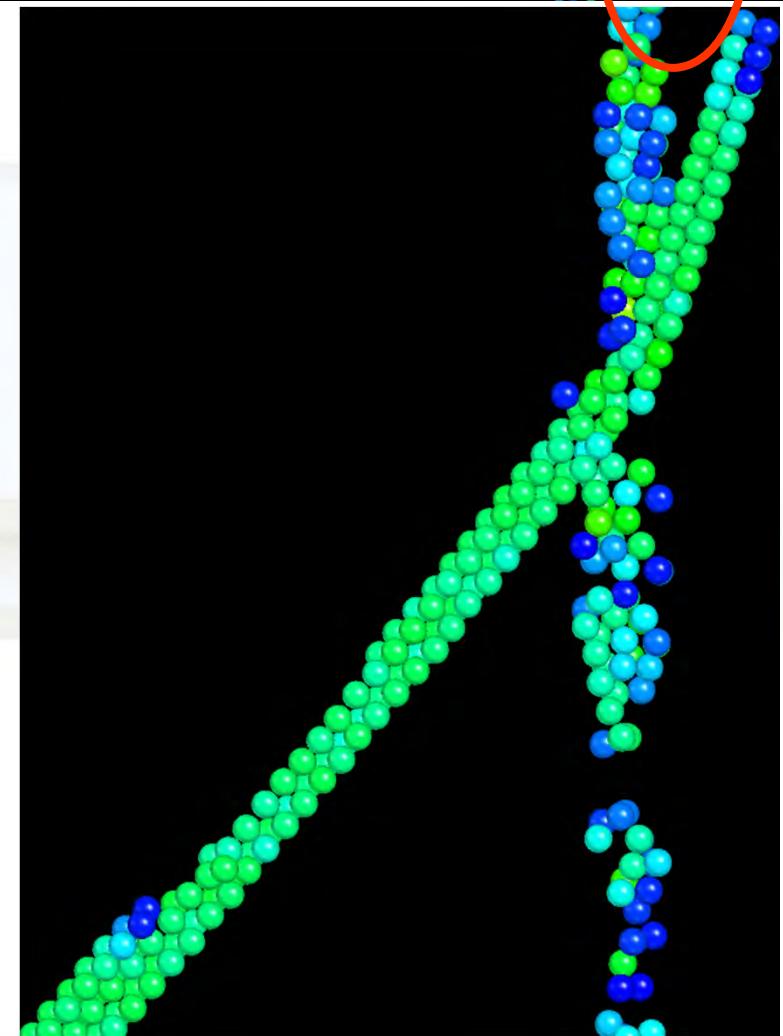
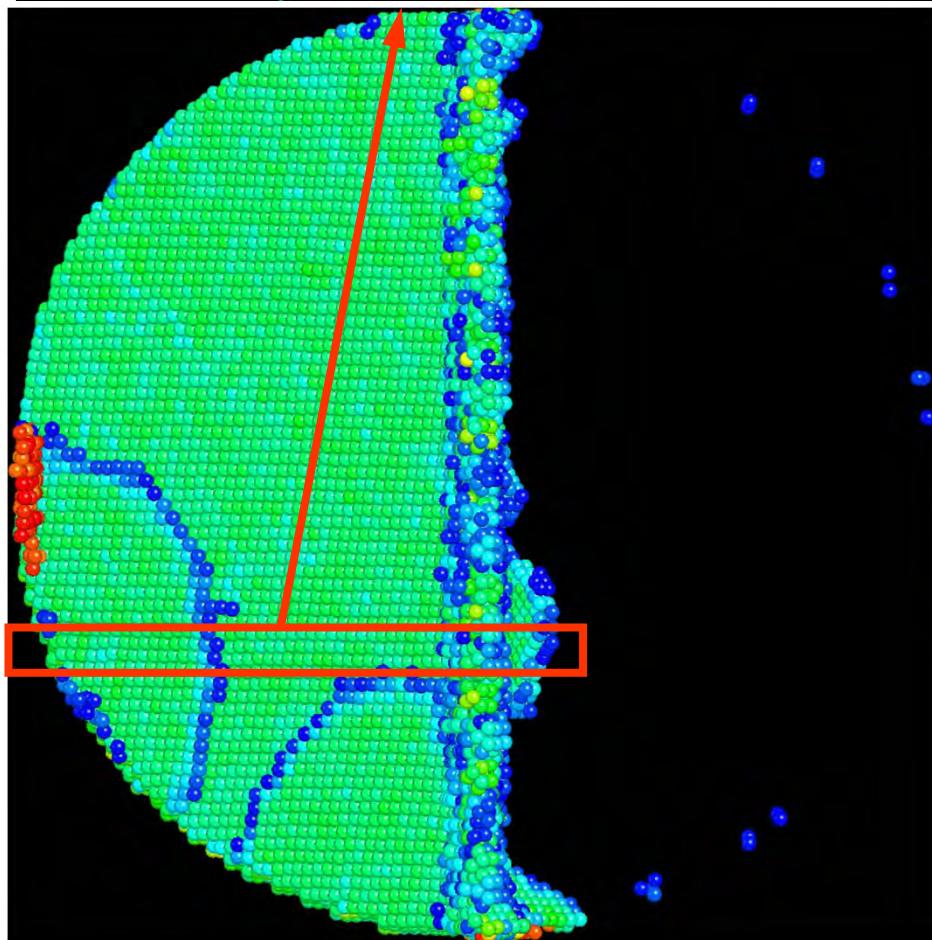
— stresszz





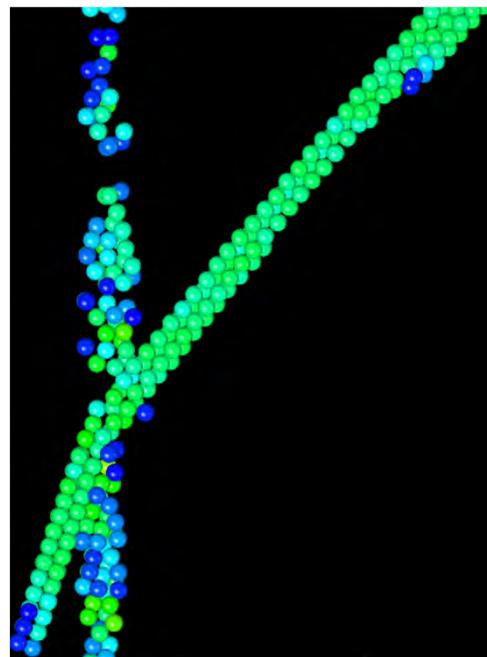


90°

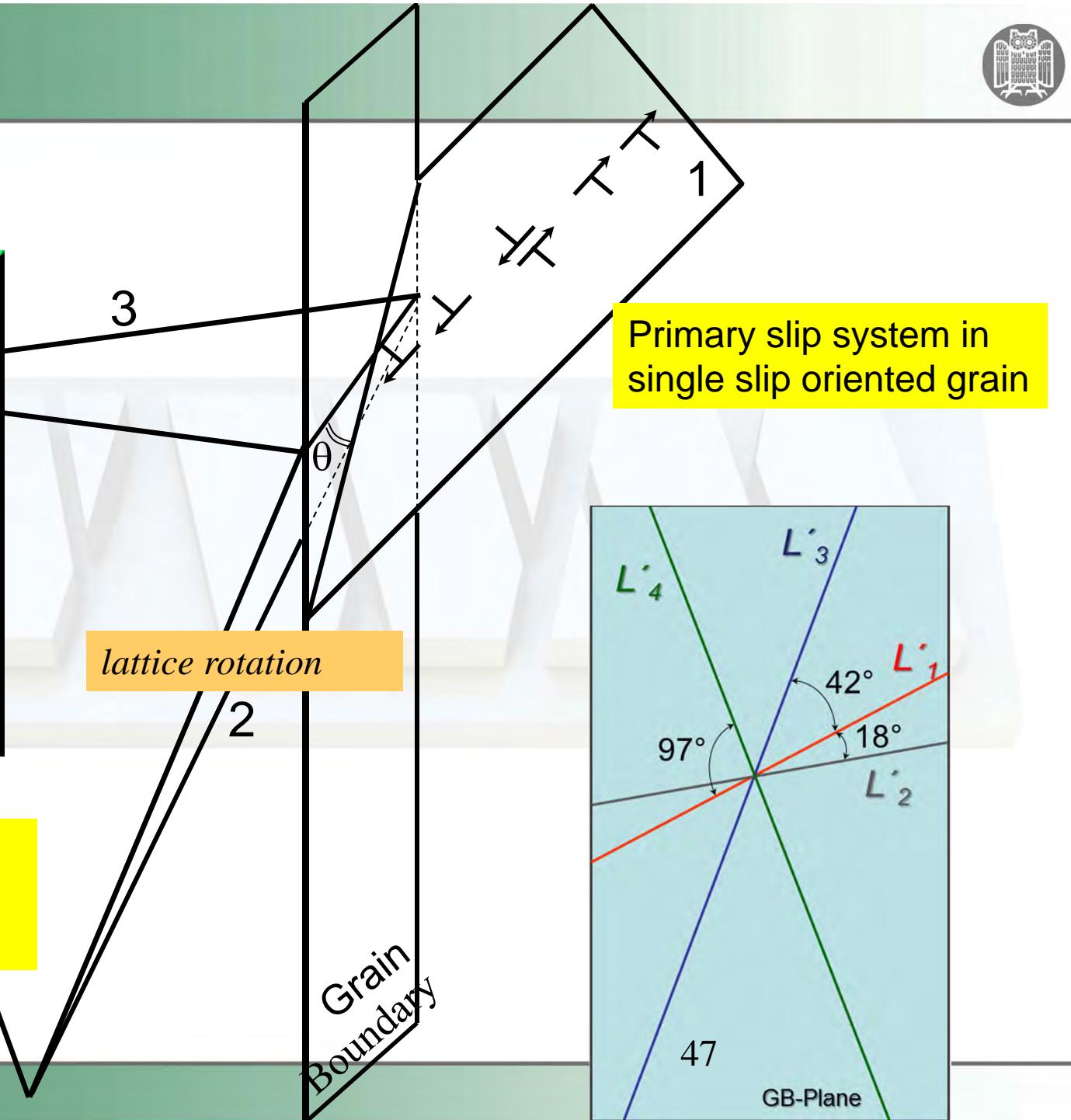




Slip Transmission



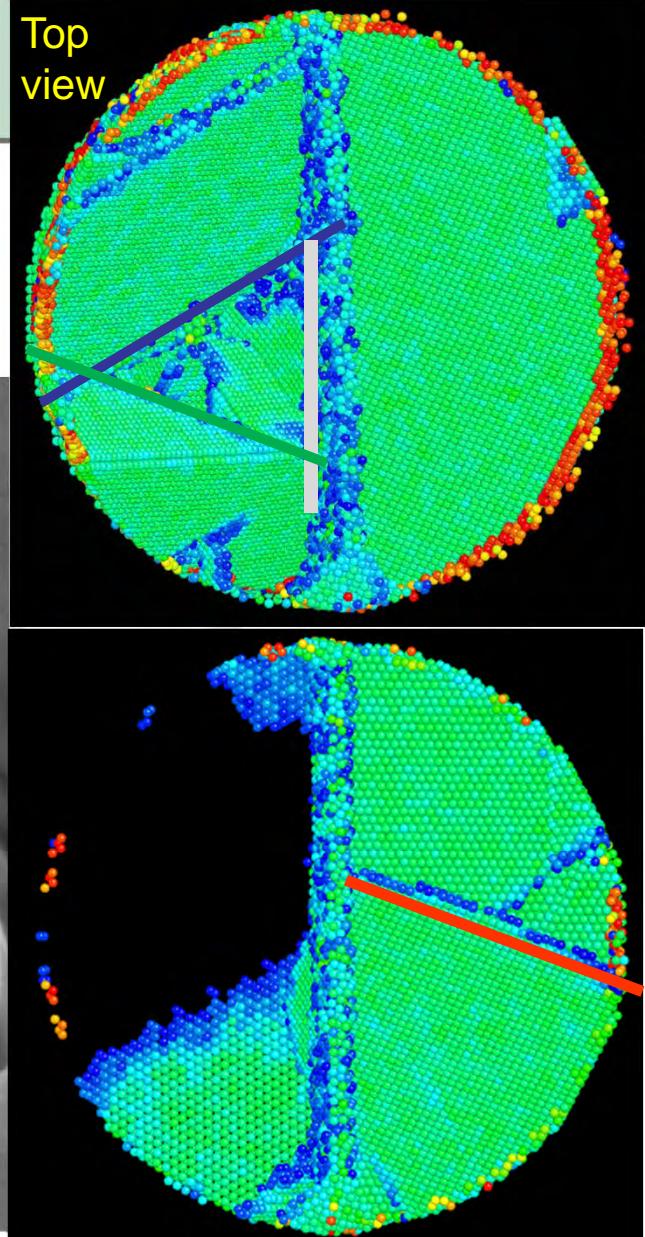
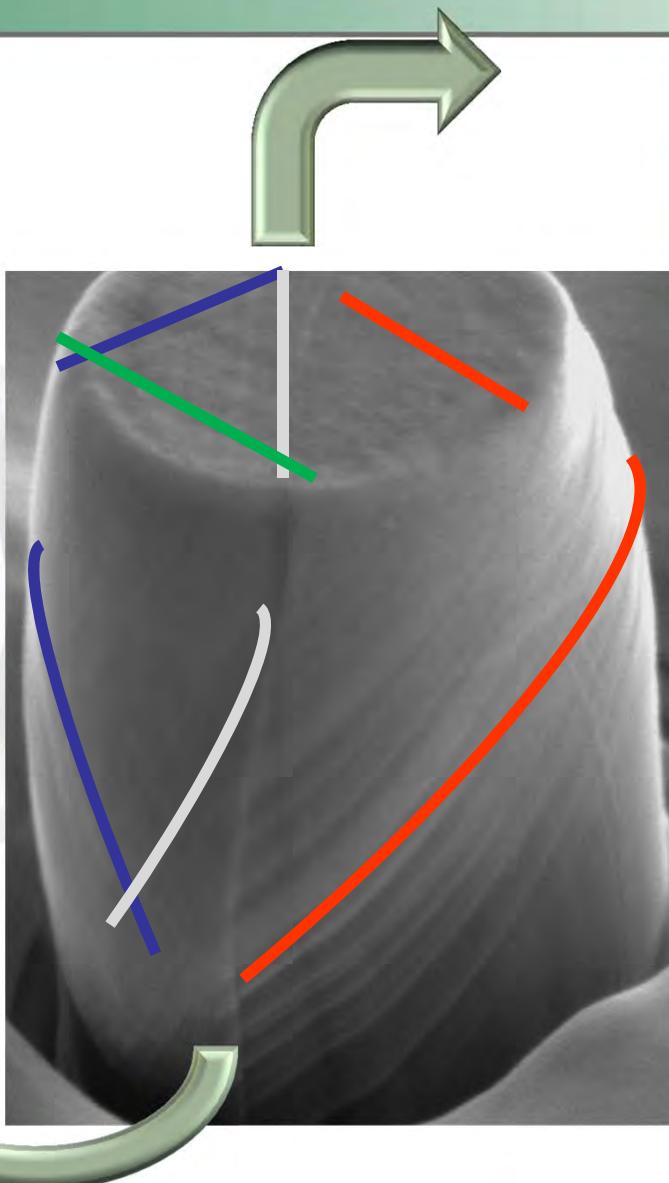
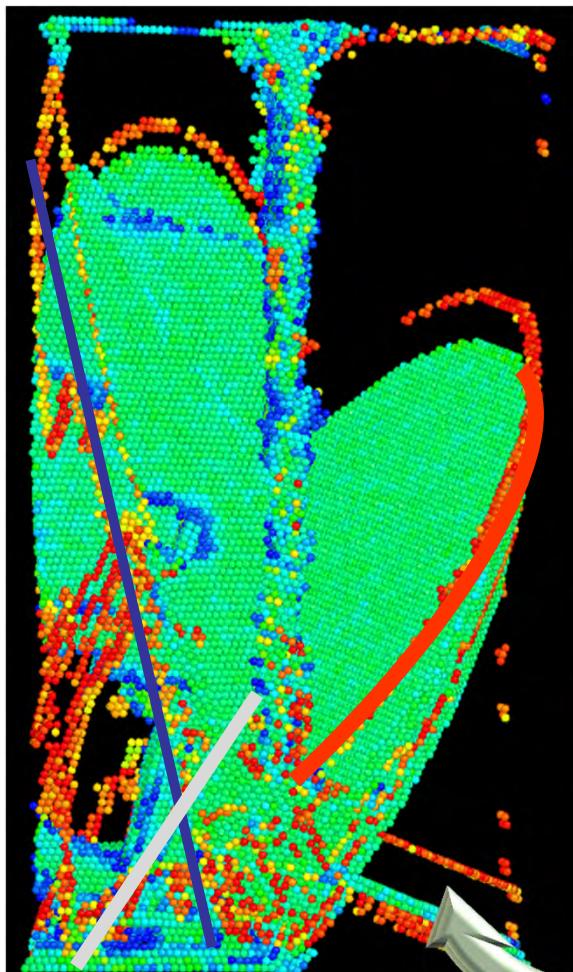
Primary slip systems in
multiple slip oriented
grain





Comparision with MD

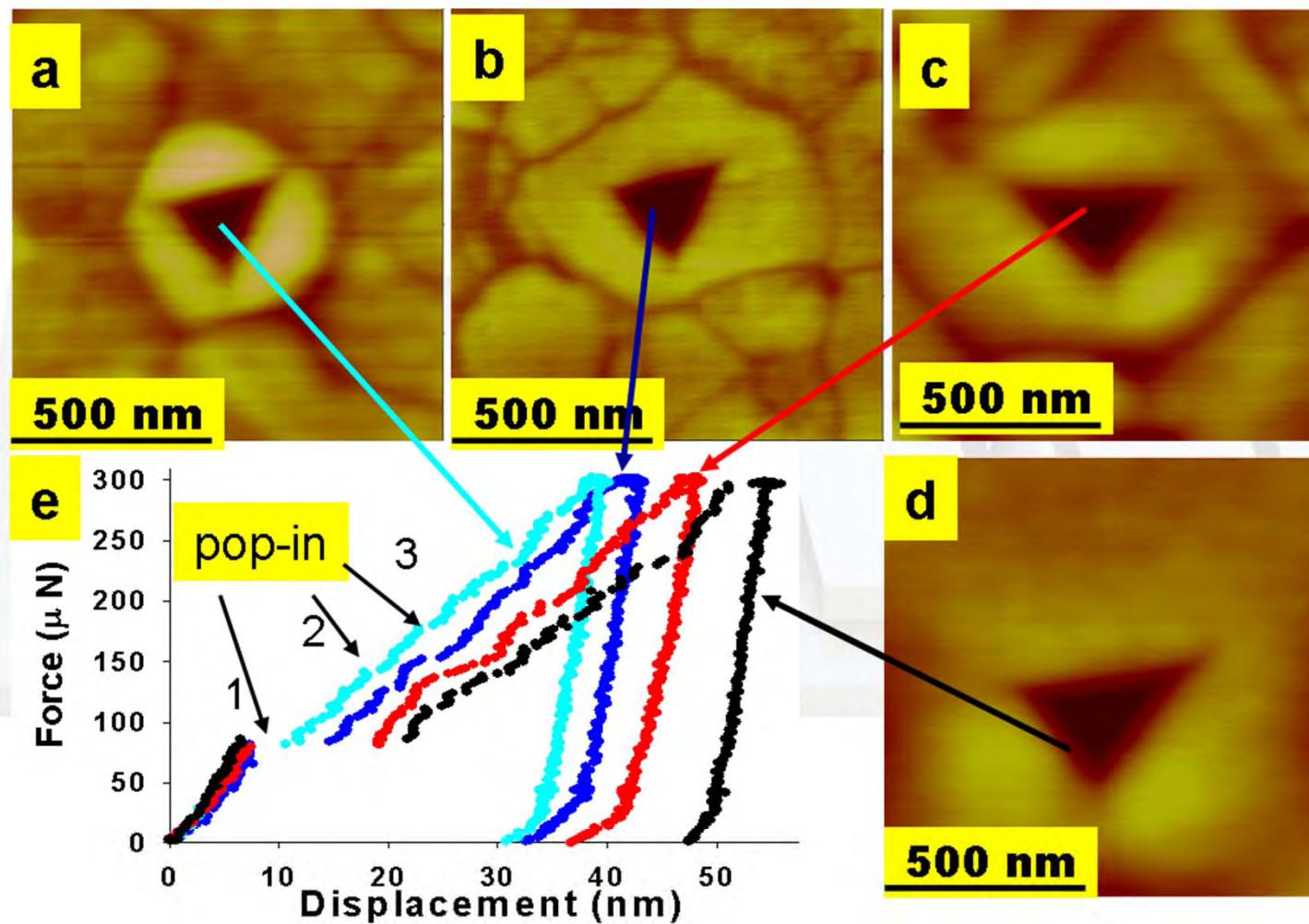
Side view



A. Barnoush and coworkers, in preparation



Nanoindentation in einzelnen Körnern

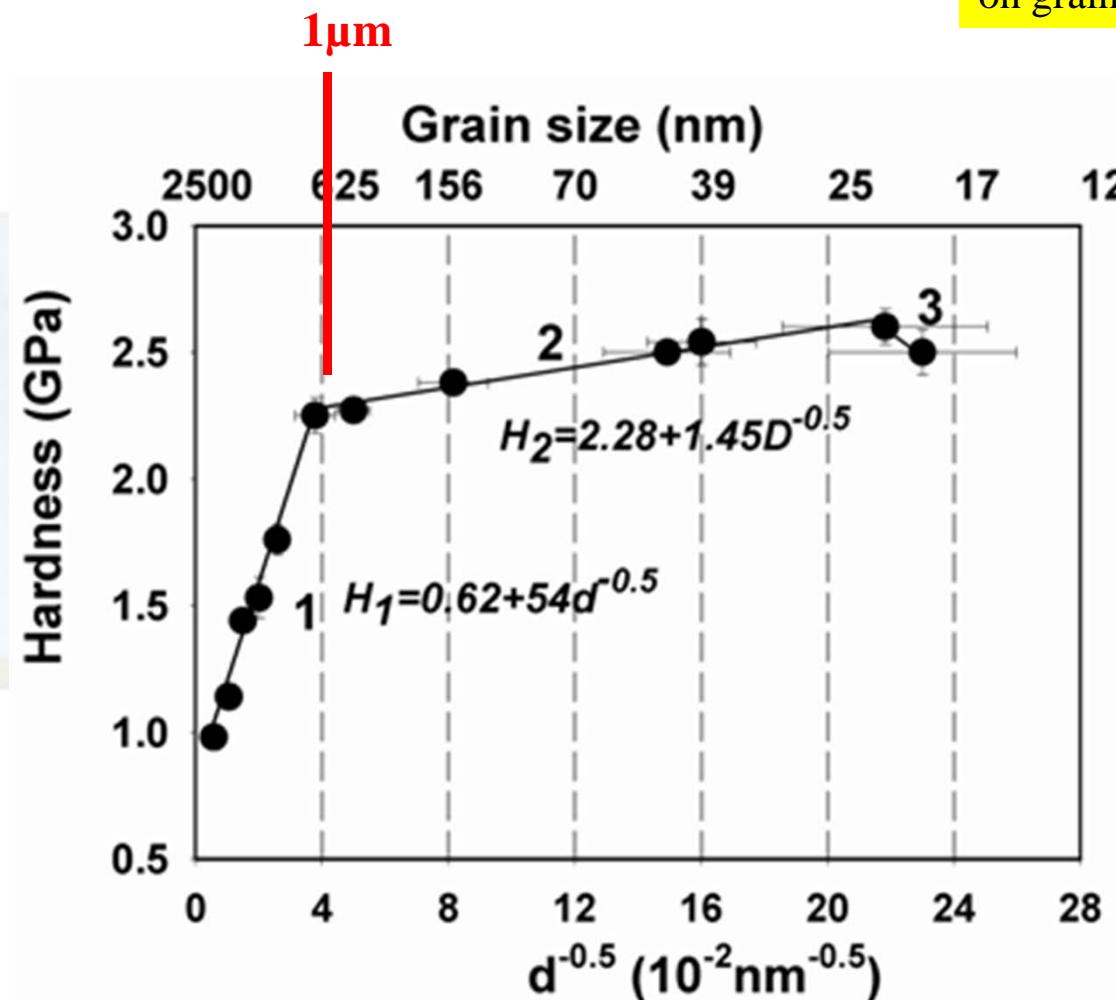




Deformation and size



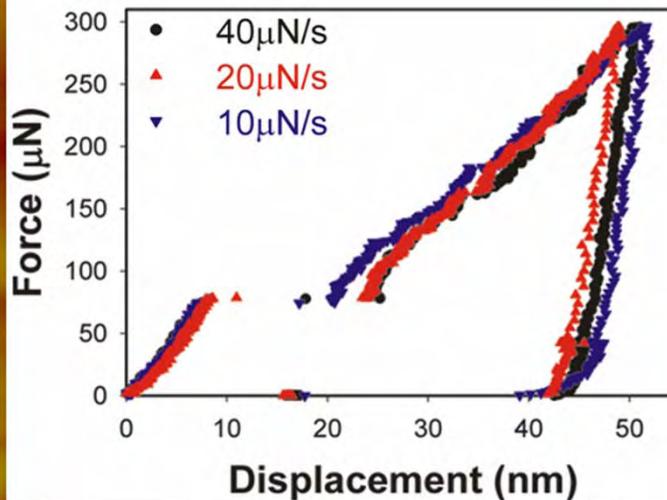
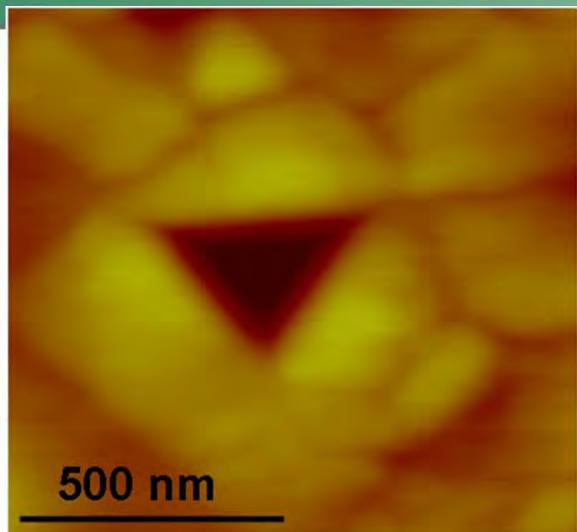
Constitutive equations depend
on grain size



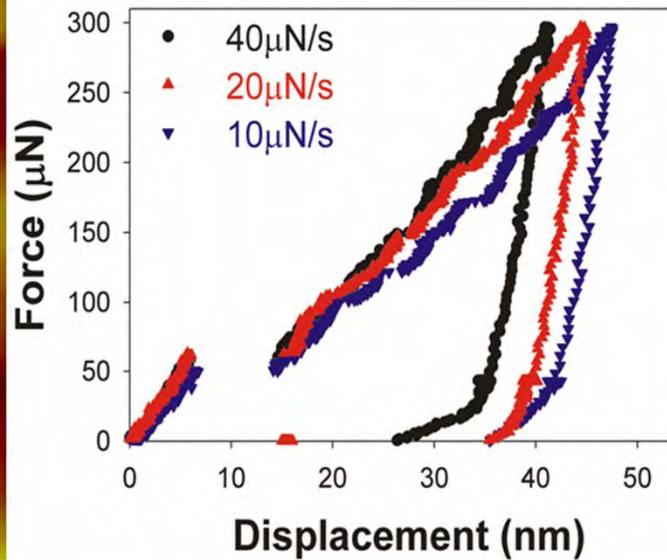
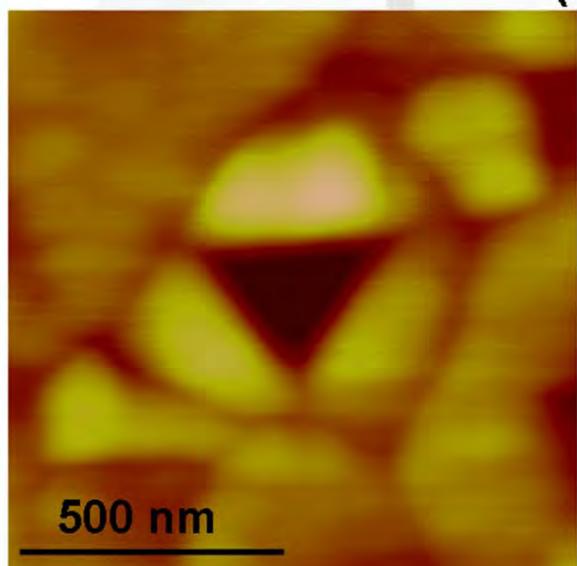
Ni, PED
+ heat treatment
to produce the different
grain sizes



Strain rate sensitivity



(a)



(b)

Konstante
Pop-in-Weite

Pop-in-Weite begrenzt
durch Korngrenzen

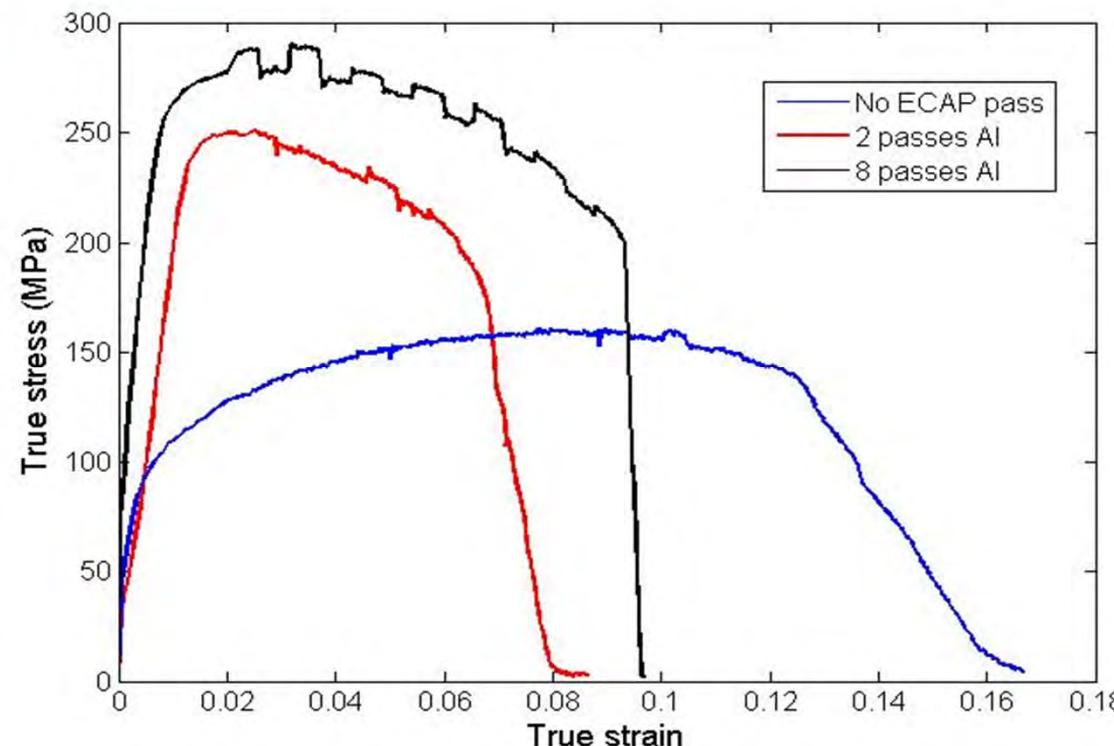
-> dehnrateempfindlich



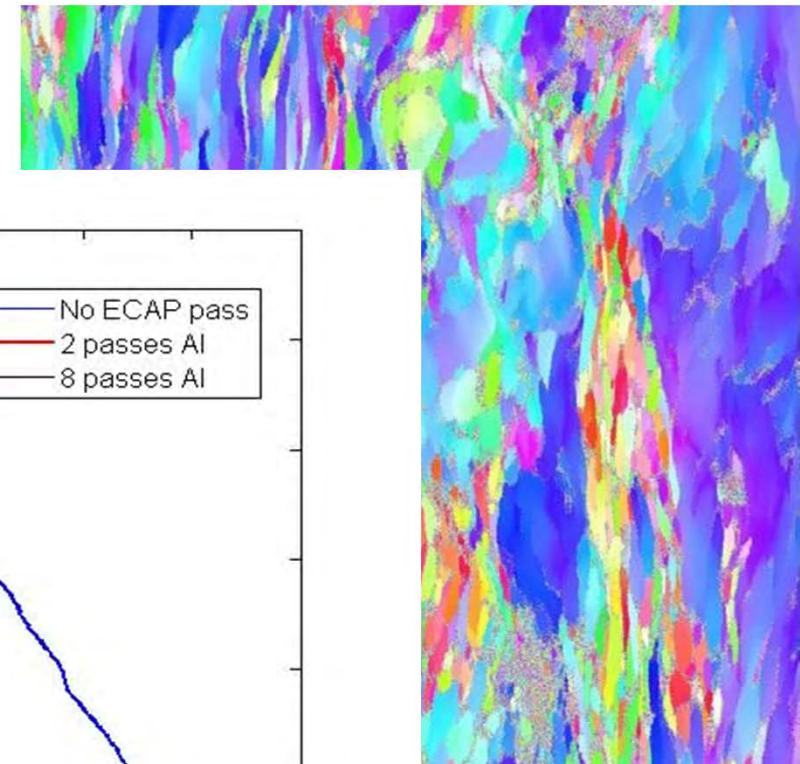
Constitutive equation and strain rate sensitivity



Global results: Al (AlMg0.5Si0.4) route C



- 2 mean orient
- Grain sizes: :
- High amount

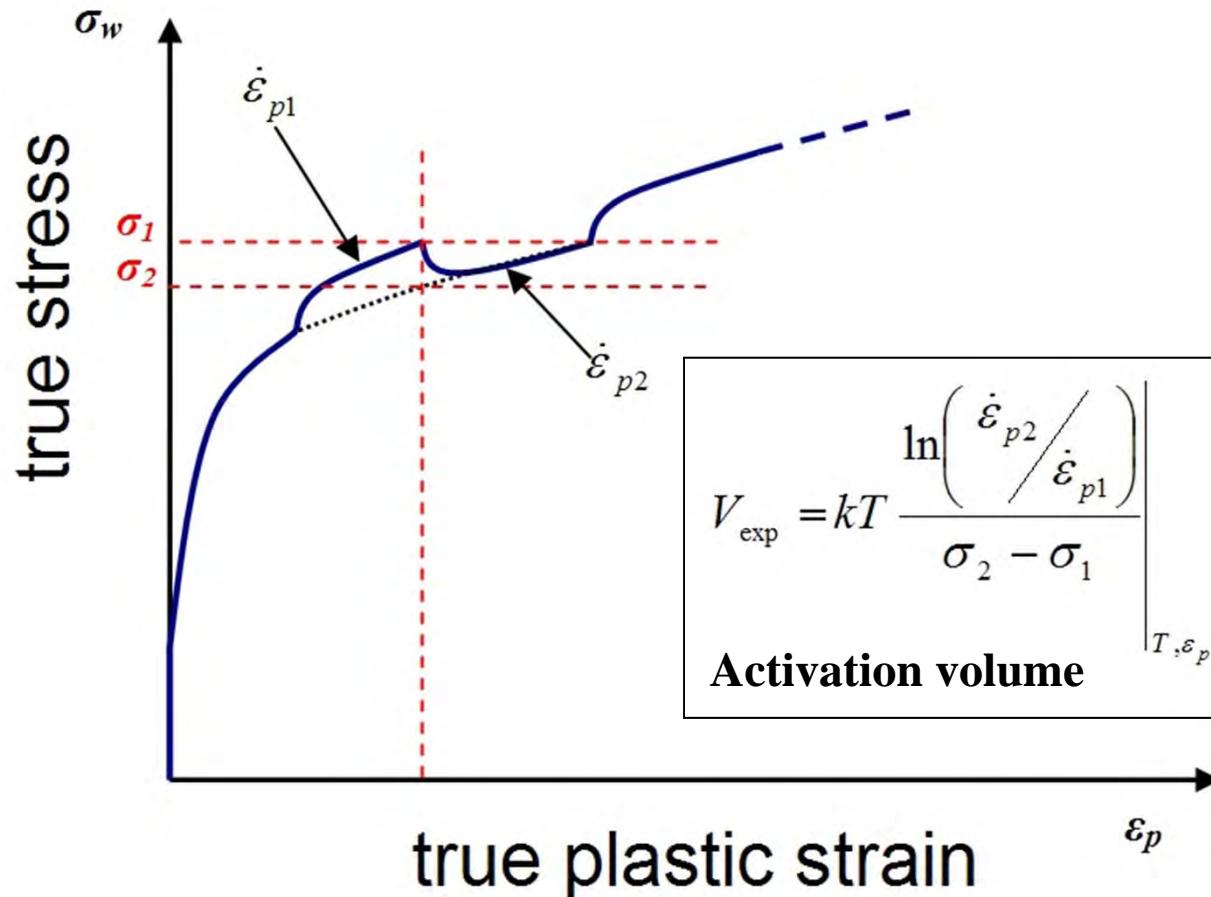


distribution
round 350 nm
HAGB (+20 %)

Strain rate sensitivity depends on grain size

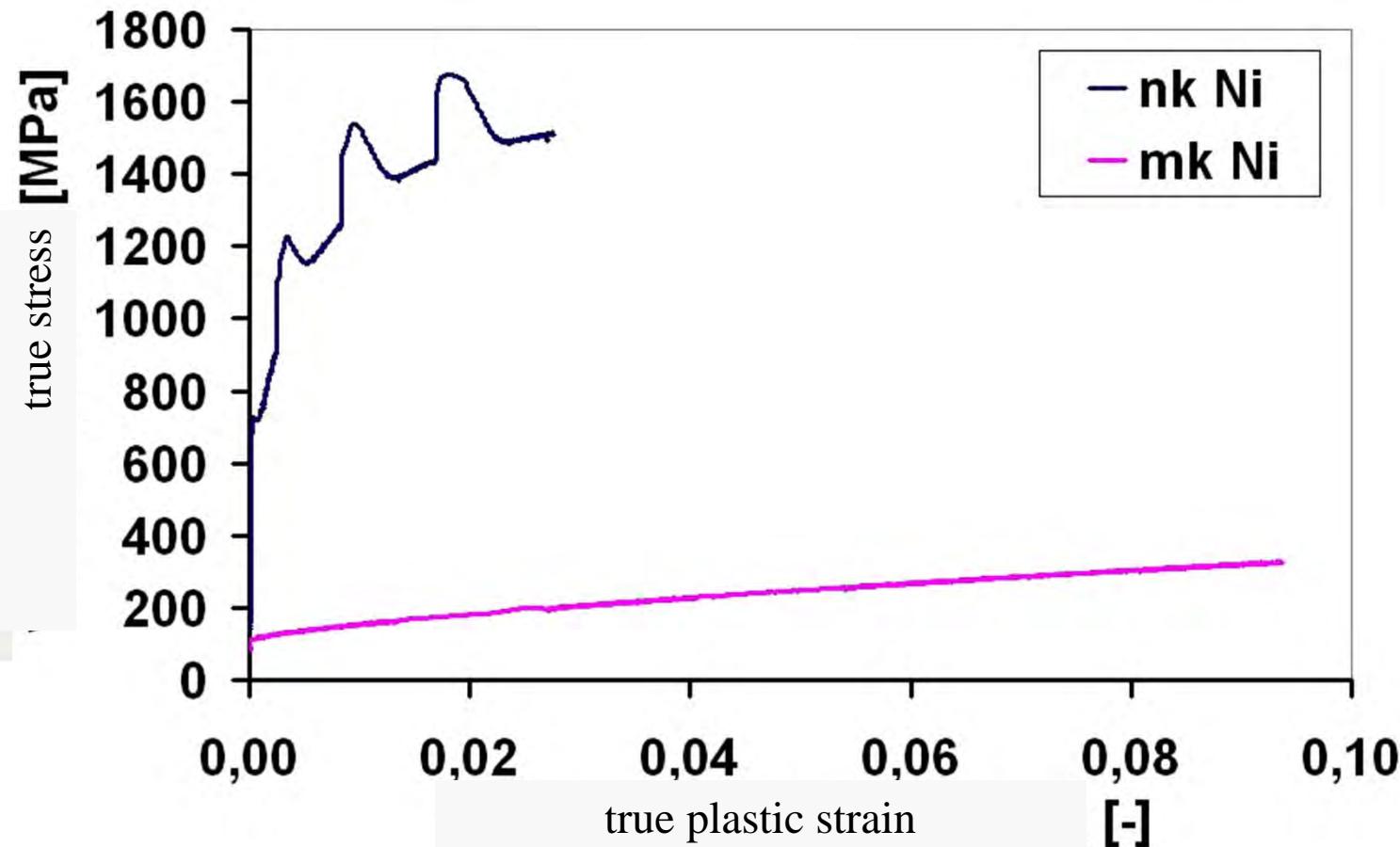


Global Method: strain rate jump test



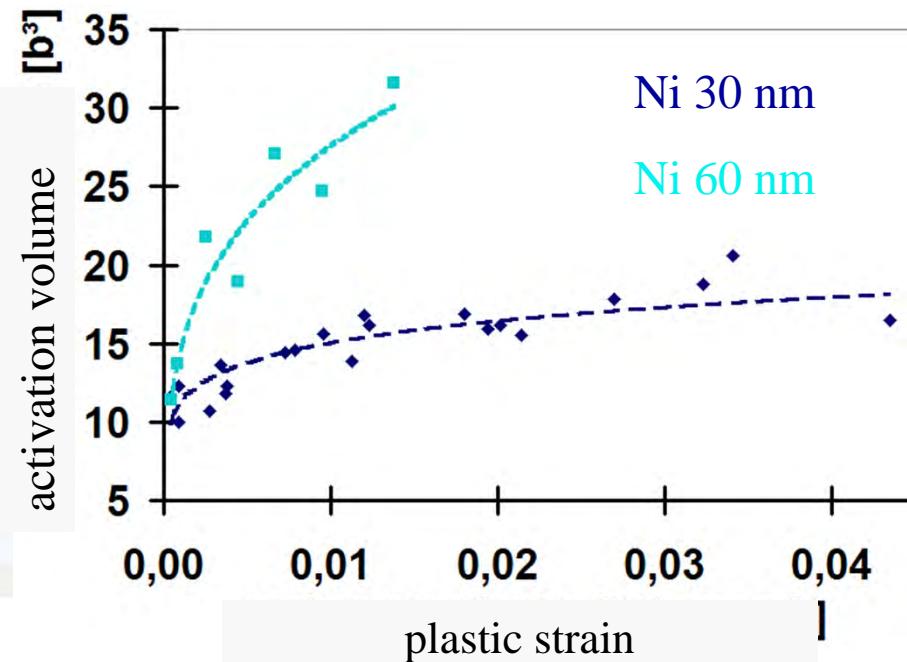
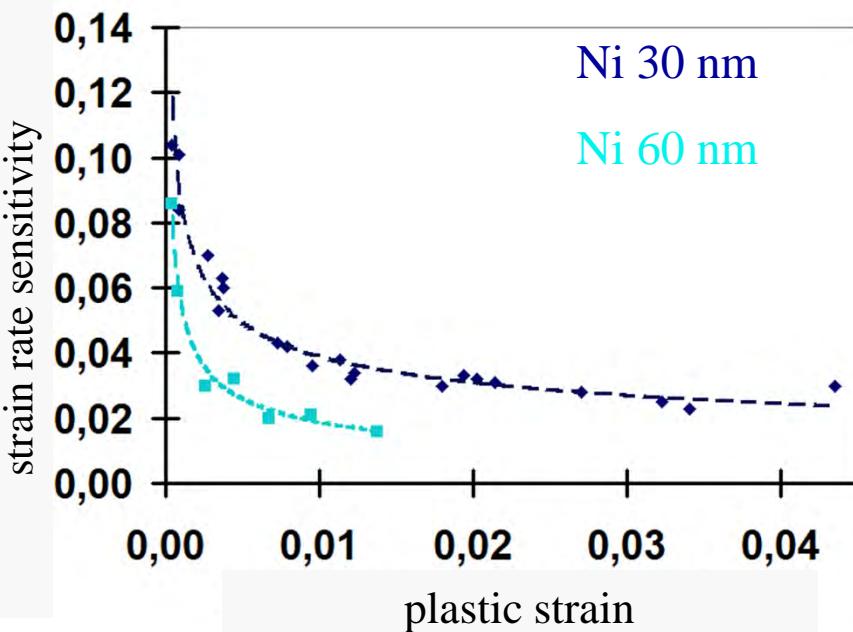


Strain rate sensitivity of Nk and mk Ni





Influence of grain size



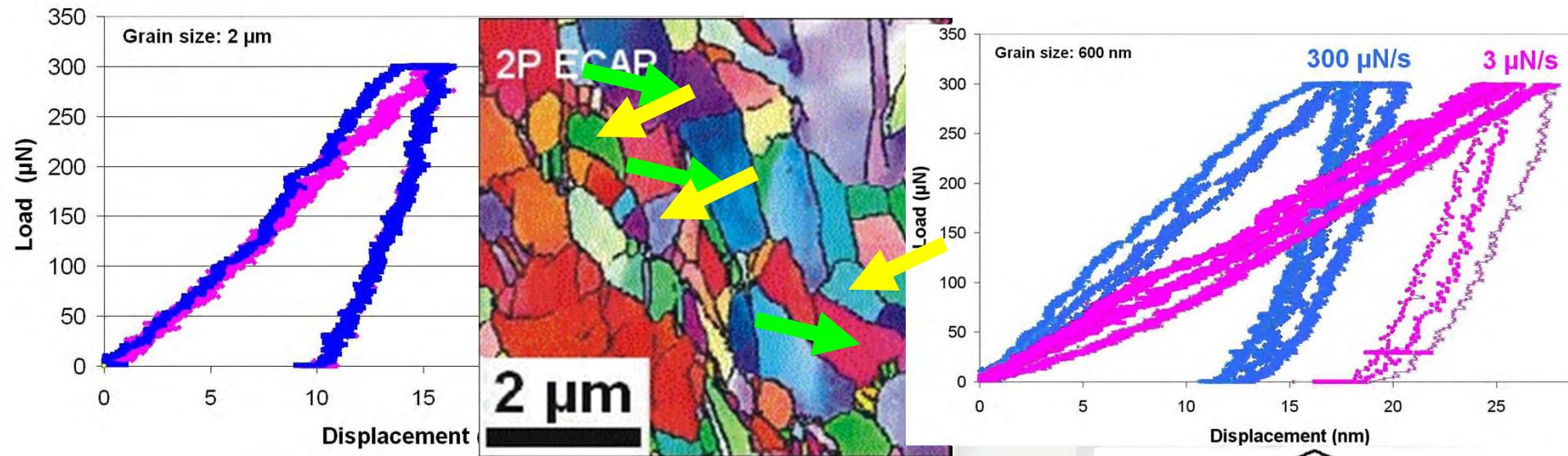
Activation volume decreases with grain size



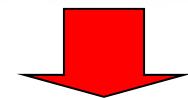
Indentation of single grains



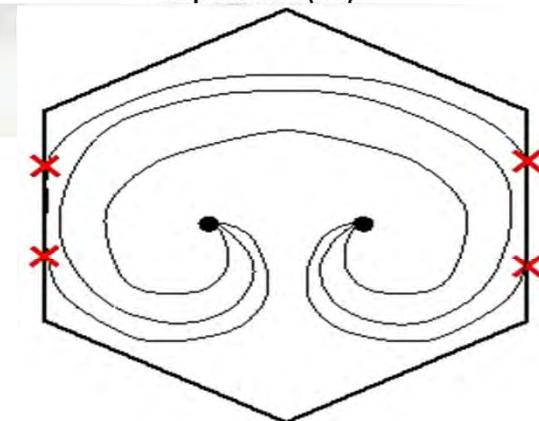
ECAP-Ni: complex microstructure



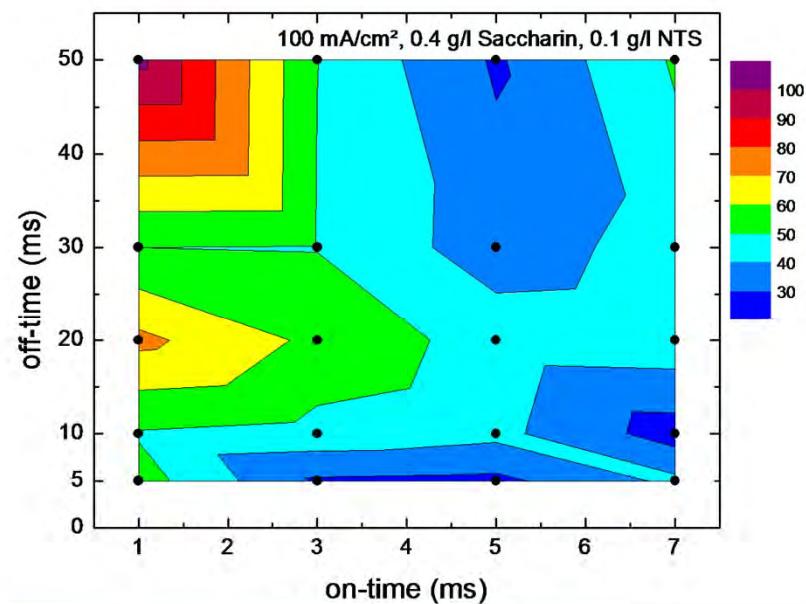
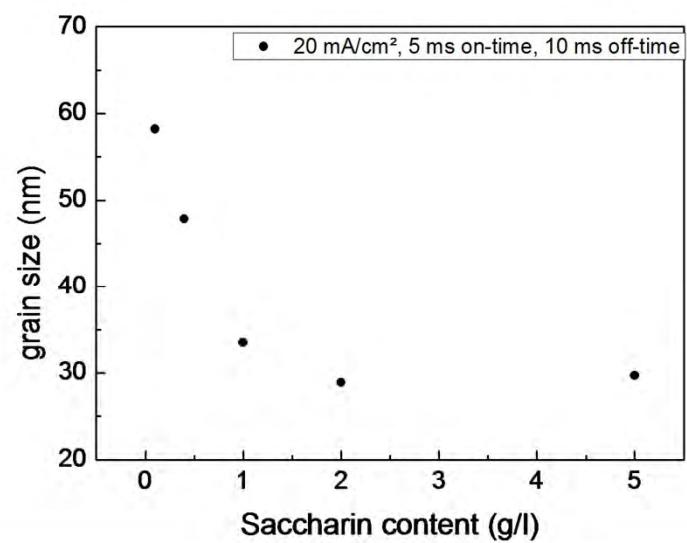
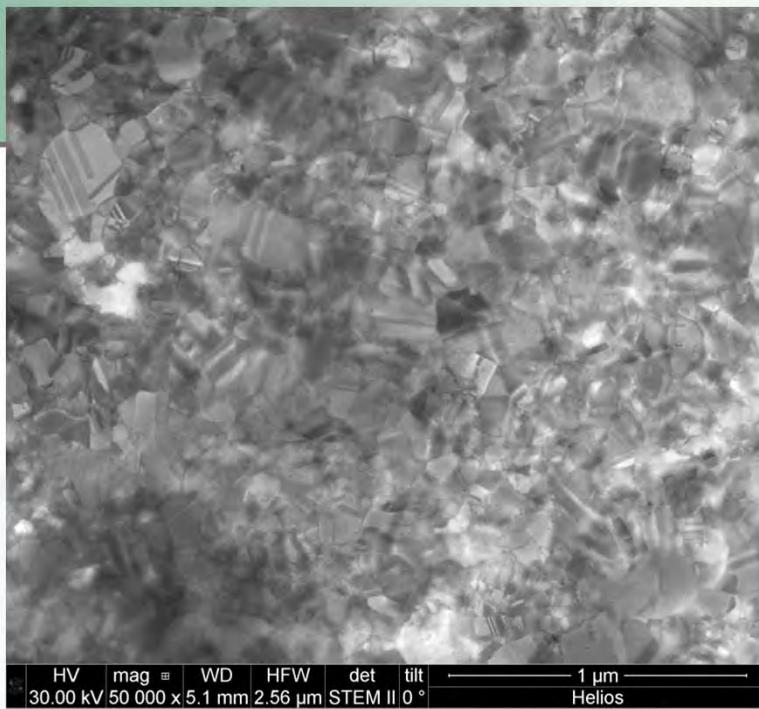
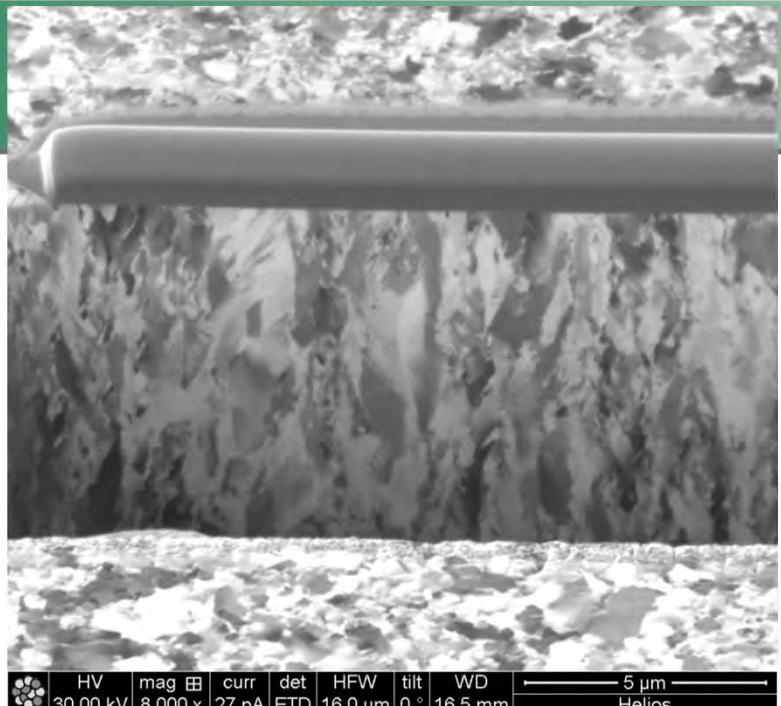
Direct dislocation grain boundary-interaction

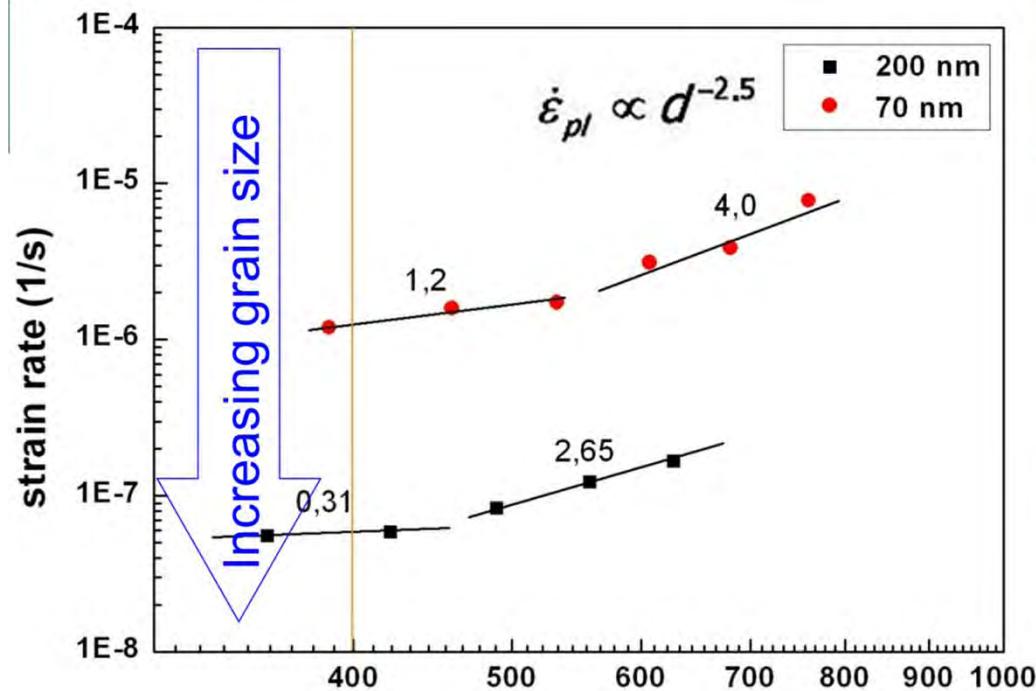


Strain rate sensitivity

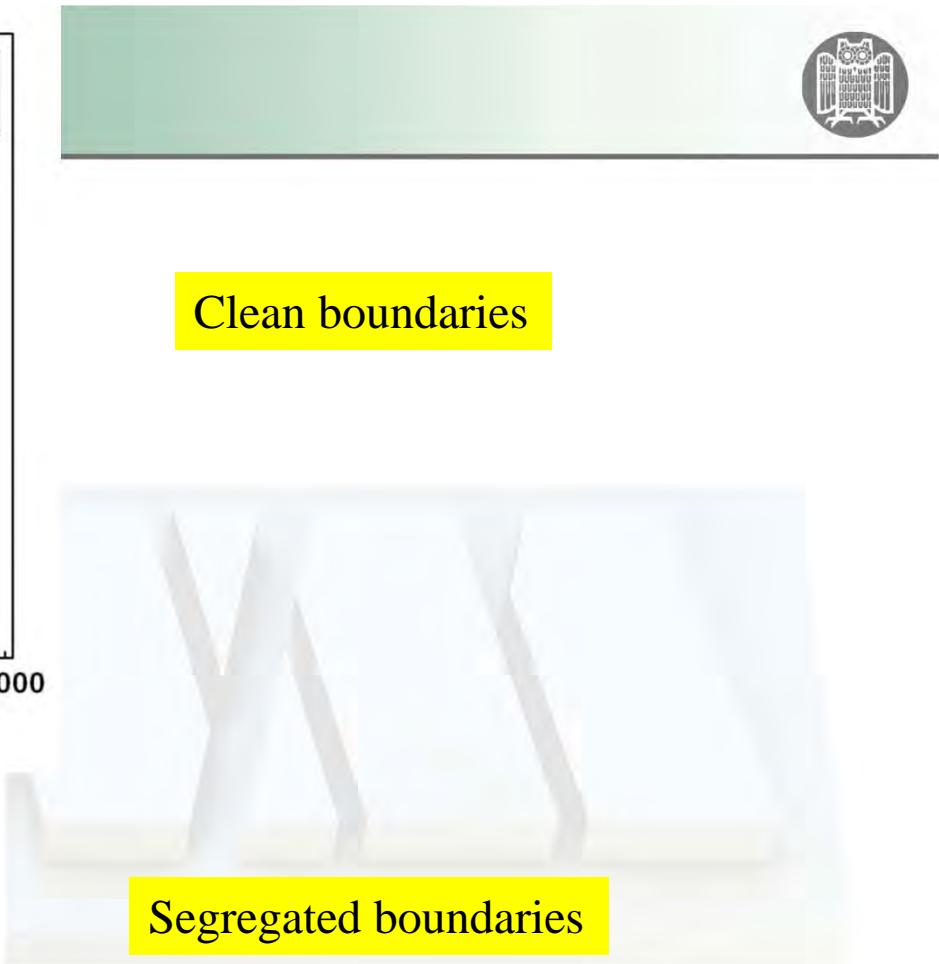
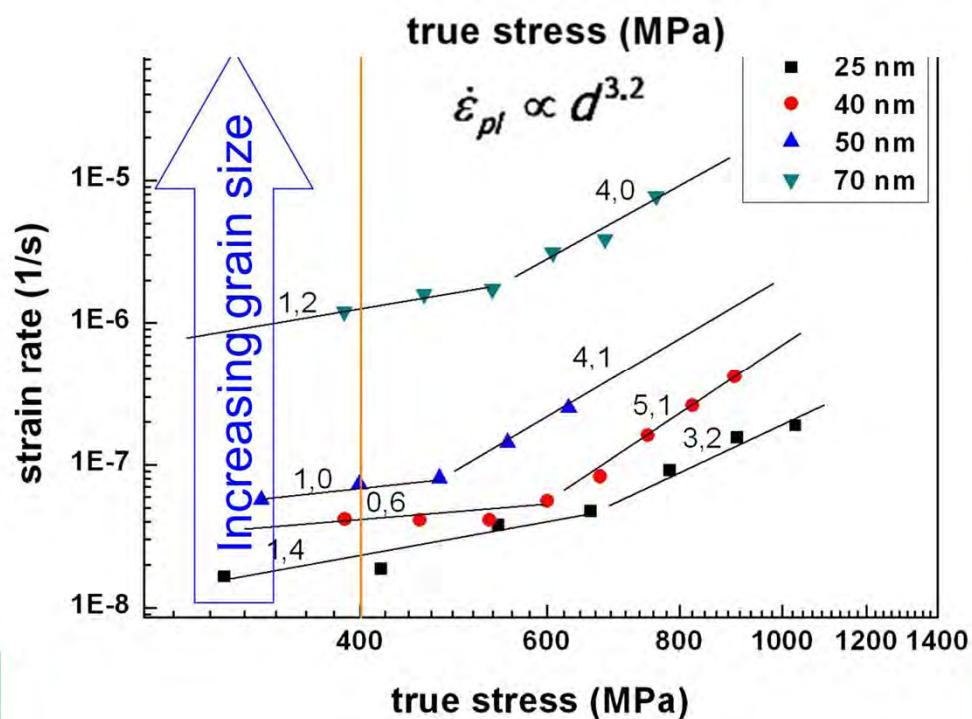


Horst Vehoff, Delphine Lemaire, Kerstin Schüler, Thomas Waschkies, and Bo Yang. International Journal of Materials Research, 98(4):259–268, April 2007.





Clean boundaries



Segregated boundaries